## SEL EXHIBIT NO. 2027

INNOLUX CORP. v. PATENT OF SEMICONDUCTOR ENERGY LABORATORY CO., LTD.

IPR2013-00066

Page 1 1 UNITED STATES PATENT AND TRADEMARK OFFICE BEFORE THE PATENT TRIAL AND APPEAL BOARD 2 3 INNOLUX CORPORATION, ) ) 4 Petitioner, ) ) 5 IPR2013-00066 ) vs. ) U.S. Pat. No. 7,876,413 6 SEMICONDUCTOR ENERGY ) LABORATORY CO., LTD., ) 7 ) Patent Owner. ) 8 9 10 The videotaped deposition of MICHAEL J. 11 12 ESCUTI, Ph.D., called by the Petitioner for 13 examination, pursuant to Notice, and pursuant to 14 the applicable rules, taken before Sandra L. 15 Rocca, CSR, CRR, at 115 South LaSalle Street, Chicago, Illinois, on the 5th day of September, 16 17 2013, at the hour of 9:39 a.m. 18 19 20 21 22 23 24 25

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2	2 NUMBER PRESENTED
JEFFER MANGELS BUTLER & MITCHELL, LLP	3 Deposition Exhibit 4 No. 1013 schematic Fig. B (Modified
3 By: MR. STANLEY M. GIBSON 3 Park Plaza, Suite 1100	Fig. 4 of Shiba) from Escuti
4 Irvine, CA 92614	5 '204 declaration, pg. 50 130 6 No. 1014 New Modified Fig. 4 of
(949) 623-7200/Fax: (949) 623-7202	Shiba schematic 139 7
5 sgibson@jmbm.com	No. 1015 U.S. Pat. No. 7,697,102 176
6 appeared on behalf of the Petitioner;	8 No. 1016 U.S. Pat. No. 6,404,480 178
7	9
8	No. 1017 SEL-CMO 0064398 179 10
9 By: MR. STANLEY A. SCHLITTER	No. 1018 U.S. Pat. No. 5,684,555 183
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(312) 577-1250/Fax: (312) 577-1370 11 sschlitter@steptoe.com	13 No. 1020 schematics and hand drawings re Fig. C and Fig. D 227
12 -and-	14 No. 2010 schematic re Fig. 2C prior art 66
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14 120 South Riverside Plaza Suite 2200	No. 2013 LG Display product info
15 Chicago, IL 60606	17       web pages, 2 pgs.       116         18       No. 2014       Chunghwa Picture Tubes web
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16     edward.manzo@huschblackwell.com       17     appeared on behalf of the	No. 2015 ShinMaywa web page, 2 pgs. 116
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19 20 Also Present:	No. 2017 Micro-Tec web pages, 7 pgs. 116 22
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	Page 6	1	Page 8
1	and spell your last name, please.	1	petition?
2		2	-
3		3	the prior art in relative terms to this patent and
4	Q. And I take it you've had your deposition		evaluate the positions that the positioner that
5	taken before?		the Petitioner was taking toward the Board or has
6	A. I've had a deposition taken three times		taken in the petition and form opinions about
7	before.		those and advise the team on what the technical
8	Q. Even though you're somewhat familiar	8	issues are and things like that.
9	with the process, I just want to go over the	9	Q. And other than attorneys for the patent
10	background rules briefly with you.	10	owner, did you communicate with anyone regarding
11	You understand that you've taken an oath	11	the subject of your assignment at any time?
12	to tell the truth?	12	A. I have not communicated with anyone
13	A. I do understand that.	13	aside from the attorney team on this matter.
14	Q. And that's the same oath you would take	14	Q. And what did you review to formulate
15	as if you were testifying in a court of law.	15	your opinion for this matter?
16	You understand that?	16	1 · · ·
17	A. I do understand that.	17	my declaration of what I've reviewed, but it began
18	Q. If at any time you do not understand one	18	with the '413 patent. I also reviewed the
	of my questions, please let me know and I'll be	19	petition, the Board's decision, the request for
	happy to rephrase it. The court reporter sitting	20	rehearing and the decision of the request for
1	to your right is taking down your testimony today	21	rehearing.
1	and at the conclusion of your deposition, you'll	22	Of course, I also reviewed the prior
1	receive a booklet of your testimony and have the	1	art, in particular Sukegawa and the patent
1	opportunity to make changes and corrections to	1	Nakamoto and others in connection with the '413
25	your testimony. But please be advised, if you do	25	litigation.
	Page 7		Page 9
)	make any changes or corrections, we can comment on	1	Q. When you say "and others," what are you
	your credibility as it pertains to those changes	2	referring to?
3	or corrections.	3	A. Well, Shiba is also another reference
4	Do you understand that?		that's that I commented on for this patent and,
5	A. I do understand that.		of course, there's a closely related case that
6	Q. Any reason why your deposition cannot		we'll talk about tomorrow with at least one
	proceed today?		
8	A. There is no reason.	8	Q. Did you review any other prior art in
9	Q. When were you first contacted in this	9	performing your assignment on the '413 patent?
	matter?	10	A. Certainly not in detail. Aside from
11	A. As best as I can recall, it was in		these references, this is what I've examined in
	April.		detail.
13	Q. Of this year?	13	Q. When you say "not in detail," are there
14	A. Of this year, yeah.		things that you looked at that you did not look at
15	Q. And what were you asked to do?		in detail, but there are other references that you
16	A. At first I was asked to review the '413		looked at?
	patent that we're talking about today and join a	17	A. Along the way I certainly searched
	meeting with the attorneys here and discuss my		for example, one of the issues in this case is
	understanding of the patent and the possibility of		contact through an opening and I certainly looked
20 21	my joining the IPR in support of this patent.		through other prior art for an understanding of
	Q. And I take it you then accepted the assignment?		what other prior art gave about that that
22 23	A. I did.		terminology and what an appropriate and reasonable definition would be.
23 24	Q. And what did you understand that your	23 24	But it turned out that the references we
	assignment was to do in this case or in this		already had were representative of that that

	Page 10		Page 12
1	was evidence enough for my position on that, so	1	the university research.
	that I didn't turn to those. I didn't need to	2	Q. And who were you consulting for?
1	turn to those because they were cumulative.	3	A. There were three firms that I can
4	Q. Do you recall what you reviewed in that	4	specifically remember. One was Cabot. Another
	regard, the ones that you didn't need to turn to?	5	was a small firm that was to be honest, I don't
6	A. I don't recall.	6	remember their name. They were a very small firm
7	Q. Did you review any other patents that	7	and local to Providence, Rhode Island. And then
	are owned by SEL other than the '204 and the '413?	8	then lastly, there was some consulting to 3M,
9	A. In this matter, I did not review any	9	of course at St. Paul, Minnesota.
10	other patents. Of course, I can't recall if	10	Q. And what type of consulting work were
11		11	you doing for Cabot?
12	are assigned to SEL. I don't recall.	12	A. The consulting work was to advise them
13	Q. But doing this assignment, you don't	13	on their questions for using a particular kind of
14	remember reviewing any other SEL patents?	14	material that they had and had certain material
15	A. That's correct. In this assignment, I		properties and they were looking for opportunities
16	didn't review any other patents owned by this		to use it and market it well, to use it in an
17	patent owner.	17	application that could lead to new business for
18	Q. Are you familiar with any other patents	18	them.
19	owned by SEL, other than '204 and '413, as you sit	19	Q. And for the small firm?
20	here today?	20	A. For the small firm, it was a it was
21	A. I'm not familiar with any other patents		actually to help them create a toy. It was quite
	that are involved in any litigation that SEL	1	fun. They were they were a firm, more of
23	SEL has.		more of a design firm, and they wanted to create
24	Q. Well, apart from litigation, are you	1	skateboarding/rollerblading glove that would have
25	aware of any at all?	25	a circuit inside it so that a child could press a
	Page 11		Page 13
1	A. No, I'm not.	-	button and then have it make a noise and make a
2	<ul><li>A. No, I'm not.</li><li>Q. Let's talk a little bit about your</li></ul>	2	button and then have it make a noise and make a song or make various things happen. So it was an
2 3	<ul><li>A. No, I'm not.</li><li>Q. Let's talk a little bit about your educational background.</li></ul>	2 3	button and then have it make a noise and make a song or make various things happen. So it was an integrated circuit that I was designing and
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2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>A. No, I'm not.</li> <li>Q. Let's talk a little bit about your</li> <li>educational background.</li> <li>If you can tell me where you graduated</li> <li>from college and what year?</li> <li>A. I graduated with my Bachelor's of</li> <li>Science in electrical and computer engineering in</li> <li>1997 at Drexel University. I then went on to</li> <li>graduate school and earned two degrees, first a</li> <li>Master's and then a Ph.D., where the final year</li> <li>for the Ph.D. was 2002 and that was at Brown</li> <li>University, also in electrical engineering.</li> <li>Q. And the Master's, is that also at Brown?</li> <li>A. It was.</li> <li>Q. And do you remember what year that was?</li> <li>A. It's in my CV specifically, of course,</li> <li>but as best as I can remember, it was 1999.</li> <li>Q. And were you working in industry at all</li> <li>from 1997 to 2002?</li> <li>A. I consulted with industry as a</li> <li>consultant, but I was not employed or working.</li> </ul>	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>button and then have it make a noise and make a song or make various things happen. So it was an integrated circuit that I was designing and prototyping for them.</li> <li>Q. Do you know if that was ever commercialized?</li> <li>A. It was a very small outfit and I think that project was came to a prototype and then didn't find any future funding.</li> <li>Q. And then what were you doing for 3M?</li> <li>A. For 3M, my principal role was to lead short courses, a series of short courses that was on the subject of LCDs and displays more generally. It went beyond LCDs. So this was in conjunction with my Ph.D. advisor where we were both creating the short course and presenting it to them in their facility to technical folks of all kinds.</li> <li>Q. And when did you first start either studying or working with LCDs?</li> <li>A. I first became aware of the principles of LCDs and TFTs during my Bachelor's degree training, so that would be before 1997. During</li> </ul>

	Page 14		Page 1
1	has continued in my research to today.		something. There were many, many things that we
2			looked at in the optical side.
3	kind of LCDs were you building or making?	3	
4		4	was on the optical side?
5	facility where I and my colleagues would prototype	5	~
6	the sometimes the whole display system, but	6	optical physics, but it also involved display
1	' typically, it would be we'd make a single pixel		systems, and in one case the in-plane switching
	or a small number of pixels.	1	mode, which definitely involved the electronics
9	-		because key to that is a set of electrodes and
10	the substrates and to the patterning of electrodes		pixel control system that is different than
•	and in some occasions with TFTs and and the		standard, and I had to make that as well.
	kinds of LCDs would vary quite a lot because it	12	
1	was research, after all, so it wasn't simply the	1	then it looks like you did a post-doc in the
t	standard modes, the twisted nematic and the other		Netherlands, is that right?
	modes, but it was it delved into other modes	15	_
	that would be more energy efficient, for example,	1	years as a post-doc in the Netherlands, in
	and that was certainly a hot topic at the time.		Eindhoven specifically.
18		18	
	dealing with TFTs, what were you doing when you	19	· · · ·
20	were not dealing with TFTs?	20	the technical university that's in Eindhoven. But
21	A. Well, we studied, I think, the displays	21	in their system, there's a blending that's quite
22	as a system. We didn't just study one small		great. I think it's quite good for students where
	aspect or a single aspect of displays during		industry serves roles within the university in a
	graduate work. We studied displays as a system	1	very intimate way.
	and so that system required multiple aspects. One	25	So while I was there, one of my
	Page 15		Page 17
1	of them is, of course, the optics of an LCD. The	1	supervisors was a very senior person in Philips
	other aspect has to do with the electronic control	1	Research labs, which is also located there. So
3	of the LCD pixels.	3	my projects were influenced by both the university
4	And then there's there's sort of the	•	side and the industry side that was there. So my
5	information that drives those circuits or that	5	work specifically focused on LCDs and among
6	goes into those circuits as well. So we've we	6	other things.
7	studied all of that and my emphasis was on the	7	Q. What were you doing with LCDs?
8	first two things I just said, the optics and the	8	A. Well, one of the things we were looking
9	electronics.	9	at there and as I recall, there's a publication
10	Q. What were you doing with the optics?	l I	on this has to do with backlights and efficient
			-
11	A. Could you say specifically when?	11	backlighting for LCDs.
11 12	<ul><li>A. Could you say specifically when?</li><li>Q. During your graduate studies, what were</li></ul>	11	Q. Anything else that you did in those two
12		12	
12 13	Q. During your graduate studies, what were	12	Q. Anything else that you did in those two
12 13	Q. During your graduate studies, what were you what were you studying or experimenting	12 13	Q. Anything else that you did in those two years with LCDs?
12 13 14 15	Q. During your graduate studies, what were you what were you studying or experimenting with in terms of the optics?	12 13 14	<ul><li>Q. Anything else that you did in those two years with LCDs?</li><li>A. Yes, yes.</li></ul>
12 13 14 15 16	<ul><li>Q. During your graduate studies, what were you what were you studying or experimenting with in terms of the optics?</li><li>A. I studied many things. So, for example,</li></ul>	12 13 14 15 16	<ul><li>Q. Anything else that you did in those two years with LCDs?</li><li>A. Yes, yes.</li><li>Q. What's that?</li></ul>
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12 13 14 15 16 17 18	<ul> <li>Q. During your graduate studies, what were you what were you studying or experimenting with in terms of the optics?</li> <li>A. I studied many things. So, for example, my dissertation was about I can't remember precisely the title. That's also in my CV, but it</li> </ul>	12 13 14 15 16 17 18	<ul> <li>Q. Anything else that you did in those two years with LCDs?</li> <li>A. Yes, yes.</li> <li>Q. What's that?</li> <li>A. There were there were many other things that I've done during that time. It's</li> </ul>
12 13 14 15 16 17 18 19	<ul> <li>Q. During your graduate studies, what were you what were you studying or experimenting with in terms of the optics?</li> <li>A. I studied many things. So, for example, my dissertation was about I can't remember precisely the title. That's also in my CV, but it was about novel LCDs and photonic switches. And</li> </ul>	12 13 14 15 16 17 18 19	<ul> <li>Q. Anything else that you did in those two years with LCDs?</li> <li>A. Yes, yes.</li> <li>Q. What's that?</li> <li>A. There were there were many other things that I've done during that time. It's I'm certainly not going to remember all of it. It</li> </ul>
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12 13 14 15 16 17 18 19 20 21	<ul> <li>Q. During your graduate studies, what were you what were you studying or experimenting with in terms of the optics?</li> <li>A. I studied many things. So, for example, my dissertation was about I can't remember precisely the title. That's also in my CV, but it was about novel LCDs and photonic switches. And so we looked at birefringent layers and the effect of controlling polarization.</li> </ul>	12 13 14 15 16 17 18 19 20 21	<ul> <li>Q. Anything else that you did in those two years with LCDs?</li> <li>A. Yes, yes.</li> <li>Q. What's that?</li> <li>A. There were there were many other things that I've done during that time. It's I'm certainly not going to remember all of it. It was a dynamic research environment where we could explore different things.</li> </ul>
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Page 18	Dama 20
1 both from the chemistry I'm not a chemist, but 1 well, my focus has always been on the inter	Page 20 action
2 I was working with chemical engineers. We also 2 of light and matter and so it's this field of	
3 looked for ways, using other principals, to 3 optoelectronics, sometimes it's called photon	nics.
4 control the molecules themselves to improve 4 And many of the applications that I look at	
5 performance, whether it was light extraction or 5 involve displays, not exclusively, but involve	<i>ie</i>
6 mobility enhancement. There were many things that 6 displays, but also telecom, energy harvestin	
7 we were looking at. 7 sensors, camera systems, optical recording.	Б
8Q. Anything else that you can recall in8And so my interest is to study and	
9 that two-year period? 9 innovate in the material side and the archite	cture
10A. Right now I can't specifically remember10 of a system for a particular application. So11 anything else.11 example of that is related to LCDs that has	0110
	ore and
12Q. All right. And then you became an12 continued even now is the design of project13 assistant professor at NC State?13 LC direct-view LCDs which have improv	
15 position at NC State in 2004 as an assistant15 Q. Anything else you were researching16 professor.16 that time period?	111
	ead
17Q. And what types of courses were you17A. Yes. During that time period, I advi18teaching in that or have you taught in that18I think five Ph.D. students, four or five. We	
19 six-year period? 19 studied topics that relate to nonmechanical biogrammechanical	
20 A. The six-year period being when I was an 20 steering. We studied topics that have to do	
21 assistant professor? 21 optical filtering. We studied topics that hav	
22 Q. Yes. 22 do with optofluidics, which which is this :	
23 A. Well, in my role as assistant professor, 23 where particles or cells are within a fluid an 24 down are actively accepted from the control theorem to control th	
24 of course I both teach and research and the 24 there are optical means to control them, to n	
25 teaching involved one course that I taught was 25 them, to grab them, to analyze them. So that	u was
Page 19	Page 21
1 the was an introductory circuits course that 1 still another another side.	
2 involves a lab as well and it's required by all 2 And in my research, we also investi	-
3 our students in the department to take. So that's 3 optical TF I'm sorry organic TFTs an	
4 "Circuits, Signals and Systems." 4 enhancements that we can offer using the	
5 Another course that I taught during that 5 principles that we have for improved perf	ormance.
6 time, actually created, was a course on LCDs and 6 Q. Anything else that you can recall i	ormance. n
6 time, actually created, was a course on LCDs and6 Q. Anything else that you can recall i7 organic electronics, and that course in particular7 that six-year time period, from 2004 to 20	ormance. n
<ul> <li>6 time, actually created, was a course on LCDs and</li> <li>7 organic electronics, and that course in particular</li> <li>8 had support from the National Science Foundation</li> <li>6 Q. Anything else that you can recall i</li> <li>7 that six-year time period, from 2004 to 20</li> <li>8 terms of research?</li> </ul>	ormance. n 10, in
<ul> <li>6 time, actually created, was a course on LCDs and</li> <li>7 organic electronics, and that course in particular</li> <li>8 had support from the National Science Foundation</li> <li>9 for me to develop the lab portion of that course.</li> <li>6 Q. Anything else that you can recall i</li> <li>7 that six-year time period, from 2004 to 20</li> <li>8 terms of research?</li> <li>9 A. At the moment, I can't recall anyther</li> </ul>	ormance. n 10, in
<ul> <li>6 time, actually created, was a course on LCDs and</li> <li>7 organic electronics, and that course in particular</li> <li>8 had support from the National Science Foundation</li> <li>9 for me to develop the lab portion of that course.</li> <li>10 And so in that course, students that</li> <li>6 Q. Anything else that you can recall i</li> <li>7 that six-year time period, from 2004 to 20</li> <li>8 terms of research?</li> <li>9 A. At the moment, I can't recall anyth</li> <li>10 further.</li> </ul>	ormance. n 10, in ing
<ul> <li>6 time, actually created, was a course on LCDs and</li> <li>7 organic electronics, and that course in particular</li> <li>8 had support from the National Science Foundation</li> <li>9 for me to develop the lab portion of that course.</li> <li>10 And so in that course, students that</li> <li>11 I created with one of my graduate students, we</li> <li>6 Q. Anything else that you can recall in</li> <li>7 that six-year time period, from 2004 to 20</li> <li>8 terms of research?</li> <li>9 A. At the moment, I can't recall anyth</li> <li>10 further.</li> <li>11 Q. All right. Then in 2010 you becam</li> </ul>	ormance. n 10, in ing
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<ul> <li>6 time, actually created, was a course on LCDs and</li> <li>7 organic electronics, and that course in particular</li> <li>8 had support from the National Science Foundation</li> <li>9 for me to develop the lab portion of that course.</li> <li>10 And so in that course, students that</li> <li>11 I created with one of my graduate students, we</li> <li>12 would guide our students to actually make the</li> <li>13 elements we were studying. So they made a simple</li> <li>14 LCD, they made an organic TFT, they made an</li> <li>15 organic solar cell and an organic LED, and then</li> <li>16 they tested it and evaluated it. So that's</li> <li>17 began teaching a new course on electromation</li> <li>18 There's a third course I taught that</li> <li>19 I think it's at least approximately titled</li> <li>6 Q. Anything else that you can recall in</li> <li>7 that six-year time period, from 2004 to 20</li> <li>8 terms of research?</li> <li>9 A. At the moment, I can't recall anyth</li> <li>10 further.</li> <li>11 Q. All right. Then in 2010 you becan</li> <li>12 associate professor at NC State?</li> <li>13 A. I did.</li> <li>14 Q. And did your courses change or did</li> <li>15 stay the same?</li> <li>16 A. My courses around that time change</li> <li>17 began teaching a new course on electromation</li> <li>18 and it's also required by all students in my</li> <li>19 I think it's at least approximately titled</li> </ul>	ormance. n 110, in ing ne an d they ged. I agnetics
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6 time, actually created, was a course on LCDs and 7 organic electronics, and that course in particular 8 had support from the National Science Foundation 9 for me to develop the lab portion of that course.6 Q. Anything else that you can recall in 7 that six-year time period, from 2004 to 20 8 terms of research?9 for me to develop the lab portion of that course.9 A. At the moment, I can't recall anyth 10 further.10 And so in that course, students that 11 I created with one of my graduate students, we 12 would guide our students to actually make the 13 elements we were studying. So they made a simple 14 LCD, they made an organic TFT, they made an 15 organic solar cell and an organic LED, and then 16 they tested it and evaluated it. So that's 17 another course that I taught.11 Q. And did your courses change or di 15 stay the same?18 There's a third course I taught that 19 I think it's at least approximately titled 20 "Introduction to Photonics and Optical 21 Q. Okay. And in terms of research, what16 A. My courses around that time change 17 began teaching a new course on electromation 18 and it's also required by all students in my 19 department. It's an undergraduate course in 22 classical electromagnetics.	ormance. n 110, in ing ne an d they ged. I agnetics and that side
6 time, actually created, was a course on LCDs and 7 organic electronics, and that course in particular 8 had support from the National Science Foundation 9 for me to develop the lab portion of that course. 10 And so in that course, students that 11 I created with one of my graduate students, we 12 would guide our students to actually make the 13 elements we were studying. So they made a simple 14 LCD, they made an organic LED, and then 15 organic solar cell and an organic LED, and then 16 they tested it and evaluated it. So that's 17 another course that I taught.6 Q. Anything else that you can recall in 7 that six-year time period, from 2004 to 20 8 terms of research? 9 A. At the moment, I can't recall anyth 10 further.11 I created with one of my graduate students, we 12 would guide our students to actually make the 13 elements we were studying. So they made a simple 14 LCD, they made an organic LED, and then 15 organic solar cell and an organic LED, and then 16 they tested it and evaluated it. So that's 17 another course that I taught.11 Q. All right. Then in 2010 you becan 12 associate professor at NC State? 13 A. I did.18 There's a third course I taught that 19 I think it's at least approximately titled 20 "Introduction to Photonics and Optical 22 Q. Okay. And in terms of research, what 23 were you doing while you were an assistant6 Q. Anything else that you can recall in 	ormance. n 110, in ing ne an d they ged. I agnetics and that side f
6 time, actually created, was a course on LCDs and 7 organic electronics, and that course in particular 8 had support from the National Science Foundation 9 for me to develop the lab portion of that course.6 Q. Anything else that you can recall in 7 that six-year time period, from 2004 to 20 8 terms of research?9 for me to develop the lab portion of that course.9 A. At the moment, I can't recall anyth 10 further.10 And so in that course, students that 11 I created with one of my graduate students, we 12 would guide our students to actually make the 13 elements we were studying. So they made a simple 14 LCD, they made an organic TFT, they made an 15 organic solar cell and an organic LED, and then 16 they tested it and evaluated it. So that's 17 another course that I taught.11 Q. And did your courses change or di 15 stay the same?18 There's a third course I taught that 19 I think it's at least approximately titled 20 "Introduction to Photonics and Optical 21 Q. Okay. And in terms of research, what16 A. My courses around that time change 17 began teaching a new course on electromation 18 and it's also required by all students in my 19 department. It's an undergraduate course in 22 classical electromagnetics.	ormance. n 110, in ing ne an d they ged. I agnetics and that side f egan

	Page 22	,	Page 24
1	it. It's also the first time it's being taught		university, through sponsored programs that
	2 anywhere in the university. And this course is		industry would pay the university to sponsor
3			research in my lab.
4		4	
5	nanotechnology and its applications in across		just discussing?
1	many fields, including nanoelectronics,	6	
	nanomaterials, biotechnology, among many others.	7	Q. And ImagineOptix, how did that get
8		8	started?
9	anything different since 2010 in your research?	9	A. ImagineOptix started in actually,
10	A. In my academic research, I think largely	10	right as I joined NC State, I encountered two of
11	I've continued the general directions that I laid		my co-founders. They are father and son, so they
12	out. I certainly have a different emphasis now.		have the same last name and confusingly, they have
13	Some are more I'm spending much more time on	13	the same first name, but they have different
14	than others, but it's largely in the same	14	middle names.
15	directions.	15	So I met them and we founded the company
16	Q. What are you spending much more time on?	16	with where it was clear that they saw an
17	, 15	17	opportunity to build pico projectors, small
1	are more and more important, one of them is	18	projectors that could be integrated into other
19	displays and display systems where we have	19	3 1 , , , , , , , , , , , , , , , , , ,
	technologies that solve energy problems or	20	things like camcorders and it as we as we
21	complexity problems within display systems. So		talked, we realized that my technology that I was
	that's one.	1	already studying for my post-doc and had plans to
23	Another is in telecom. So we are able		pursue at NC State, would be a very good solution
	to make elements that have great benefits to the	1	for that. So we joined together.
25	telecom industry. So we have an emphasis on	25	I became, you know, a majority
	Page 23		Page 25
1	studying that and providing prototypes for		shareholder of the company and we then proceeded
	industry. It's industry-sponsored, in fact. Both	1	from there. And that's really where it started.
1.	of these are industry-sponsored.		It continued then to seek funding from from any
4	Q. When you say "telecom," can you be a		means that we could to establish the company and
1 .	little more specific?	1	pay for the intellectual property costs, for
6	A. Well, this may not be as specific as		example.
	you're asking, but it's hardware that would		Q. And when you said your technology would
	support an optical fiber system, for example,	1	be a great fit for what they were doing, what were
	supporting the internet.	1	you referring to in terms of your technology?
10	A third project that's taking much of	10	A. Well, the technology that we had been
4	our attention is in the direction of making		studying and continue to study today, offers a
	optical films for astronomers and so there's	12 13	dramatic improvement to the energy efficiency of a display system when configured in the ways that we
1 1 2	savaral astronomars that walks have weathing f		UISDAY SYSTEM WHEN CONTINUED IN THE WAYS THAT WE
	several astronomers that we've been working for that study they're called evonlanets and solar		
14	that study they're called exoplanets and solar	14	were pursuing. And so that means that, for
14 15	that study they're called exoplanets and solar systems that have planets around them and so we,	14 15	were pursuing. And so that means that, for example, your cell phone display or your projector
14 15 16	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that	14 15 16	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would
14 15 16 17	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that.	14 15 16 17	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard
14 15 16 17 18	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that. Q. Apart from ImagineOptix, which we'll get	14 15 16 17 18	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard methods and, of course, that means that your cell
14 15 16 17 18 19	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that. Q. Apart from ImagineOptix, which we'll get into in a moment, have you done and apart from	14 15 16 17 18 19	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard methods and, of course, that means that your cell phone would last twice as long roughly, or a
14 15 16 17 18 19 20	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that. Q. Apart from ImagineOptix, which we'll get into in a moment, have you done and apart from what you've just discussed have you done any	14 15 16 17 18 19 20	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard methods and, of course, that means that your cell phone would last twice as long roughly, or a projector could be twice as bright, still using
14 15 16 17 18 19 20 21	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that. Q. Apart from ImagineOptix, which we'll get into in a moment, have you done and apart from what you've just discussed have you done any other work for industry while you've been at	14 15 16 17 18 19 20 21	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard methods and, of course, that means that your cell phone would last twice as long roughly, or a projector could be twice as bright, still using all the same power or other technology.
14 15 16 17 18 19 20 21 22	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that. Q. Apart from ImagineOptix, which we'll get into in a moment, have you done and apart from what you've just discussed have you done any other work for industry while you've been at NC State?	14 15 16 17 18 19 20 21 22	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard methods and, of course, that means that your cell phone would last twice as long roughly, or a projector could be twice as bright, still using all the same power or other technology. So that's the basis of the technology,
14 15 16 17 18 19 20 21 22 23	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that. Q. Apart from ImagineOptix, which we'll get into in a moment, have you done and apart from what you've just discussed have you done any other work for industry while you've been at NC State? A. I think it's the case that all of my	14 15 16 17 18 19 20 21 22 23	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard methods and, of course, that means that your cell phone would last twice as long roughly, or a projector could be twice as bright, still using all the same power or other technology. So that's the basis of the technology, but that can be applied in many ways and there
14 15 16 17 18 19 20 21 22 23 24	that study they're called exoplanets and solar systems that have planets around them and so we, in partnership with them, create elements that help them do that. Q. Apart from ImagineOptix, which we'll get into in a moment, have you done and apart from what you've just discussed have you done any other work for industry while you've been at NC State?	14 15 16 17 18 19 20 21 22 23 24	were pursuing. And so that means that, for example, your cell phone display or your projector could have twice the efficiency that it would otherwise without our technology using standard methods and, of course, that means that your cell phone would last twice as long roughly, or a projector could be twice as bright, still using all the same power or other technology. So that's the basis of the technology,

		1	
1	Page 26	1	Page 28
	layer along with micro-displays and direct-view	1	the simple reason was that we found better ways to do it that would not displace the current
	screens.	1	technology quite as much. So it would compliment
3	So in that case, we were designing		
1	systems and building prototyping systems that		it rather than replace it.
1	involved the TFT plane and our technology which	5	Q. And can you give me a general
	directly applies in the optical layers and in a	1	description of how this technology, this new
	whole system, you know, with control drivers and	1	technology that you're working on now would
-	electronics and software that would do that. So	- I	compliment and not replace?
	my company was pursuing several projects or did	9	A. The energy the improvement in energy
	pursue several projects and prototypes that lead	4	efficiency that I've been referring to this whole time occurs because the elements we make handle
	to that kind of thing.	1	
12	Q. Is the technology focused on the optical	1	both polarizations of the light at the same time,
1	layer?	1	whereas almost all LCD systems use only one
14	A. Well, the technology involves	1	polarization at a time. Typically, that's one of
1	electronics. It's so I'm not sure can you	1	the linear polarizations.
1	rephrase the question?	16	In our case, we're making elements that
17	Q. You mentioned		handle and manipulate both at the same time. So
18	A. It's not	1	because we're handling both, we can send both
19	Q the technology went into the optical		through the system. We can use unpolarized light
1	layer. So I'm just trying to understand, was the		rather than polarized light, and as you may know,
[	technology is that what was special about the		most light sources, LEDs or fluorescent lights,
	technology was the changes in the optical layer or		outside lighting is unpolarized. And so to be
	was it something else?	1	used in an LCD, it first has to be formatted for
24	A. The technology's value occurs in the		use in the LCD and that process generally cuts out
25	optical layer and so this improvement in energy	25	half the light as absorption, as loss.
	Page 27		Page 29
1	efficiency is related to the optics of what's	1	Q. So is this a technology that's focused
	going on in the display, but the technology		on the optical layer? A. I don't think that's a fair
3			
	depends on the electronics that support it. So	3	
4	it's not apart from the electronics. It's an	4	characterization. As we just said, it's a
4 5	it's not apart from the electronics. It's an optoelectronic technology. So	4	characterization. As we just said, it's a technology that where the benefit occurs in the
4 5 6	it's not apart from the electronics. It's an optoelectronic technology. So Q. Is that described in I didn't mean to	4 5 6	characterization. As we just said, it's a technology that where the benefit occurs in the optical layer, but it has consequences in the
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4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>it's not apart from the electronics. It's an optoelectronic technology. So</li> <li>Q. Is that described in I didn't mean to cut you off. Go ahead.</li> <li>A. I'm sorry. Well, just as an example, because we're changing the liquid crystal layer, that necessarily in our case led to requirement changes in the TFT layer. For example, we required different voltages than were standard and so we had to build backplanes and work with systems that had that difference in particular.</li> <li>Q. Anything else in change in the TFT layer?</li> <li>A. I think many things changed in the TFT layer. It had to be completely redesigned for our technology and that's what our team did.</li> <li>Q. And is this are these products have they been commercialized at all or A. That set of projects led to prototypes</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>characterization. As we just said, it's a technology that where the benefit occurs in the optical layer, but it has consequences in the electronic layer as well.</li> <li>Q. Let me just go ahead and hand you your declaration, which I think also has your CV attached, which is Exhibit 2012. (Document marked previously as Exhibit Number 2012 was presented.)</li> <li>BY MR. GIBSON:</li> <li>Q. Do you recognize that as your declaration and your CV at the end? And I believe your signature's on page 101. Sorry, your signature's not on page 101.</li> <li>It's earlier than that.</li> <li>A. My signature's on page 3. It appears to be my declaration and its appendices.</li> <li>Q. And Appendix B is your that's your curriculum vitae?</li> </ul>
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4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>it's not apart from the electronics. It's an optoelectronic technology. So</li> <li>Q. Is that described in I didn't mean to cut you off. Go ahead.</li> <li>A. I'm sorry. Well, just as an example, because we're changing the liquid crystal layer, that necessarily in our case led to requirement changes in the TFT layer. For example, we required different voltages than were standard and so we had to build backplanes and work with systems that had that difference in particular.</li> <li>Q. Anything else in change in the TFT layer?</li> <li>A. I think many things changed in the TFT layer. It had to be completely redesigned for our technology and that's what our team did.</li> <li>Q. And is this are these products have they been commercialized at all or A. That set of projects led to prototypes</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>characterization. As we just said, it's a technology that where the benefit occurs in the optical layer, but it has consequences in the electronic layer as well.</li> <li>Q. Let me just go ahead and hand you your declaration, which I think also has your CV attached, which is Exhibit 2012. (Document marked previously as Exhibit Number 2012 was presented.)</li> <li>BY MR. GIBSON:</li> <li>Q. Do you recognize that as your declaration and your CV at the end? And I believe your signature's on page 101. Sorry, your signature's not on page 101.</li> <li>It's earlier than that.</li> <li>A. My signature's on page 3. It appears to be my declaration and its appendices.</li> <li>Q. And Appendix B is your that's your curriculum vitae?</li> </ul>

1	Page 30		Page 3
1		1	diffractive optical element that has unique
	pinion, to the list of publications and to the	1	properties and that's what's being illustrated
	issued patents since that time.		here. Do you want me to go into the technical
4		1	properties of polarization gradings?
	the list of publications?	5	
6		6	
1	know that there is one journal paper that was, I		Is that an accurate way to call this?
8		8	· · · · · · · · · · · · · · · · · · ·
9			element. One is as a hologram or a grading. If
10		1	you use it as a beam splitter, that's one thing
1	Optics Letters.	1	you could do. You could also use it in an LCD, as
12	-	1	we talked about earlier, as a way to switch the
	on?	1	pixel or to switch what happens to the light
14			through that pixel. It's not a simple beam
1	it's as you can imagine, there are many		splitter.
1	manuscripts that are in play at any one time. So	16	<u>~</u>
1	I think this particular manuscript had to do with		describing earlier that you're currently working
1	what are called vortex beams and these are optical	1	on at ImagineOptix?
	beams that have additional quantum properties that	19	
	can be used both in communication systems, in	1	are many other pieces of the technology.
	sensing, and also in the optofluidics context that	21	Q. Does this use an organic material?
1	I mentioned earlier.	22	
23	MR. GIBSON: And why don't we go ahead		is usually some kind of glass. It could also be
1	and mark this as 1006?		metal, aluminum. It could be ITO. It could be
25	THE WITNESS: Thank you.	ł.	could be silicon in one of my projects and but
-			
1	Page 31 (Document marked as Exhibit Number 1006	1	Page 3: the liquid crystal layer is necessarily an organic
2	for identification.)		material. All liquid crystals, that I'm aware of
3	BY MR. GIBSON:		are involve organic components to them.
4	Q. And can you tell me what 1006 is?	4	Q. Are there TFTs used in this process with
5	A. It appears to be a printout of the		this technology?
5	A. It appears to be a printout of the		uns teennology?
6	ImaginaOntiv wabaita and page in the ImagineOntiv	1	
1	ImagineOptix website, one page in the ImagineOptix	6	A. Certainly. When this is combined with
7	website.	6 7	A. Certainly. When this is combined with the backplane for an LCD system, as I talked about
7 8	website. Q. Do you know who created the website?	6 7 8	A. Certainly. When this is combined with the backplane for an LCD system, as I talked about earlier, then yes, there are TFTs involved with
7 8 9	<ul><li>website.</li><li>Q. Do you know who created the website?</li><li>A. Well, at least approximately I do.</li></ul>	6 7 8 9	A. Certainly. When this is combined with the backplane for an LCD system, as I talked about earlier, then yes, there are TFTs involved with that.
7 8 9 10	<ul><li>website.</li><li>Q. Do you know who created the website?</li><li>A. Well, at least approximately I do.</li><li>The my partners in the company worked with a</li></ul>	6 7 8 9 10	<ul><li>A. Certainly. When this is combined with the backplane for an LCD system, as I talked about earlier, then yes, there are TFTs involved with that.</li><li>Q. And are those organic TFTs?</li></ul>
7 8 9 10 11	<ul><li>website.</li><li>Q. Do you know who created the website?</li><li>A. Well, at least approximately I do.</li><li>The my partners in the company worked with a firm to create the website such as it is, and the</li></ul>	6 7 8 9 10 11	<ul><li>A. Certainly. When this is combined with the backplane for an LCD system, as I talked about earlier, then yes, there are TFTs involved with that.</li><li>Q. And are those organic TFTs?</li><li>A. They were not. They were silicon-based</li></ul>
7 8 9 10 11 12	<ul> <li>website.</li> <li>Q. Do you know who created the website?</li> <li>A. Well, at least approximately I do.</li> <li>The my partners in the company worked with a firm to create the website such as it is, and the drawings these in particular are technical</li> </ul>	6 7 8 9 10 11 12	<ul><li>A. Certainly. When this is combined with the backplane for an LCD system, as I talked about earlier, then yes, there are TFTs involved with that.</li><li>Q. And are those organic TFTs?</li><li>A. They were not. They were silicon-based TFTs and more recent projects with the company are</li></ul>
7 8 9 10 11 12 13	<ul> <li>website.</li> <li>Q. Do you know who created the website?</li> <li>A. Well, at least approximately I do.</li> <li>The my partners in the company worked with a firm to create the website such as it is, and the drawings these in particular are technical drawings that either come out of my published</li> </ul>	6 7 8 9 10 11 12 13	<ul> <li>A. Certainly. When this is combined with the backplane for an LCD system, as I talked about earlier, then yes, there are TFTs involved with that.</li> <li>Q. And are those organic TFTs?</li> <li>A. They were not. They were silicon-based TFTs and more recent projects with the company are looking at gallium nitride TFTs.</li> </ul>
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1			
	Page 34 1 biography, list of education, kind of a mini	1	Page 36 A. It is not complete. It's not been
	2 mini resume, certainly not complete and not	1	updated recently, but I'm not aware of anything
	3 updated recently now that I'm looking at it.		that's inaccurate.
		4	Q. And it's something else that you would
	4 Q. And would you consider this to be 5 accurate?	1 .	plan to update in the next year or hope to update
		1	in the next year?
1	6 A. As far as I'm aware, everything that's	7	A. I do hope to update, if I can find the
1	7 here is accurate, but it's certainly not	1	time in my priority list.
	8 comprehensive and the audience I mean, the	9	Q. I think you discuss in your declaration
1	<ul><li>Purpose of this is simply to inform students of</li><li>Who I am and has a very different purpose than</li></ul>		that you've worked with students fabricating LCDs
			and TFTs?
	being I guess being a full, real resume.	12	A. Can you show me in my declaration where
1	· · · · · · · · · · · · · · · · · · ·	1	you're referring to?
1:		13	Q. Yeah, let me I believe it's in
14	•		pages 6 to 7.
	5 1008.	15	A. You're referring to paragraph 9?
1	Ϋ́Υ,	17	Q. Yes, at the bottom where it talks about
1	7 for identification.) 8 BY MR. GIBSON:	1	you developed a laboratory course on liquid
1			
19		20	crystal displays and organic electronics. A. I do see that in paragraph 9.
20	<b>.</b>	20	Q. Is that the research course you were
	think this page doesn't look like this when it's	1	talking about that also involved the lab before?
	2 on the screen. But I suspect it's the it's a	22	A. That is the course I was referring to
	B printout of my group's website, its main page.		-
24		•	before. It's to be precise, it's not I
2:	5 at NC State?	23	don't think it's proper to call it a research
	Page 35		Page 37
	A. Yes, my group from the point of view of		course.
	2 my students and post-docs.	2	Q. It involves lab work, but it's not for
			research?
	Q. And do you see anything inaccurate about	-	
4	this?	4	A. That's correct. It's for teaching,
4	this? A. Like I said before, it's not updated I	4 5	which generally has a different purpose, but it
	<ul> <li>this?</li> <li>A. Like I said before, it's not updated I</li> <li>think recently and so it's certainly not complete,</li> </ul>	4 5 6	which generally has a different purpose, but it was supported by, as it says, the NSF. And so
	<ul> <li>this?</li> <li>A. Like I said before, it's not updated I</li> <li>think recently and so it's certainly not complete,</li> <li>but it's I don't I'm not aware of anything</li> </ul>	4 5 6 7	which generally has a different purpose, but it was supported by, as it says, the NSF. And so creating the course involved research into how,
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10 (Pages 34 - 37)

1	Page 38 of anything inaccurate in them.		Page 40 It's a high molecular weight polymer that is
2			has the acronym P3HT. That stands for, you know,
	old are they?	1	the molecular name that you see in the paragraph
4			there. So it's poly(3-hexylthiophene).
5	Q. Let's start with that. When were they	5	
	last updated?		a Module 4 there's a picture of Module 4 OTFT.
7	A. I don't recall. You know, you could	7	
1	probably just as easily find out online. If you	8	been fabricated?
1	want me to estimate, I think it's two years since	9	A. It is an example from a student in this
	we updated these pages.	10	laboratory, which let's keep in mind, is designed
11	Q. Has the course changed in those two		so that undergraduate students with very limited
12	years?		knowledge can create a working and functional TFT
13	A. Somewhat, but I think in a very minor	1	within two hours or so in a fairly conventional
14	way.		lab room and not in a clean room process.
15	Q. And this is one of the courses you're	15	-
16	still teaching?	16	but it actually functions like a TFT and it's very
17	A. It's one of the courses that in general	1	exciting for students to go through that process
18	I'm teaching, but right now this semester, I'm not		building it themselves.
	teaching it.	19	Q. You said the inorganic material was used
20	Q. The only module that relates to TFTs is	20	for the semiconductor in this one.
21	Module 4, is that correct?	21	Is there also an organic material used
22	A. Can you tell me what you mean by	22	for the gate dielectric?
23	"relates to"?	23	A. Well, that's true. I think there is a
24	Q. Where you're actually teaching a	24	the insulating layer is a in this example,
25	construction of a TFT.	25	it's polyvinyl alcohol, PVA, and the main of
1			
1	Page 39 A. In this course, in this lab this set		Page 41 course the main reason for that is that that's an
1	Page 39	1	Page 41 course the main reason for that is that that's an
1 2	Page 39 A. In this course, in this lab this set	1	Page 41
1 2 3	Page 39 A. In this course, in this lab this set of lab modules, the last one, Module 4, does focus	1 2	Page 41 course the main reason for that is that that's an insulating layer that students can very easily
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1 2 3 4 5 6 7 8 9	Page 39 A. In this course, in this lab this set of lab modules, the last one, Module 4, does focus explicitly on TFTs, but I don't want to give the impression that the other elements don't involve that in don't involve TFTs because in the course, the lecture part of the course, clearly we're teaching principles of active matrix TFTs for use in LCDs, for use in organic light-emitting diode displays as well. So even if they're not	1 2 3 4 5 6 7 8 9	Page 41 course the main reason for that is that that's an insulating layer that students can very easily apply or deposit. It's very easy to create that kind of insulating film as opposed to many of the other oxides that are possible. They have to be grown in CVD or some other very sophisticated chamber, which was counter to the goals of this course. Q. And the ITO is being used as the source
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Page 42	Page
1 awarded. They've gone from the application column	1 Q. Okay. So these may be the outcome of
2 to the issued column.	2 your own work or it could be in collaboration
3 Q. Have you updated your CV since you	3 with students or other researchers?
4 prepared this one?	4 A. I think all of my publications have
5 A. I have not. I update it as needed, when	5 coauthors and that's on purpose because, of
6 asked.	6 course, I'm a mentor and an educator. So whenever
7 Q. So are the list of publications,	7 possible, I want students involved in the work.
8 though, without that absent that one, you think	8 In addition, I also put a lot of
	<ul><li>9 emphasis on partnerships with industry and other</li></ul>
	10 universities so that we can collaborate and come
11 one and I can't recall if there's any others.	
12 Q. And would you agree that as a university	12 of the partners. So I do have collaborators, I
13 professor, your scholarly work is going to be	13 think, on all of my publications.
14 expected to be in the form of publications or	14 Q. Would you consider these publications to
15 journals or conferences?	15 be a personal contribution in the field of science
16 A. I wouldn't limit it as such, but it	16 and technology?
17 includes that. My scholarly work certainly goes	17 A. I would.
18 into the publications and journals and	18 Q. In terms of your expert witness
19 conferences, but it also goes into the	19 experience, which I think is also listed here, it
20 intellectual property that's coming out of the	20 sounds like you've done a few cases with one
21 university as well as invited research	21 ongoing and the others have been resolved.
22 presentations that may not have a paper connected	22 I think you've done four cases other
23 to them.	23 than this one?
24 Q. All right. And the intellectual	A. That's correct. The four are listed in
25 property, those would be in your patents or patent	25 my CV in the first page into the second page.
Page 43	Page
1 applications?	1 Q. Do any of your publications deal with
2 A. They are of course they begin as	2 active matrix displays, circuit and peripheral
3 invention disclosures and then something can	3 driving circuits that are provided on the same
4 happen to them and many times it does lead to one	4 substrate?
5 or more patent applications. And as best I	5 A. One of my publications includes
6 recall, there are ten invention disclosures that	6 explicitly in the publication an active matrix
7 have come from my time with students at the	
8 university at NC State, and there were some from	/ backplane. That's the one cited in my
9 my graduate school time as well and some from my	7 backplane. That's the one cited in my 8 declaration. There may be others, but I can't
	8 declaration. There may be others, but I can't
	8 declaration. There may be others, but I can't 9 recall.
10 post-doc time.	<ul> <li>8 declaration. There may be others, but I can't</li> <li>9 recall.</li> <li>10 Q. Can you identify which one that is?</li> </ul>
<ul><li>10 post-doc time.</li><li>11 Q. And those are all listed in your CV?</li></ul>	<ul> <li>8 declaration. There may be others, but I can't</li> <li>9 recall.</li> <li>10 Q. Can you identify which one that is?</li> <li>11 A. Sure. It's identified in paragraph 11</li> </ul>
<ul> <li>10 post-doc time.</li> <li>11 Q. And those are all listed in your CV?</li> <li>12 A. All of the patent applications and</li> </ul>	<ul> <li>8 declaration. There may be others, but I can't</li> <li>9 recall.</li> <li>10 Q. Can you identify which one that is?</li> <li>11 A. Sure. It's identified in paragraph 11</li> <li>12 of my declaration.</li> </ul>
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<ul> <li>10 post-doc time.</li> <li>11 Q. And those are all listed in your CV?</li> <li>12 A. All of the patent applications and</li> <li>13 issued patents are listed. I don't think I</li> <li>14 included the invention disclosures themselves.</li> <li>15 Q. And the are there invention</li> <li>16 disclosures that didn't become applications?</li> </ul>	<ul> <li>8 declaration. There may be others, but I can't</li> <li>9 recall.</li> <li>10 Q. Can you identify which one that is?</li> <li>11 A. Sure. It's identified in paragraph 11</li> <li>12 of my declaration.</li> <li>13 Would you like me to identify it in my</li> <li>14 CV?</li> <li>15 Q. Yes.</li> <li>16 A. So that paper I'm referring to is</li> </ul>
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<b></b>			
	Page 46 Which you've listed as 1 through 33, do any of	1	Page 48 A. Oh, I think the description in my
1	2 them deal with active matrix display circuit		declaration is the most helpful thing to turn to.
	<sup>3</sup> peripheral driving circuits that are provided on		It's in paragraph 30. It says, "I believe a
	the same substrate?		person of ordinary skill in the art in the field
4			of the '413 patent in 1997 would be aware of
	5 that none of the publications in the listed in		liquid crystal display structures including
1	the journal publications include a focus on the		techniques for providing connections therein and
1	3 TFT backplane, but there's a reason for that and		to circuits outside a sealant."
	• that is that it's that work that I've done is	9	
1	) in relationship with my company and other	10	· · · · · · · · · · · · · · · · · · ·
	another company as well and for I guess business	11	
	reasons, we haven't chosen to publish it.		this level of ordinary skill and some of the ways
13	-		could involve not personal experience with
14			fabrication.
1	project that I referred to early on when I was	15	
	assistant professor, some of that is published in	1	background? Would they need to have any kind of
	' that journal I'm sorry in that conference	17	
	proceeding that I pointed to. But almost all of	18	A. Again it's, I don't think, limited. I
	it is not published, expressly because it was	19	think there are many ways to get to this ordinary
	related to intellectual property and business	1	level of skill. I think the typical way would be
21	opportunities.		would involve education, some number of years
22	Q. And when you say the work that you did	22	in an engineering kind of program, could be up to
23	when you were an assistant professor that you		a Bachelor's degree, but I don't think it should
24	mentioned earlier, what specifically are you	1	be limited to that.
25	discussing?	25	Q. What techniques would they have to be
	Page 47		Page 49
1	A. I could go back through the transcript	1	aware of in 1997?
2	and find that, but is that what you want me to do?	2	A. Well, the ones I'm specifically
3		3	referring to here that I'm adopting from the case
4	as to what you're referring to.		before I joined it, is providing connections
5		5	therein and to circuits outside a sealant.
	my time as an assistant professor, then associate	6	Q. So from your perspective, that person
	professor and in that discussion, I referred to a	7	may not even have to have a B.S. degree?
	project that did involve TFTs. That's what I'm	8	A. I think so, yeah. I think in other
	referring to.		countries there are many ways to get to this level
10	Q. That project?		of ordinary skill. Especially in Asia, I think
11	A. Well, that yeah, that work, which		they have different tracts that would be something
12			less than a Bachelor's degree equivalence over
13	projects, but that's what I'm referring to.		here.
14	Q. Any of your publications address	14	Q. And any type of courses that they would
15	peripheral driving circuits such as shift		need to take?
	registers and decoders for driving an active	16	A. It's hard to say. Again, they would
17	matrix display circuit and external connecting		need to understand something about semiconductor
	lines for electrically connecting those circuits?		processing, but it would not necessarily have to
19	A. They do not explicitly address that.		be in a lab. They would have to understand what
20	Q. And you would agree that 1997 is the		it means to work with a sealant and certain
21	point for determining one of ordinary skill in the		circuit principles and some of the basic aspects
22	art for this matter?		and fundamentals that relate to the materials
23	A. I would for this matter.		we're talking about.
24	Q. And what type of person would you say is	24	Q. What would they have to know about
23	one of ordinary skill in the art as of 1997?	23	certain circuit principles?

-	Page 50	Τ	Page 52
1	Page 50 A. I think, for example, they'd have to	1	
	understand conductivity and how materials relate		those two?
	to conductivity.	3	A. Those are clearly the primary ones. I
4	Q. Anything else?	1	think there are, in addition, many research level
5	A. There are many other things that I think		materials that were being pursued at that time,
1	go into this language and a person of ordinary		including organic TFTs and other materials, oxides
1	skill would need to understand many techniques. I	E	of all kinds, semiconducting oxides.
	think I'd have a hard time listing them out all	8	Q. If we're just talking about products,
1	for you.		liquid crystal display products, what materials
10	Q. What would they have to know about a	1	were being used with TFTs? Just those two?
1	sealant?	11	A. No, I would not limit it to those two.
12	A. I think they would have to understand	1	So, you know, there are other compound
	how a sealant works, how it's generally applied in		semiconductors. Gallium nitride, which is is
	the field, the principles of adhesion of a sealant		used in some context, but clearly silicon,
1	on various surfaces, for example.		polysilicon I'm sorry yeah, amorphous and
	Q. As of 1997, would you consider yourself		polydomain silicon would be the primary material
16	to have qualified as a person of ordinary skill in		used in by 1997.
	the art?	18	Q. Okay. And in your publications, do any
10	A. I would.	1	of those address amorphous silicon TFTs?
20	Q. And what is that based on?	20	A. The publication that I pointed to
21	A. At the time I would by 1997, I had		earlier in my conference proceedings list, it's
	taken courses that involved labs as well as	22	
1	lectures in microelectronics, in semiconductor	23	
1	processing and the operations of LCDs, not just	24	· · · · · · · · · · · · · · · · · · ·
	the operation, but the building and construction	1	backplane.
25	the operation, but the canading and construction	1	
	D 51		De 52
1	Page 51	1	Page 53
	and principles of LCDs, including the sealant, as	1	Q. Was it amorphous silicon?
2	and principles of LCDs, including the sealant, as well as the optics and the backplane driving	2	<ul><li>Q. Was it amorphous silicon?</li><li>A. I can't recall.</li></ul>
2 3	and principles of LCDs, including the sealant, as well as the optics and the backplane driving principles.	2 3	<ul><li>Q. Was it amorphous silicon?</li><li>A. I can't recall.</li><li>Q. Okay. And any of your other</li></ul>
2 3 4	and principles of LCDs, including the sealant, as well as the optics and the backplane driving principles. So even by that time, 1997, when I	2 3 4	<ul><li>Q. Was it amorphous silicon?</li><li>A. I can't recall.</li><li>Q. Okay. And any of your other</li><li>publications or your conference proceeding address</li></ul>
2 3 4 5	and principles of LCDs, including the sealant, as well as the optics and the backplane driving principles. So even by that time, 1997, when I finished my Bachelor's degree, I had that	2 3 4 5	<ul><li>Q. Was it amorphous silicon?</li><li>A. I can't recall.</li><li>Q. Okay. And any of your other</li><li>publications or your conference proceeding address</li><li>amorphous silicon TFTs?</li></ul>
2 3 4 5 6	and principles of LCDs, including the sealant, as well as the optics and the backplane driving principles. So even by that time, 1997, when I finished my Bachelor's degree, I had that experience.	2 3 4 5 6	<ul> <li>Q. Was it amorphous silicon?</li> <li>A. I can't recall.</li> <li>Q. Okay. And any of your other</li> <li>publications or your conference proceeding address</li> <li>amorphous silicon TFTs?</li> <li>A. I can't recall if any of them have a</li> </ul>
2 3 4 5 6 7	<ul> <li>and principles of LCDs, including the sealant, as well as the optics and the backplane driving principles.</li> <li>So even by that time, 1997, when I finished my Bachelor's degree, I had that experience.</li> <li>Q. So you would consider this to be a</li> </ul>	2 3 4 5 6 7	<ul> <li>Q. Was it amorphous silicon?</li> <li>A. I can't recall.</li> <li>Q. Okay. And any of your other</li> <li>publications or your conference proceeding address</li> <li>amorphous silicon TFTs?</li> <li>A. I can't recall if any of them have a</li> <li>mention of it, but I think you're asking for more</li> </ul>
2 3 4 5 6 7 8	<ul> <li>and principles of LCDs, including the sealant, as</li> <li>well as the optics and the backplane driving</li> <li>principles.</li> <li>So even by that time, 1997, when I</li> <li>finished my Bachelor's degree, I had that</li> <li>experience.</li> <li>Q. So you would consider this to be a</li> <li>fairly low level for an ordinary skill in the art?</li> </ul>	2 3 4 5 6 7 8	<ul> <li>Q. Was it amorphous silicon?</li> <li>A. I can't recall.</li> <li>Q. Okay. And any of your other</li> <li>publications or your conference proceeding address</li> <li>amorphous silicon TFTs?</li> <li>A. I can't recall if any of them have a</li> <li>mention of it, but I think you're asking for more</li> <li>than just a mention of it. But aside from that</li> </ul>
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	Page 54		Dago 56
1	Page 54 there are ones out there that were amorphous	1	Page 56 Q. Do you recall what materials or what
	silicon?		metals are used in the fabrication of the source
3	· · · · · ·	1	and drain electrodes for the thin film transistors
1	it is possible to create something like that for		in the various wirings over the glass substrate
	for example, for low quality, low cost kinds of	1	that are taught by the '413 patent, the Sukegawa
	displays that one might use in toys, it may be	1	patent and the Nakamoto patent?
	possible to do that. It depends.	7	
8			refresh my memory to be able to answer that.
9	polycrystalline silicon?	9	Q. And if I told you that there was that
10			they reference chromium, aluminum, tantalum and
	silicon would be would have a better		molybdenum, would that refresh your memory?
1	performance and could be used for that in some	12	• • •
1	settings.	13	question. Those are, of course, conductors and
14	•		metals.
15	just want you to understand whether you were	15	Q. Do any of your publications or
1	aware of any liquid crystal display products that	16	conference papers address those types of metals
	were actually using a polycrystalline silicon for	1	for making source and drain electrodes and wirings
1	the TFTs?		onto a glass substrate?
19	A. I can't name a product or paper from my	19	A. What was the specific list of metals?
20	memory that would include that, but I expect that	20	Q. Chromium, aluminum, tantalum and
21	there are some.	21	molybdenum.
22	Q. Now, can you point to any of your	22	A. Yes, there are many publications I have
23	publications or conference papers in your	23	on reflective substrates with some of those.
24	curriculum vitae that address polycrystalline	24	Q. Is it easy for you to identify a few of
25	silicon TFTs?	25	those?
	D 55	1	
1	Page 55		Page 57
1	A. To my to my knowledge, the list of	1	A. It may not be easy. I'd have to go
2	A. To my to my knowledge, the list of publications, both in journals and conference	2	A. It may not be easy. I'd have to go through the actual publications and confirm for
2 3	A. To my to my knowledge, the list of publications, both in journals and conference proceedings, do not include an explicit component	2 3	A. It may not be easy. I'd have to go through the actual publications and confirm for myself. But if you want, I can take a moment and
2 3 4	A. To my to my knowledge, the list of publications, both in journals and conference proceedings, do not include an explicit component that would have polycrystalline silicon in a	2 3	A. It may not be easy. I'd have to go through the actual publications and confirm for myself. But if you want, I can take a moment and look.
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1	· · · · · · · · · · · · · · · · · · ·	1	
	Page 58		Page 60
	now, I'm happy to.	1	the Sukegawa patent and the Nakamoto patent all
2		1	describe multi-layer wiring structures that are
	to take, you know, too long. If it's going to be	1	used to carry signals via a flexible printed
	too difficult, then we'll skip it.	1	circuit into an active matrix display?
5		5	MR. SCHLITTER: Objection, form,
	here to think through and recall based on the	1	foundation.
	titles, so I think it will take a while.	7	THE WITNESS: I would not agree. I
8			would not agree with that statement.
•	Nakamoto, also lists several insulating films that	1	BY MR. GIBSON:
1	are used as insulating layers in the TFT array.	10	Q. Why not?
11	Do you recall that?	11	A. Well, you use the word "multi-layer
12	A. I'm not sure which specification you're		wiring structure," right, in singular, at least
	referring to. Can you rephrase it or give me the		that's how I heard it. And so I instead would say
14	specification you're asking me about?		that in especially the '413 and the Sukegawa
15	Q. All right. So you don't recall what the		patent, there are multiple wirings that form,
16	materials that were used for the insulating films?		along with an insulator in between and in the
17	A. Is that your question, what are the		terminal portion other aspects, a connection from
18	repeat your question.	18	the terminal portion to the display portion.
19	Q. Those three patents, do you recall what	19	In Nakamoto, there is, as best I recall,
	insulating what materials are used for the	F	and maybe you should I should see the reference
21	insulating layers?	1	before I offer this, but so I'll stop there.
22	A. And what are the three patents?	22	Q. I did use the word "structures."
23	Q. The '413, the Sukegawa and Nakamoto.	23	Does that change your answer if it's
24	MR. SCHLITTER: Objection, form.		plural?
25	THE WITNESS: I recall that some of the	25	A. It depends on what you mean by your
	Page 59		Page 61
1	Page 59 examples explicitly cited include silicon nitride,	1	Page 61 phrase. What do you mean by "multi-layer wiring
1		•	-
2	examples explicitly cited include silicon nitride,	•	phrase. What do you mean by "multi-layer wiring
2	examples explicitly cited include silicon nitride, but they are not limited to that.	2 3	phrase. What do you mean by "multi-layer wiring structure"?
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	Page 62	+ .	Page 64
1	BY MR. GIBSON:	1	8
2			e exhibits in the case, Exhibit 1001, which is the
	3 conference papers address using multiple layers of	1	'413 patent.
	wiring to carry signals via a flexible printed	4	5
	5 circuit into an active matrix display?	5	1 5
6	<b>3</b>	6	· · · · · · · · · · · · · · · · · · ·
1	7 flexible printed circuit is unpublished.	7	
8		8	
	work that you've done with the flexible printed	1	that's at issue in the petition?
10	circuit earlier in the deposition?	10	11
11	1 •1		patent.
	work we've discussed involved a flexible printed	12	
1	circuit onto glass substrates with an active	13	<b>J</b>
	matrix on it.	14	( F
15		15	1 /
	having multi-layer wiring structures that are used		BY MR. GIBSON:
1	to carry the that are used to carry the	17	Q. And would you agree that that's the
1	signals?	1	Nakamoto patent along with its translation?
19	•	19	A. It does appear to be the Nakamoto patent
20	1 5		in the original and its translation.
1	characterizing that phrase.	21	Q. Okay. And let's give you Exhibit 1003,
	BY MR. GIBSON:		which is the Sukegawa patent.
23		23	(Document marked previously as Exhibit
24	5 ,	24	Number 1003 was presented.)
25	THE WITNESS: Can you give me an example	25	
	Page 63		Page 65
	of what you mean by "multiple layers of wires"?	1	BY MR. GIBSON:
2	BY MR. GIBSON:	2	Q. Is that the Sukegawa patent?
3	<pre></pre>	3	A. It does appear to be the Sukegawa U.S.
4	1	1	patent.
	metal deposition steps where they where there	5	Q. And those are the three patents that you
	are conductors in different physical layers in the	6	reviewed for your declaration in this matter?
	sequence of layers on the backplane, if that's	7	A. These are three of the prior art patents
8	what you mean, then yes.		that I reviewed. There's one additional, Shiba,
9	Q. In what project was were you dealing		that I included in my declaration.
E C	with an FPC or a flexible printed circuit in that	10	Q. Why did you include Shiba in your
1	context?	1	declaration?
12	A. It was related to the work with	12	A. The primary reason was related to the
	ImagineOptix and the partners through through		definition of the phrase "through an opening."
	them in those early projects that I had in my		And there's a section we can turn to, if you'd
1	early time at NC State where we were applying the		like, where I give many examples in Shiba and
	technology in a way that required changing and		others where contact through an opening is
17	well, that required designing and fabricating		consistent with the Board's first definition as a
1			term of art.
19	Q. And that work, none of that was	19	Q. Now, I want to focus on the sealant and
	published I think you said, is that right?		I'm going to give you Exhibit 2010, the placement
21	A. To my knowledge, that work is is		of sealant. I'm sure you're familiar with that
	still not published.		issue in this matter?
23	Q. And it's not in any patents or patent	23	A. I am. I'm familiar with the matter and
	applications?		this marked-up figure.
25	A. Not that I'm aware of.	25	
			1

	Page 66		Page 68
1		1	Hatalis?
2		2	A. The marked up figure that's here on
3	· · · · · · · · · · · · · · · · · · ·	3	page 48 of my declaration does show a counter
4		1	substrate that shows where I think one of ordinary
5		1	skill would understand that counter substrate to
6		6	be if the sealant was placed where Dr. Hatalis has
7			placed it.
8	sealant, correct?	8	Q. And the placing of the counter substrate
9	· · · · · · · · · · · · · · · · · · ·	9	that you have there is consistent with Nakamoto,
10		10	correct?
11	Q. But you disagree with his placement?	11	A. Can you tell me what you mean by
12	• •	12	"consistent with"?
13	skill would not put the seal where he has placed	13	Q. You've placed it the same way that
1	it.	14	Nakamoto places the counter substrate over the
15	Q. You would agree that Sukegawa would have	1	sealant?
16	sealant?	16	A. Can you tell me what you mean by "the
17	A. Sukegawa mentions that there is a	17	same way"? I don't understand what you mean.
	sealant, but does not mention or disclose at all	18	Q. Look at Fig. 9 of Nakamoto.
19	where the sealant would be positioned, except I'll	19	Do you have that in front of you?
	note he does not illustrate it in this figure or	20	A. I do. I now have Fig. 9 of Nakamoto.
21	any of the terminal portions in Sukegawa.	21	Q. And you would agree that there's a in
22	So I think it's fair to say that	22	Fig. 9 we have a substrate?
23	Sukegawa is teaching that wherever the sealant is,	23	A. There's a substrate and a counter
24	it's not where Dr. Hatalis has put it.	24	substrate in Fig. 9 of Nakamoto.
25	Q. Now, but my question was, you would	25	Q. And there's an SL marking. Would you
	Page 67		Page 69
1	agree there is sealant being used in Sukegawa?	1	understand that to be sealant?
2	One of ordinary skill in the art would understand	2	A. That is what Nakamoto refers to as the
3	that there's going to be sealant used?	3	
4	A. I do agree that a person of ordinary	4	Q. And do you see that the counter
5			
1 2	skill would would hear what Sukegawa has said		substrate is over the sealant?
1			substrate is over the sealant? A. I do see that.
6	skill would would hear what Sukegawa has said	5 6 7	substrate is over the sealant? A. I do see that. Q. And then just as you've drawn in your
6 7	skill would would hear what Sukegawa has said about the fact that there should be sealant	5 6 7 8	<ul><li>substrate is over the sealant?</li><li>A. I do see that.</li><li>Q. And then just as you've drawn in your declaration on page 48, the counter substrate</li></ul>
6 7 8	skill would would hear what Sukegawa has said about the fact that there should be sealant holding the two substrates together and that it	5 6 7 8 9	<ul><li>substrate is over the sealant?</li><li>A. I do see that.</li><li>Q. And then just as you've drawn in your declaration on page 48, the counter substrate extends into that open region if we look at</li></ul>
6 7 8	skill would would hear what Sukegawa has said about the fact that there should be sealant holding the two substrates together and that it should be somewhere between the two substrates	5 6 7 8 9	<ul><li>substrate is over the sealant?</li><li>A. I do see that.</li><li>Q. And then just as you've drawn in your declaration on page 48, the counter substrate extends into that open region if we look at Sukegawa as marked by the 13?</li></ul>
6 7 8 9 10	skill would would hear what Sukegawa has said about the fact that there should be sealant holding the two substrates together and that it should be somewhere between the two substrates illustrated in Fig. 3D. Q. And why do you believe there has to be some sealant?	5 6 7 8 9 10 11	<ul> <li>substrate is over the sealant?</li> <li>A. I do see that.</li> <li>Q. And then just as you've drawn in your declaration on page 48, the counter substrate extends into that open region if we look at Sukegawa as marked by the 13?</li> <li>A. Well, what I see is that the sealant is</li> </ul>
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6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	<ul> <li>skill would would hear what Sukegawa has said about the fact that there should be sealant holding the two substrates together and that it should be somewhere between the two substrates illustrated in Fig. 3D.</li> <li>Q. And why do you believe there has to be some sealant?</li> <li>A. Well, the sealant's function is to really do two things. It's to first keep the liquid crystal material, which is literally a liquid, inside between the two substrates. And it's also and it does so in large part by keeping the two substrates together with a firm adhesion. And so by 1997, and it continues today, a sealant is the means to do that.</li> <li>Q. Now, in your declaration, if you'd turn</li> </ul>	5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21	<ul> <li>substrate is over the sealant?</li> <li>A. I do see that.</li> <li>Q. And then just as you've drawn in your declaration on page 48, the counter substrate extends into that open region if we look at Sukegawa as marked by the 13?</li> <li>A. Well, what I see is that the sealant is not the edge of the counter substrate and that it does overhang in the explicit disclosure of Nakamoto and I think that is a good example of what one of ordinary skill would would do in any case with the sealant, to have an offset back from the edge of the substrate some distance.</li> <li>Q. So your drawing in Fig on Fig. 2C on page 48 of your declaration is consistent with Nakamoto's Fig. 9?</li> <li>MR. SCHLITTER: Objection, form.</li> </ul>
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	Page 70		Page
1	checking terminal that is underneath element 13.		a different matter.
2	And certainly in Sukegawa, having access to that	2	Q. Why wouldn't you want it to adhere?
3	terminal after the two substrates are joined is	3	A. Could you repeat the question?
4	paramount. It's central to his objectives to	4	Q. Sure. I mean, is there why would you
5		5	want the epoxy not to adhere to the two
6		1	substrates?
7	put it, the counter substrate would block access	7	A. Well, it's less about what I would want
8	to that.	8	to do, of course, but what Nakamoto discloses.
9	BY MR. GIBSON:	9	Nakamoto discloses two things, right? First,
10	Q. And it's your view in Fig. 9 it's	10	there's a sealant which adheres to the two
11	blocked in Nakamoto?	11	substrates and keeps the liquid crystal inside
12	A. In Fig	12	between glass and then there's an epoxy that
13	MR. SCHLITTER: Objection, form.	13	protects the sealant. There's just no disclosure
14	THE WITNESS: In Fig. 9, there is more	14	that it has to adhere to the substrates.
15	distance between the counter substrate and the	15	Q. My question's a little bit different.
16	FPC. So it is different. I mean, they both have	16	Why is why would one of ordinary
17	a counter substrate that is overhanging the	17	skill in the art want to design the epoxy so that
18	sealant, that's true. But in Nakamoto, the	18	it wouldn't adhere to the two substrates?
19	counter substrate is well away from the FPC so	19	MR. SCHLITTER: Objection, foundation.
20	that the checking terminal can still be accessed.	20	THE WITNESS: I don't I don't think I
21	BY MR. GIBSON:	21	can speculate on that.
22	Q. It's still overhanging the open area	22	BY MR. GIBSON:
23	that when we look at Fig. 2C it's designated 13,	23	Q. You don't know one way or the other?
24	correct?	24	A. Certainly Nakamoto doesn't disclose one
25	MR. SCHLITTER: Objection, form.	25	way or the other and at the moment I can't I
	Page 71		Page 7
1	THE WITNESS: Can you point me to the	1	don't know one way or the other what one of
2	particular area in Fig. 9 that you're referring	2	ordinary skill would consider in that case.
3	to?	3	Q. In terms of I think you had some
4	BY MR. GIBSON:		discussion about the repairing operation that's
5	Q. It looks like it has the initials I'm	1	described by Sukegawa. Do you recall that? I
6	not sure if it's MPX or	1	think it starts on page 161 or paragraph 161,
7	A. EPX?	7	page 80.
8	Q. EPX. Do you see that area?	8	A. Let me take a quick look to refresh my
9	A. I do see the epoxy region.		memory.
10	Q. Okay. And what does the you see the	10	Are you referring to the paragraphs with
	counter substrate's overhanging the epoxy region?		letters underneath that paragraph
12	A. That's what the figure shows.	12	Q. Yes.
13	Q. And what do you understand the purpose	13	A 161? Okay, so they relate to the
	of the epoxy is there?	1	discussion of peeling, that's true.
		115	Q. And do you have anything in your CV that
15	A. Nakamoto describes the purpose of the	15	
15 16	epoxy as protecting the sealant.	16	discusses any publications or anything else,
15 16 17	epoxy as protecting the sealant. Q. Is it also holding the two substrates	16 17	your experience on TFT LCD repair?
15 16 17 18	epoxy as protecting the sealant. Q. Is it also holding the two substrates together?	16 17 18	your experience on TFT LCD repair? A. It's a it's certainly true that in my
15 16 17 18 19	<ul><li>epoxy as protecting the sealant.</li><li>Q. Is it also holding the two substrates together?</li><li>A. Not necessarily. If it's an epoxy, then</li></ul>	16 17 18 19	your experience on TFT LCD repair? A. It's a it's certainly true that in my work I've had to repair and do my best with
15 16 17 18 19 20	<ul><li>epoxy as protecting the sealant.</li><li>Q. Is it also holding the two substrates together?</li><li>A. Not necessarily. If it's an epoxy, then that means it's a kind of glue and so to some</li></ul>	16 17 18 19 20	your experience on TFT LCD repair? A. It's a it's certainly true that in my work I've had to repair and do my best with displays and TFT backplanes that have not turned
15 16 17 18 19 20 21	<ul><li>epoxy as protecting the sealant.</li><li>Q. Is it also holding the two substrates together?</li><li>A. Not necessarily. If it's an epoxy, then that means it's a kind of glue and so to some extent, it's adhering at least to the sealant.</li></ul>	16 17 18 19 20 21	your experience on TFT LCD repair? A. It's a it's certainly true that in my work I've had to repair and do my best with displays and TFT backplanes that have not turned out perfectly. I'm not sure I would call that the
15 16 17 18 19 20 21 22	<ul><li>epoxy as protecting the sealant.</li><li>Q. Is it also holding the two substrates together?</li><li>A. Not necessarily. If it's an epoxy, then that means it's a kind of glue and so to some extent, it's adhering at least to the sealant.</li><li>But I think it's possible to design materials so</li></ul>	16 17 18 19 20 21 22	your experience on TFT LCD repair? A. It's a it's certainly true that in my work I've had to repair and do my best with displays and TFT backplanes that have not turned out perfectly. I'm not sure I would call that the peeling operation that that is identical to
15 16 17 18 19 20 21 22 23	<ul><li>epoxy as protecting the sealant.</li><li>Q. Is it also holding the two substrates together?</li><li>A. Not necessarily. If it's an epoxy, then that means it's a kind of glue and so to some extent, it's adhering at least to the sealant.</li><li>But I think it's possible to design materials so that it just sticks to the sealant and not to the</li></ul>	16 17 18 19 20 21 22 23	your experience on TFT LCD repair? A. It's a it's certainly true that in my work I've had to repair and do my best with displays and TFT backplanes that have not turned out perfectly. I'm not sure I would call that the peeling operation that that is identical to what's in Sukegawa, but certainly I have faced the
<ol> <li>15</li> <li>16</li> <li>17</li> <li>18</li> <li>19</li> <li>20</li> <li>21</li> <li>22</li> <li>23</li> <li>24</li> </ol>	<ul><li>epoxy as protecting the sealant.</li><li>Q. Is it also holding the two substrates together?</li><li>A. Not necessarily. If it's an epoxy, then that means it's a kind of glue and so to some extent, it's adhering at least to the sealant.</li><li>But I think it's possible to design materials so</li></ul>	<ol> <li>16</li> <li>17</li> <li>18</li> <li>19</li> <li>20</li> <li>21</li> <li>22</li> <li>23</li> <li>24</li> </ol>	your experience on TFT LCD repair? A. It's a it's certainly true that in my work I've had to repair and do my best with displays and TFT backplanes that have not turned out perfectly. I'm not sure I would call that the peeling operation that that is identical to

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	Page 74		Page 76
1	out the way we want it to.	1	BY MR. GIBSON:
2	Q. But have you published anything,	2	Q. Now, would you expect that the websites
	patents, publications, conference papers, on TFT	3	would say the LG website or the CPT website,
4	LCD repair?	4	the first two that you mentioned, that they would
5	A. I can't recall that that kind of topic	5	publicly disclose their proprietary information
	is in any of my publications or patents, but	6	related to the display module repair procedures?
7	certainly that kind of thing occurs when	7	A. I would not expect any company to if
8	fabricating real devices.		they were smart, to disclose proprietary
9		9	information about any of their processes,
10		10	including repair operations.
11	A. I can't recall.	11	Q. And do you have any knowledge of the
12	Q conference papers or anything like	12	
13		13	the repair process?
14	A. I can't recall.	14	
15	Q. You attach a number of websites to your	15	Q. And do you know if the equipment used in
16		ł	display repair is exactly the same as that used in
17	Did you look at any other websites that	1	display production?
[	you didn't attach?	18	A. I'm not aware of that kind of
19	A. In this matter regarding these pages,		requirement, but I am aware that as I looked into
1	no, I did not.	1	the literature for any mention anywhere in journal
21	Q. And how many hours did you spend		literature, conference proceedings or the patent
1	reviewing the websites on display inspection	•	literature on a repairing operation, that there
	repair?		was very little disclosed at all.
24	A. Do you mean specifically these	24	Q. Is that because most of it's proprietary
25	approximately eight websites listed on these	25	or do you know?
	Page 75		Page 77
1	pages?	1	A. I don't know. That's one possibility.
2	Q. Yeah.	2	Q. So you don't know whether the equipment
3	A. Not many, one hour.		used in the display repair is exactly the same as
4	Q. Would you consider that hour to make you		that used in the display production?
	an expert in TFT LCD repair?	5	A. I think it's unlikely that it is exactly
6	MR. SCHLITTER: Objection, foundation.		the same, but it also is not likely some magic box
7	THE WITNESS: I can't agree with that		that's not disclosed anywhere else. And the tools
	characterization of the time or if that would be		to form metals and the kinds of conductors and
	sufficient. No, it's my general my own		insulators that are referred to in in the
	experience and my research with the processes that		patent, those processes are pretty well-known and
	are listed here, my familiarity through my		they have fundamental laws of physics that limit
12	students' work or my own personal work that		the temperatures and pressures that can be used in
	anablad mata mad the make itas and 1	1.5	forming those layers, and those are well-known in
13	enabled me to read the websites and understand		
13 14	what's being talked about and fairly quickly form	14	the fabrication process.
13 14 15	what's being talked about and fairly quickly form an opinion on the text that's largely represented	14 15	the fabrication process. Q. And are they well-known to you in the
13 14 15 16	what's being talked about and fairly quickly form an opinion on the text that's largely represented here.	14 15 16	the fabrication process. Q. And are they well-known to you in the display repair process?
13 14 15 16 17	what's being talked about and fairly quickly form an opinion on the text that's largely represented here. BY MR. GIBSON:	14 15 16 17	<ul><li>the fabrication process.</li><li>Q. And are they well-known to you in the display repair process?</li><li>A. They're well-known to me in the display</li></ul>
13 14 15 16 17 18	what's being talked about and fairly quickly form an opinion on the text that's largely represented here. BY MR. GIBSON: Q. But you would agree that just reviewing	14 15 16 17 18	<ul><li>the fabrication process.</li><li>Q. And are they well-known to you in the display repair process?</li><li>A. They're well-known to me in the display fabrication process, but those same physical</li></ul>
13 14 15 16 17 18 19	<ul> <li>what's being talked about and fairly quickly form</li> <li>an opinion on the text that's largely represented</li> <li>here.</li> <li>BY MR. GIBSON:</li> <li>Q. But you would agree that just reviewing</li> <li>some websites wouldn't make you an expert on TFT</li> </ul>	14 15 16 17 18 19	<ul> <li>the fabrication process.</li> <li>Q. And are they well-known to you in the display repair process?</li> <li>A. They're well-known to me in the display fabrication process, but those same physical limitations would apply to the repair process.</li> </ul>
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13 14 15 16 17 18 19 20 21	<ul> <li>what's being talked about and fairly quickly form</li> <li>an opinion on the text that's largely represented</li> <li>here.</li> <li>BY MR. GIBSON:</li> <li>Q. But you would agree that just reviewing</li> <li>some websites wouldn't make you an expert on TFT</li> <li>LCD repair?</li> <li>MR. SCHLITTER: Objection, form.</li> </ul>	14 15 16 17 18 19 20 21	<ul> <li>the fabrication process.</li> <li>Q. And are they well-known to you in the display repair process?</li> <li>A. They're well-known to me in the display fabrication process, but those same physical limitations would apply to the repair process.</li> <li>Q. Do you know how many displays can fit onto a piece of a glass substrate?</li> </ul>
<ol> <li>13</li> <li>14</li> <li>15</li> <li>16</li> <li>17</li> <li>18</li> <li>19</li> <li>20</li> <li>21</li> <li>22</li> </ol>	<ul> <li>what's being talked about and fairly quickly form</li> <li>an opinion on the text that's largely represented</li> <li>here.</li> <li>BY MR. GIBSON:</li> <li>Q. But you would agree that just reviewing</li> <li>some websites wouldn't make you an expert on TFT</li> <li>LCD repair?</li> <li>MR. SCHLITTER: Objection, form.</li> <li>THE WITNESS: To be an expert, one of</li> </ul>	14 15 16 17 18 19 20 21 22	<ul> <li>the fabrication process.</li> <li>Q. And are they well-known to you in the display repair process?</li> <li>A. They're well-known to me in the display fabrication process, but those same physical limitations would apply to the repair process.</li> <li>Q. Do you know how many displays can fit onto a piece of a glass substrate?</li> <li>MR. SCHLITTER: Objection, foundation,</li> </ul>
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	Page 78		Page 80
1	BY MR. GIBSON:	1	mainstream commercial product.
2	Q. And do you have a range of how many?	2	
3	A. The literature's pretty clear that it	3	equipment is going to have a large size glass
4		4	substrate with many individual displays
5	sorts. I've I recall seeing large TVs being	5	MR. SCHLITTER: Objection, form,
	formed in a grid of three-by-three, sometimes	6	foundation.
7	four-by-three. Smaller displays can be formed in	7	BY MR. GIBSON:
8	larger arrays than even that.	8	Q that are being made all in parallel?
9	Q. And so you said "it depends."	9	A. That's simply not required. The first
10	What do you mean, what does it depend	10	few months that I just mentioned, those are real
11	on?	11	commercial products. Some of the devices we have
12	A. The number of displays formed on a	12	could have been made on that that kind of line.
13	particular mother substrate would depend on the	13	So I can't agree with that characterization that
14	size of that substrate and the size of the	14	that's either necessary or required, but it may be
15	eventual product that's being produced and the	15	typical.
16	processes that are being used to produce them, the	16	Q. Yeah. And my answer my question
17	generation of the LCD fab line.	17	rather, wasn't whether it's required. My question
18	Q. And would you agree that the production	18	is directed to what is typical, you know, in large
19	equipment that is made to handle large large	19	scale production.
20	sized glass substrates with many individual	20	A. Every large scale process of a product
21	displays all made in parallel onto that same	21	that I have that I'm aware of begins with a
22	substrate?	22	small production line process with typically one
23	MR. SCHLITTER: Objection, form.	23	one or a small number at a time.
24	8	24	That's the partners I work with have
25	What I that's it's not required to be so.	25	exactly that. But as soon as they can, if
	Page 79		Page 81
1	There are, I'm sure, many fabrication lines that	1	customers justify it, there is a transfer to a
2	are smaller than that and that produce one display	2	higher throughput line where you do have parallel
3	at a time.	3	or you have multiple displays being produced in
4	BY MR. GIBSON:	4	parallel essentially through the line.
5	Q. Do you know any that do that?	5	Q. Or you have the larger size glass
1			
6	A. I do. Some of my partners that I work		substrate with multiple displays?
	A. I do. Some of my partners that I work with through ImagineOptix, I've seen them myself.	6 7	A. That's right. And to your question
7 8	<ul><li>A. I do. Some of my partners that I work</li><li>with through ImagineOptix, I've seen them myself.</li><li>Q. And are these actual products that are</li></ul>	6 7 8	A. That's right. And to your question then, in the commercial products, both can appear.
7 8 9	<ul><li>A. I do. Some of my partners that I work</li><li>with through ImagineOptix, I've seen them myself.</li><li>Q. And are these actual products that are</li><li>commercialized and sold?</li></ul>	6 7 8 9	A. That's right. And to your question then, in the commercial products, both can appear. Results from both can appear.
7 8 9 10	<ul> <li>A. I do. Some of my partners that I work</li> <li>with through ImagineOptix, I've seen them myself.</li> <li>Q. And are these actual products that are</li> <li>commercialized and sold?</li> <li>A. As you can appreciate, when a new</li> </ul>	6 7 8 9 10	<ul><li>A. That's right. And to your question</li><li>then, in the commercial products, both can appear.</li><li>Results from both can appear.</li><li>Q. Now, would you agree that the equipment</li></ul>
7 8 9 10 11	<ul> <li>A. I do. Some of my partners that I work</li> <li>with through ImagineOptix, I've seen them myself.</li> <li>Q. And are these actual products that are</li> <li>commercialized and sold?</li> <li>A. As you can appreciate, when a new</li> <li>product comes out, the first step is a prototype</li> </ul>	6 7 8 9 10 11	<ul><li>A. That's right. And to your question</li><li>then, in the commercial products, both can appear.</li><li>Results from both can appear.</li><li>Q. Now, would you agree that the equipment</li><li>that's used to repair a display will be different</li></ul>
7 8 9 10 11 12	<ul> <li>A. I do. Some of my partners that I work</li> <li>with through ImagineOptix, I've seen them myself.</li> <li>Q. And are these actual products that are</li> <li>commercialized and sold?</li> <li>A. As you can appreciate, when a new</li> <li>product comes out, the first step is a prototype</li> <li>and then the next step is typically a limited</li> </ul>	6 7 8 9 10 11 12	<ul><li>A. That's right. And to your question</li><li>then, in the commercial products, both can appear.</li><li>Results from both can appear.</li><li>Q. Now, would you agree that the equipment</li><li>that's used to repair a display will be different</li><li>than the equipment that's being used when you have</li></ul>
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21 (Pages 78 - 81)

[	Da 97		Page 84
1	Page 82 because they damage the whole display that's	1	A. I'd have to see the website printout to
	already produced and being repaired. So they		know for sure.
	they would not it would not be possible to use	3	MR. GIBSON: Okay. Maybe we can take a
	those for the repair operation.		break and if I can indulge you to grab his
5	I also know that there are limits on the	1	exhibits?
1	ability to create these layers that are	6	VIDEOGRAPHER: We're going off record.
1	fundamental to the materials themselves and to	1	The time is 11:48.
	basic physics. So I can't even imagine another	8	(Short recess.)
1	way, for example, to form a high quality ITO layer	9	VIDEOGRAPHER: We're now back on record.
	without having elevated temperatures and most	10	The time is 11:56. Please continue.
	likely vacuum. You could you could deposit the	1	BY MR. GIBSON:
	atoms, but they wouldn't conduct in the way that's	12	Q. All right. We'll come back to that once
	necessary for this application.		we have the documents.
ł	BY MR. GIBSON:	14	In general, in the fabrication of
15	Q. Okay. I don't think that was an answer		display products, how important is it to conserve
1	to my question. My question is directed toward	1	space?
	repair.	17	MR. SCHLITTER: Objection, form.
18	And wouldn't you expect that the	18	THE WITNESS: What space are you
	equipment that's aimed to repair a display will	1	referring to?
	only handle one display at a time?		BY MR. GIBSON:
21	MR. SCHLITTER: Objection, foundation.	21	Q. Well, the space in the structure itself.
22	THE WITNESS: I have no reason to to	22	MR. SCHLITTER: Same objection.
	expect that. It could be that. It depends	23	THE WITNESS: I still don't have enough
	otherwise.	24	information to answer your question.
25		25	Can you point me to a figure? Which
		L	
	Page 83		Page 85
1	Page 83	1	Page 85 space or what space are you referring to in the
	BY MR. GIBSON:		space or what space are you referring to in the
2	BY MR. GIBSON: Q. Are you aware of any equipment that's	2	space or what space are you referring to in the fabrication of a display product?
2 3	BY MR. GIBSON: Q. Are you aware of any equipment that's used to repair multiple displays at one time?	23	space or what space are you referring to in the fabrication of a display product? BY MR. GIBSON:
2 3 4	<ul><li>BY MR. GIBSON:</li><li>Q. Are you aware of any equipment that's used to repair multiple displays at one time?</li><li>A. I can't recall if that was within the</li></ul>	2 3 4	<ul><li>space or what space are you referring to in the fabrication of a display product?</li><li>BY MR. GIBSON:</li><li>Q. Well, in the in the multi-layer</li></ul>
2 3 4 5	<ul> <li>BY MR. GIBSON:</li> <li>Q. Are you aware of any equipment that's used to repair multiple displays at one time?</li> <li>A. I can't recall if that was within the what I've what I've seen. The very few papers</li> </ul>	2 3 4 5	<ul><li>space or what space are you referring to in the fabrication of a display product?</li><li>BY MR. GIBSON:</li><li>Q. Well, in the in the multi-layer terminal portion, is it important to conserve</li></ul>
2 3 4 5 6	<ul> <li>BY MR. GIBSON:</li> <li>Q. Are you aware of any equipment that's used to repair multiple displays at one time?</li> <li>A. I can't recall if that was within the</li> <li>what I've what I've seen. The very few papers that I noticed that mention repair at all do not</li> </ul>	2 3 4 5 6	<ul><li>space or what space are you referring to in the fabrication of a display product?</li><li>BY MR. GIBSON:</li><li>Q. Well, in the in the multi-layer terminal portion, is it important to conserve space?</li></ul>
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234 567789 100111 1213141516 17718819	<ul> <li>BY MR. GIBSON:</li> <li>Q. Are you aware of any equipment that's used to repair multiple displays at one time?</li> <li>A. I can't recall if that was within the what I've what I've seen. The very few papers that I noticed that mention repair at all do not I just don't recall what they said.</li> <li>Q. The Pascal website that's mentioned in your paragraph D A. I see paragraph D. Is the attachment included here?</li> <li>Q. Unfortunately not. And if we if you need those, then we'll have to I don't know if you have them handy, but we need to get a copy of them. MR. SCHLITTER: I could I could get them. I'm not sure that I have them handy. THE WITNESS: It depends most likely on your question.</li> </ul>	23 45 67 89 10 11 12 13 14 15 16 17 18 19	<ul> <li>space or what space are you referring to in the fabrication of a display product?</li> <li>BY MR. GIBSON: <ul> <li>Q. Well, in the in the multi-layer</li> <li>terminal portion, is it important to conserve</li> <li>space?</li> <li>MR. SCHLITTER: Objection, form. THE WITNESS: It depends.</li> </ul> </li> <li>BY MR. GIBSON: <ul> <li>Q. What does it depend on?</li> <li>A. Well, there are various trade-offs that go into the design of a terminal portion.</li> <li>Certainly there are the technical trade-offs, but there's also the considerations of cost and the availability of the elements involved, especially the FPC.</li> <li>So it depends on all those on whetheryou know, whether the area in space and size of the terminal is larger or smaller.</li> </ul> </li> </ul>
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23345567789910011112133144155166177188199200211222	BY MR. GIBSON: Q. Are you aware of any equipment that's used to repair multiple displays at one time? A. I can't recall if that was within the what I've what I've seen. The very few papers that I noticed that mention repair at all do not I just don't recall what they said. Q. The Pascal website that's mentioned in your paragraph D A. I see paragraph D. Is the attachment included here? Q. Unfortunately not. And if we if you need those, then we'll have to I don't know if you have them handy, but we need to get a copy of them. MR. SCHLITTER: I could I could get them. I'm not sure that I have them handy. THE WITNESS: It depends most likely on your question. BY MR. GIBSON: Q. And we may we may need them for this question.	23345567789910011112133144155166177188199200211222	<ul> <li>space or what space are you referring to in the fabrication of a display product?</li> <li>BY MR. GIBSON: <ul> <li>Q. Well, in the in the multi-layer</li> <li>terminal portion, is it important to conserve</li> <li>space?</li> <li>MR. SCHLITTER: Objection, form. THE WITNESS: It depends.</li> </ul> </li> <li>BY MR. GIBSON: <ul> <li>Q. What does it depend on?</li> <li>A. Well, there are various trade-offs that go into the design of a terminal portion.</li> <li>Certainly there are the technical trade-offs, but there's also the considerations of cost and the availability of the elements involved, especially the FPC.</li> <li>So it depends on all those on whetheryou know, whether the area in space and size of the terminal is larger or smaller.</li> <li>Q. Do the display producers try to have a large border region around the TFT array or do they try to minimize the edge area?</li> </ul> </li> </ul>
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233455677899100111121331441551661771881992002122223324	BY MR. GIBSON: Q. Are you aware of any equipment that's used to repair multiple displays at one time? A. I can't recall if that was within the what I've what I've seen. The very few papers that I noticed that mention repair at all do not I just don't recall what they said. Q. The Pascal website that's mentioned in your paragraph D A. I see paragraph D. Is the attachment included here? Q. Unfortunately not. And if we if you need those, then we'll have to I don't know if you have them handy, but we need to get a copy of them. MR. SCHLITTER: I could I could get them. I'm not sure that I have them handy. THE WITNESS: It depends most likely on your question. BY MR. GIBSON: Q. And we may we may need them for this question.	233445567789910011112133144155166177188199200212223324	<ul> <li>space or what space are you referring to in the fabrication of a display product?</li> <li>BY MR. GIBSON: <ul> <li>Q. Well, in the in the multi-layer</li> <li>terminal portion, is it important to conserve</li> <li>space?</li> <li>MR. SCHLITTER: Objection, form. THE WITNESS: It depends.</li> </ul> </li> <li>BY MR. GIBSON: <ul> <li>Q. What does it depend on?</li> <li>A. Well, there are various trade-offs that go into the design of a terminal portion.</li> <li>Certainly there are the technical trade-offs, but there's also the considerations of cost and the availability of the elements involved, especially the FPC.</li> <li>So it depends on all those on whetheryou know, whether the area in space and size of the terminal is larger or smaller.</li> <li>Q. Do the display producers try to have a large border region around the TFT array or do they try to minimize the edge area?</li> </ul> </li> </ul>

	D 96	1	D 00
1	Page 86 Q. And why is that?		Page 88 number of displays produced on a given glass
2		1	substrate?
	unpleasing to most consumers and customers. We,	3	
	even at the time of 1997, expect that what we're	4	
	going to see is the display with a frame or border	5	
4	around it that's modest in size compared to the	_	final display/display area and the number that
	display.		would be implemented there. It also depends on
8			the design of the terminal region for a particular
	generations of glass substrate size that were in	9	manufacturer. I don't think there's one answer to
	production?	10	that.
11	A. I'm in familiar excuse me. I am	11	
	familiar with the general ideas of those	12	
	generations, but not the specific sizes in those	13	· · · · · · · · · · · · · · · · · · ·
1	generations. I don't recall that.	14	
15	Q. Do you know how many displays were	15	5 , , ,
	produced on a given glass substrate of a given	16	
	generation, or that's something you don't know?	1	begin from a certain number of displays on a
18	MR. SCHLITTER: Objection, foundation.		substrate, for example, four-by-three and you
19	THE WITNESS: I don't recall that. I've		increase the border region of that, then at some
1	certainly seen that kind of description, but I	20	
1	don't remember those kind of details.	21	require you to have less than the four-by-three
1	BY MR. GIBSON:		grid of those displays.
23	Q. What about in 1997, do you know what was		BY MR. GIBSON:
\$	the state of the art in glass substrate size that	24	Q. So you would like to decrease the border
25	was in production as of 1997?	25	region to avoid that, correct?
	Page 87		Page 89
1	A. I don't recall the substrate size at	1	A. Most of the time I think that's the
-		1	
2	that point.	2	case. You would want to do whatever you can to
23	that point. Q. Do you know how large a Gen 3 glass		case. You would want to do whatever you can to minimize that border region.
3	-		
3	Q. Do you know how large a Gen 3 glass	3 4	minimize that border region.
3 4 5	Q. Do you know how large a Gen 3 glass substrate is?	3 4 5	<ul><li>minimize that border region.</li><li>Q. And one of the ways you could minimize</li></ul>
3 4 5 6	<ul><li>Q. Do you know how large a Gen 3 glass</li><li>substrate is?</li><li>A. I suspect there's some variation in that</li></ul>	3 4 5	<ul><li>minimize that border region.</li><li>Q. And one of the ways you could minimize that border region is to put the sealant as close</li></ul>
3 4 5 6	<ul><li>Q. Do you know how large a Gen 3 glass</li><li>substrate is?</li><li>A. I suspect there's some variation in that</li><li>size, but I don't recall even what that typical</li></ul>	3 4 5 6 7	<ul><li>minimize that border region.</li><li>Q. And one of the ways you could minimize that border region is to put the sealant as close as possible to the terminal region, correct?</li></ul>
3 4 5 6 7 8	<ul><li>Q. Do you know how large a Gen 3 glass substrate is?</li><li>A. I suspect there's some variation in that size, but I don't recall even what that typical answer would be.</li></ul>	3 4 5 6 7 8	<ul><li>minimize that border region.</li><li>Q. And one of the ways you could minimize that border region is to put the sealant as close as possible to the terminal region, correct?</li><li>A. I think that is that one of ordinary</li></ul>
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3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>Q. Do you know how large a Gen 3 glass</li> <li>substrate is?</li> <li>A. I suspect there's some variation in that</li> <li>size, but I don't recall even what that typical</li> <li>answer would be.</li> <li>Q. Do you know how large the glass</li> <li>substrate is of a Gen 8, 9 or 10?</li> <li>MR. SCHLITTER: Objection, form.</li> <li>THE WITNESS: I don't recall</li> <li>specifically, but those are the more I</li> <li>understand that to be more recent generations and</li> <li>so they're likely larger than the previous</li> <li>generations.</li> <li>BY MR. GIBSON:</li> <li>Q. Would you have any knowledge of how many</li> <li>14-inch displays could fit on a Gen 3.5 versus a</li> <li>Gen 8?</li> <li>A. I can't recall any specific answer to</li> <li>how many would be on those those generations.</li> <li>Q. Do you know how the total area that a</li> </ul>	3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>minimize that border region.</li> <li>Q. And one of the ways you could minimize that border region is to put the sealant as close as possible to the terminal region, correct?</li> <li>A. I think that is that one of ordinary skill would see that as one of the options available.</li> <li>Q. If a if a terminal region is located a large distance from the sealing region, how would that affect the series resistance?</li> <li>MR. SCHLITTER: Objection, form. THE WITNESS: I think you're going to have to tell me what you mean by "terminal region." There could be many answers to what that is.</li> <li>So what do you mean by "terminal region" before I continue answering questions on this.</li> <li>BY MR. GIBSON:</li> <li>Q. Or terminal portion, would you be more comfortable than that?</li> </ul>

23 (Pages 86 - 89)

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		1	D. 00
1	Page 90 the words in paragraph 127 of your declaration.	1	Page 92 THE WITNESS: Are you are you asking
2		1	in a specific context or just as a general
$\begin{vmatrix} 2\\ 3 \end{vmatrix}$			principle?
1	terminal portion?	1	BY MR. GIBSON:
5	A. Well, this paragraph is referring to	5	Q. General principle.
1	Dr. Hatalis' declaration and in this paragraph,	6	A. As a general principle, it is true that
	I'm addressing his assertion that it would be	1	if you shorten a conductor, then the resistance is
1	obvious to a person of ordinary skill to place the	1	lowered.
	sealant over the wirings that are in the terminal	9	Q. And if we look at Fig. 9 of Nakamoto
	portion, the second wirings in particular. And	10	A. I've got it.
	I	11	Q would you agree that in Fig. 9,
12	Q. So if we look at Sukegawa, for example,		Nakamoto is contemplating running a
1	can you tell me what terminal portion you were	1	multi-conductor wiring from the terminal portion
1	referring to?	1	into the display portion?
15	A. Sure. Specifically in Sukegawa, we have	15	A. Nakamoto in Fig. 9 shows two layers, G1
1	several figures that say "terminal portion."	1	and D1, which are both conductors, and that is
	Well, to be clear, Fig. 3C has arrows that say the	1	running from underneath the tape carrier package
	directions to the terminal portion and then many	F	I think it's called in Nakamoto across the
1	of the other figures that show the FPC, for	1	sealant into the display area.
1	example, Figs. 2, all of them, Fig. 3B, Fig. 3A,	20	Q. And that's the metal G1 and the ITO
	Fig. 3E and later figures, they show the terminal		layer, D1?
	what Sukegawa would, I think, call the terminal	22	A. That's what I'm referring to.
1	portion.	23	Q. And would you agree that D1 is the outer
24	Q. Okay. So if we talk about that as our	24	top metal in contact with the with ACF?
1	as our terminal region, if that's located a	25	MR. SCHLITTER: Objection, foundation,
	0		
1	Dage 01		Page Q3
1	Page 91	1	Page 93
	large distance from the sealing region, how does	1	form.
2	large distance from the sealing region, how does that impact the series resistance?	2	form. THE WITNESS: I can't I can't agree
2 3	large distance from the sealing region, how does that impact the series resistance? MR. SCHLITTER: Objection, form.	2 3	form. THE WITNESS: I can't I can't agree with that mainly because D1, if it's ITO, is not a
2 3 4	large distance from the sealing region, how does that impact the series resistance? MR. SCHLITTER: Objection, form. THE WITNESS: The basic principle of	2 3 4	form. THE WITNESS: I can't I can't agree with that mainly because D1, if it's ITO, is not a metal. It's a conducting oxide. So it is the top
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8 remind refresh my memory on the specification9 if it if it does disclose that it is intending9 Q. If we look at Fig. 5 of N10 to provide a means for reliable connections to10 you agree that the sealant region11 scan lines.10 you agree that the sealant region12 BY MR. GIBSON:12 A. I'm not sure that's show13 Q. Okay. So without reviewing the patent13 right. It's especially shown by14 again, you don't you don't know the answer to15 that?16 A. I don't recall if that's explicit in17 Nakamoto.17 Nakamoto.17 Q. PSV1 is the oxide silicon18 Q. What about Sukegawa, same question?19 A. Well, Sukegawa also is certainly20 directed toward liquid crystal displays. And what20 A. It's called the protective21 I recall the primary objective of Sukegawa being21 And it can be made in oxide silicon	Nakamoto, would on is formed on top yn in Fig. 5, combining Fig. 5 ure. I'm looking.
9 if it if it does disclose that it is intending 10 to provide a means for reliable connections to 11 scan lines.9 Q. If we look at Fig. 5 of N 10 you agree that the sealant region 11 of PSV1?12 BY MR. GIBSON: 13 Q. Okay. So without reviewing the patent 14 again, you don't you don't know the answer to 15 that?10 you agree that the sealant region 11 of PSV1?12 BY MR. GIBSON: 13 Q. Okay. So without reviewing the patent 14 again, you don't you don't know the answer to 15 that?12 A. I'm not sure that's shown by 14 with Fig. 9. So let me make su 15 Is PSV1 the orientation layer?16 A. I don't recall if that's explicit in 17 Nakamoto.17 Q. PSV1 is the oxide silicon 18 ahead. If you want to look at 19 A. Well, Sukegawa also is certainly 20 directed toward liquid crystal displays. And what 21 I recall the primary objective of Sukegawa being9 Q. If we look at Fig. 5 of N 10 you agree that the sealant region 11 of PSV1?13 right. It's especially shown by 14 with Fig. 9. So let me make su 15 Is PSV1 the orientation layer? 16 myself what PSV1 is.17 Q. PSV1 is the oxide silicon 18 ahead. If you want to look at 19 paragraph 89 that describes, if 20 A. It's called the protective 21 And it can be made in oxide silicon	on is formed on top m in Fig. 5, combining Fig. 5 ure. I'm looking.
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11 scan lines.11 of PSV1?12 BY MR. GIBSON:12 A. I'm not sure that's show13 Q. Okay. So without reviewing the patent12 A. I'm not sure that's show14 again, you don't you don't know the answer to13 right. It's especially shown by14 again, you don't you don't know the answer to14 with Fig. 9. So let me make su15 that?14 with Fig. 9. So let me make su16 A. I don't recall if that's explicit in15 Is PSV1 the orientation layer?16 A. I don't recall if that's explicit in16 myself what PSV1 is.17 Nakamoto.17 Q. PSV1 is the oxide silico18 Q. What about Sukegawa, same question?19 paragraph 89 that describes, if20 directed toward liquid crystal displays. And what20 A. It's called the protective21 I recall the primary objective of Sukegawa being21 And it can be made in oxide silico	combining Fig. 5 are. I'm looking.
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20 directed toward liquid crystal displays. And what20A. It's called the protective21 I recall the primary objective of Sukegawa being21 And it can be made in oxide sile	that helps.
	e film. Yeah.
	licon films or
$ \omega\omega $ is a $ \omega $ disclosure of a means to provide $ \omega $ mande smoon minus. Bo mats to	clearly an
23 corrosion resistance in the from the terminal 23 insulator. And your question is	s whether or not
24 portion or in the terminal portion and especially 24 that appears below the sealant?	)
25 around the checking terminal. 25 Q. Yes, if the sealant regio	n is formed on
Page 95	Page 97
1 Q. And that's because you want to have a 1 top of PSV1?	
2 reliable connection? 2 A. It appears that Fig. 9 is	-
3 MR. SCHLITTER: Objection, form. 3 as partially going under the sea	lant.
4 THE WITNESS: You're asking me are 4 Q. And from Fig. 5?	
5 you asking me if I think it's good to have a 5 A. It's unclear to me if Fig.	
6 reliable connection in LCDs? Of course. 6 sealant going around what's lab	eled as PSV1 or
7 BY MR. GIBSON: 7 it's going on top of.	
8 Q. Well, and that's what Sukegawa is 8 Q. You can't tell?	
9 directed to? 9 A. I don't think you can tel	
10 MR. SCHLITTER: Objection, form. 10 Q. But you think Fig. 9 dis	closes that it
11 THE WITNESS: I'd have to read it 11 is underneath the sealant?	
12 carefully to see whether or not he explicitly 12 MR. SCHLITTER: Object	
13 speaks of a reliable connection. I just can't 13 THE WITNESS: Well, i	
14 recall. 14 Fig. 5, which is the top-down v	
15 BY MR. GIBSON:15 show the plan regions of those	
16Q. Looking at a again, in Nakamoto in16 shows a cross-section that may	•
17 Fig. 9, would you agree that the placement of the 17 realistic cross-section and it do	
18 sealant there is an example of where you can place 18 drawn, a layer labeled PSV1 the	at is underneath the
19 sealant? 19 sealant.	
20 A. Nakamoto Fig. 9 certainly shows one 20 But I do want to note that	
21 example of where to place sealant and I think is 21 one of the other patents, we have	
22 fairly representative in this sense that the 22 which is very misleading and I	
23 sealant is placed recessed back from the edge of 23 that's the case here where in the	
24 the counter substrate. 24 things are being labeled that are	en't actually in
25 Q. So you think it's a good example or 25 the same cross-section.	

			· · · · · · · · · · · · · · · · · · ·
1	Page 98 BY MR. GIBSON:	1	Page 100 think the sealant is maybe you could do that
2		1	for me. I don't know if you have a pen.
	whether that's happened here in Fig. 5?	3	
4		4	-
1	want to identify for me where the boundaries of	5	
1	PSV1 are, then perhaps I could answer you better.	6	
7	But from the black and white drawing at		to give it back.
	the moment, it's it's not apparent to me	8	A. Okay. So you're asking me to identify
1	whether the seal, which is labeled, is going on		the seal?
	top of what appears to be labeled PSV1. It's a	10	Q. Where the sealant is.
	square with a circle in it, again whether it's	11	A. Okay.
•	going on top or whether it's going around.	12	Q. I know where the SL is. I see where
12	Q. Would you understand that the PSV1 is		the where that is. I don't need you to
	going from the from the right looking at the		identify the letters SL, just where you think the
	right of the figure, there's two horizontal lines		sealant would be and then next, I'd ask you to
	that extend toward the square with the circle in		identify the sealant region.
10	-	10	A. Well, we can begin with following that
18	Would you understand that the PSV1 is		label and identifying the seal, SL, in Fig. 5 and
	going to be extending going from the right to	1	I think that's an answer to your question.
	the left toward that square with a circle going	20	Q. Okay. Now yes, and that's that's
	around if	i	what I understand as well.
21	MR. SCHLITTER: Objection.	21	Now, what is the where is the PSV1?
	BY MR. GIBSON:	23	A. Well, you and I both can see it's
23 24	Q and then going down to the bottom of		labeled and it has a line going from the text that
	Fig. 5?		seems to point to the inside of a box that's
40			
1	Page 99 MR. SCHLITTER: Objection, form.	1	Page 101 square with a circle in it.
1 2	THE WITNESS: I don't think that's my	- I	Q. All right. So you wouldn't understand
	understanding. I may misunderstand what you've	2	that PSV1 actually extends from the left I'm
			sorry from the right of Fig. 5 to the left and
	just said and it would be helpful if you drew it		
	for me so I can really respond to your question.	6	then is actually overlapping the sealant?
	But it sounds like what you've just described is		A. Well, I guess now that I'm looking at this, I notice that there's two labels for PSV1,
	the seal region or the sealant. I'm sorry. The sealant comes in from the right		uns, I nouce that there's two fabels for FSVI,
8	The seatant comes in nom the right		right There's one kind of in the middle and then
			right. There's one kind of in the middle and then
	side. It's two parallel lines and then it comes	9	there's one in the more toward the bottom left.
10	side. It's two parallel lines and then it comes over and goes around that square and then comes	9 10	there's one in the more toward the bottom left. Q. Right. That's my yes. And my
10 11	side. It's two parallel lines and then it comes over and goes around that square and then comes down to its label, SL.	9 10 11	there's one in the more toward the bottom left. Q. Right. That's my yes. And my question is that's what I'm trying I was
10 11 12	side. It's two parallel lines and then it comes over and goes around that square and then comes down to its label, SL. BY MR. GIBSON:	9 10 11 12	there's one in the more toward the bottom left. Q. Right. That's my yes. And my question is that's what I'm trying I was focusing on the one that's in the bottom left.
10 11 12 13	<ul><li>side. It's two parallel lines and then it comes over and goes around that square and then comes down to its label, SL.</li><li>BY MR. GIBSON:</li><li>Q. We'll the sealing region is much broader</li></ul>	9 10 11 12 13	there's one in the more toward the bottom left. Q. Right. That's my yes. And my question is that's what I'm trying I was focusing on the one that's in the bottom left. And you're focusing on the one that was
10 11 12 13 14	<ul><li>side. It's two parallel lines and then it comes over and goes around that square and then comes down to its label, SL.</li><li>BY MR. GIBSON:</li><li>Q. We'll the sealing region is much broader than that, right? The sealing region up almost</li></ul>	9 10 11 12 13 14	there's one in the more toward the bottom left. Q. Right. That's my yes. And my question is that's what I'm trying I was focusing on the one that's in the bottom left. And you're focusing on the one that was A. I was.
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10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>side. It's two parallel lines and then it comes over and goes around that square and then comes down to its label, SL.</li> <li>BY MR. GIBSON: <ul> <li>Q. We'll the sealing region is much broader than that, right? The sealing region up almost half of what we're seeing here in Fig. 5, correct? MR. SCHLITTER: Objection, form. THE WITNESS: I don't agree with that.</li> <li>The seal or the sealant is labeled SL. It's got specific locations in both Fig. 5 and Fig. 9. The seal region is something different altogether and I'm not sure that's labeled here in Nakamoto. In another reference it is, but not here.</li> </ul> </li> </ul>	9 10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>there's one in the more toward the bottom left.</li> <li>Q. Right. That's my yes. And my</li> <li>question is that's what I'm trying I was</li> <li>focusing on the one that's in the bottom left.</li> <li>And you're focusing on the one that was</li> <li>A. I was.</li> <li>Q. So my question was, when we're looking</li> <li>at the right side of Fig. 5, the PSV1 is going to</li> <li>be extending to that line on the left side that is</li> <li>labeled PSV1?</li> <li>MR. SCHLITTER: Objection, form.</li> <li>THE WITNESS: From other figures we can</li> <li>see PSV1 as a layer in, for example, Fig. 4 above</li> <li>or as part of the TFT. So I certainly can agree</li> </ul>
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10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>side. It's two parallel lines and then it comes over and goes around that square and then comes down to its label, SL.</li> <li>BY MR. GIBSON: <ul> <li>Q. We'll the sealing region is much broader than that, right? The sealing region up almost half of what we're seeing here in Fig. 5, correct? MR. SCHLITTER: Objection, form. THE WITNESS: I don't agree with that.</li> <li>The seal or the sealant is labeled SL. It's got specific locations in both Fig. 5 and Fig. 9. The seal region is something different altogether and I'm not sure that's labeled here in Nakamoto. In another reference it is, but not here.</li> </ul> </li> </ul>	9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>there's one in the more toward the bottom left.</li> <li>Q. Right. That's my yes. And my</li> <li>question is that's what I'm trying I was</li> <li>focusing on the one that's in the bottom left.</li> <li>And you're focusing on the one that was</li> <li>A. I was.</li> <li>Q. So my question was, when we're looking</li> <li>at the right side of Fig. 5, the PSV1 is going to</li> <li>be extending to that line on the left side that is</li> <li>labeled PSV1?</li> <li>MR. SCHLITTER: Objection, form.</li> <li>THE WITNESS: From other figures we can</li> <li>see PSV1 as a layer in, for example, Fig. 4 above</li> <li>or as part of the TFT. So I certainly can agree</li> </ul>

		Page 102		Page 104
		the lines in between. And there's two cuts in	1	would have to be removed at least partially. So
		particular that are important, there's CT1 and CT2		Fig. 5 shows I think that, but it's not clear what
		and those are going to be those are identified	1	else it's showing of where else PSV1 is being
		as the cutting regions where the two substrates		removed.
		are going to be diced. And again, I see the PSV1	5	
		labels, but I can't see where they end. I can't	· ·	PSV1 is not over the DTM or the GTM?
		tell from this figure.	7	5 7
		BY MR. GIBSON:	8	,
	9	Q. All right. So based on your		Fig. 9. I can't imagine a way to contact to those
		understanding, they may or may not overlap the		terminals if it was allowed to remain there in the
		sealant, PSV1?	1	final product. Clearly this Fig. 5 is an
	12	A. Well, based on Fig. 5, it's not clear to		intermediate step, right, because it still has
1		me. As I've already said, Fig. 9 shows it	13	display substrates that haven't been cut to their
		partially, only partially under the sealant.	1	final form. So the status of that in Fig. 5 is
	15	Q. And the PSV1 that's on the left the	1	not clear at all to me.
		left lower part of Fig. 5, doesn't that show you		BY MR. GIBSON:
		the extent of the overlap, that there's going to	17	Q. Would you agree that the PSV1 layer is
1		be PSV1 to that point?		approximately 1 micron thick?
1	19	A. Well, if that were the case, it would be	19	A. I can agree that that's a typical
- E		inconsistent with Fig. 9, right. Fig. 9 shows a		thickness of a passivation film. I don't recall
		sealant where the right side does have PSV under	1	if Nakamoto specifically identifies thickness.
		part of it, but the left side does not.	22	Q. Let's look at paragraph 90.
	23	And if we look at Fig. 5 and look where	23	A. Paragraph 90 points to PSV1 as being
-		the sealant is, what you're suggesting to me is		made approximately 1 micron film thickness.
12	25	that the PSV1 just goes underneath the whole	25	Q. And if you look at paragraph 91, which
		Page 103	_	Page 105
		from from that line in the middle left side of		is discussing Fig. 5, does that help you
		Fig. 5 all the way to the right and that can't be.		understand the extent of PSV1?
		It has to end somewhere, right, because Fig. 9	3	A. I'll take a minute and read it
		shows an example of where that is. So I can't		carefully. Okay. And can you remind me your
		tell from this figure, this top-down, black and	5	question?
		white illustration where those ending points are.	6	Q. Doesn't that inform you that as you
	7	Q. Well, there can be multiple embodiments	7	said, PSV1, it's going to be laid over and then
		of a patent, right?	8	it's going to be cut back, right?
	9	A. Yes.	9	A. Openings are going to be formed in it.
	10	Q. Do you know if Fig. 5 and Fig. 9 are the	10	Q. Openings are going to be formed in it.
		same embodiment?	11	And it's desirable to leave as much of
1.	12	A. I don't recall if Nakamoto describes it		the PSV1 in place as possible, right?
1		that way.	13	A. It depends. The disclosure in
1 1	14	Q. Okay. So you can't tell where the	14	paragraph 91 describes removing it from certain
1   1   1	14 15	Q. Okay. So you can't tell where the passivation layer ends from Fig. 5?	14 15	paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly
1   1   1   1	14 15 16	<ul><li>Q. Okay. So you can't tell where the passivation layer ends from Fig. 5?</li><li>A. Fig. 5 is not clear on where is</li></ul>	14 15 16	paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere
1 1 1 1	14 15 16 17	<ul> <li>Q. Okay. So you can't tell where the passivation layer ends from Fig. 5?</li> <li>A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It</li> </ul>	14 15 16 17	paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that
1 1 1 1 1	14 15 16 17	<ul> <li>Q. Okay. So you can't tell where the passivation layer ends from Fig. 5?</li> <li>A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It certainly is clear, even in Fig. 5, that you have</li> </ul>	14 15 16 17 18	paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that even.
1 1 1 1 1 1 1 1	14 15 16 17 18	<ul> <li>Q. Okay. So you can't tell where the passivation layer ends from Fig. 5?</li> <li>A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It certainly is clear, even in Fig. 5, that you have terminals, right. There's DTM terminals and then</li> </ul>	14 15 16 17 18 19	paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that even. Q. Well, what's going to happen is there's
1 1 1 1 1 1 1 2	14 15 16 17 18 19 20	<ul> <li>Q. Okay. So you can't tell where the passivation layer ends from Fig. 5?</li> <li>A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It certainly is clear, even in Fig. 5, that you have terminals, right. There's DTM terminals and then there's GTM terminals. And clearly PSV1 is an</li> </ul>	14 15 16 17 18 19 20	<ul> <li>paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that even.</li> <li>Q. Well, what's going to happen is there's going to be a PSV1 that's going to when it's</li> </ul>
1 1 1 1 1 1 1 1 2 2	14 15 16 17 18 19 20 21	Q. Okay. So you can't tell where the passivation layer ends from Fig. 5? A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It certainly is clear, even in Fig. 5, that you have terminals, right. There's DTM terminals and then there's GTM terminals. And clearly PSV1 is an insulator that's applied after all of the	14 15 16 17 18 19 20 21	<ul> <li>paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that even.</li> <li>Q. Well, what's going to happen is there's going to be a PSV1 that's going to when it's laid down is going to cover up the GTM and the</li> </ul>
1 1 1 1 1 1 1 1 1 2 2 2	14 15 16 17 18 19 20 21 22	Q. Okay. So you can't tell where the passivation layer ends from Fig. 5? A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It certainly is clear, even in Fig. 5, that you have terminals, right. There's DTM terminals and then there's GTM terminals. And clearly PSV1 is an insulator that's applied after all of the conductors are deposited.	14 15 16 17 18 19 20 21 22	paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that even. Q. Well, what's going to happen is there's going to be a PSV1 that's going to when it's laid down is going to cover up the GTM and the DTM; it's going to it's going to cover a large
1 1 1 1 1 1 1 1 2 2 2 2 2	14 15 16 17 18 19 20 21 22 23	<ul> <li>Q. Okay. So you can't tell where the passivation layer ends from Fig. 5?</li> <li>A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It certainly is clear, even in Fig. 5, that you have terminals, right. There's DTM terminals and then there's GTM terminals. And clearly PSV1 is an insulator that's applied after all of the conductors are deposited. So all of the conductors have been</li> </ul>	14 15 16 17 18 19 20 21 22 23	<ul> <li>paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that even.</li> <li>Q. Well, what's going to happen is there's going to be a PSV1 that's going to when it's laid down is going to cover up the GTM and the DTM; it's going to it's going to cover a large part of Fig. 5?</li> </ul>
1 1 1 1 1 1 1 1 1 2 2 2 2 2 2 2 2	14 15 16 17 18 19 20 21 22 23 24	Q. Okay. So you can't tell where the passivation layer ends from Fig. 5? A. Fig. 5 is not clear on where is passivation layer and where is not, PSV1. It certainly is clear, even in Fig. 5, that you have terminals, right. There's DTM terminals and then there's GTM terminals. And clearly PSV1 is an insulator that's applied after all of the conductors are deposited.	14 15 16 17 18 19 20 21 22 23 24	paragraph 91 describes removing it from certain parts. There's, I think, no teaching, explicitly at least, that you have to leave it everywhere else or that or that he prefers to do that even. Q. Well, what's going to happen is there's going to be a PSV1 that's going to when it's laid down is going to cover up the GTM and the DTM; it's going to it's going to cover a large

27 (Pages 102 - 105)

			Page 108
1	Page 106 Q. And then he's then Nakamoto's	1	I do see in Fig. 9 an instance where
1	disclosing what is going to be cut back in order	1	there's an opening underneath the sealant that's
1	to open up certain connections, correct?		been formed, and PSV1 is only over part of it. I
4	A. He's disclosing in at least one example		don't see Nakamoto limiting it to just those.
	the openings that he would create.	5	Q. What he teaches is just removing it over
6	Q. And he also discloses he wants to have		the DTM and GTM?
1	the PSV1 cover as large a range cover large	7	A. His disclosure's not limited to that.
	ranges, as large a range as possible, correct?	8	He also opens it up over the regions that relate
9	MR. SCHLITTER: Objection, form,		to the silver paste, AGP. It's that square or
	foundation.	1	it's it's in that region with that square and
11	THE WITNESS: Could you point me to that		the second label of PSV1.
1	disclosure?	12	And so it sounds to me like you want me
1	BY MR. GIBSON:	13	to speculate on where else he's making openings.
14	Q. Look at paragraph 93.	14	I don't know. He's identified at least three in
15	A. Well, his paragraph 93 says what it	15	this one figure.
16	says.	16	Q. Okay. But those are the only three he's
17	Q. Right. And as one of ordinary skill in	17	identified, the box with the circle, and then the
18	the art, you understand that you want to leave as	18	DTM and GTM? He doesn't identify any others,
19	much of the PSV1 in tact as possible?	19	correct?
20	A. I can agree that a person of ordinary	20	A. In the text and in Fig. 5, he doesn't
21	skill will be inclined to leave the layer present,	21	identify any others because yeah.
22	but it does depend on the design on whether that's	22	Q. Now, in view of Fig. 5, where does the
23	an advantage or preferable or not.	23	where do the DTM lines run?
24	Q. But in Fig. 5, that's what he's teaching	24	A. Well, we see the DTM lines at the top of
25	to leave as much of it as possible and you're	25	the figure, top right.
	Page 107		Page 109
1	going to open up the DTM and the GTM, right?	1	Q. Right.
2	A. Well, in paragraph 91 through apparently	2	A. And it's the series of vertical wirings.
	n. wen, in pulugiuph of unough uppulonuly	2	
3	93 at least, he's disclosing what he's doing with	2 3	Q. And where do they stop?
			-
4 5	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way	3 4 5	<ul><li>Q. And where do they stop?</li><li>A. Well, the figure shows that they're</li><li>long vertically long traces with a smaller</li></ul>
4 5 6	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants	3 4 5 6	Q. And where do they stop? A. Well, the figure shows that they're long vertically long traces with a smaller width and they at least some of them go from
4 5 6	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way	3 4 5 6 7	Q. And where do they stop? A. Well, the figure shows that they're long vertically long traces with a smaller width and they at least some of them go from what is the terminal where the FPC will connect,
4 5 6 7	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants	3 4 5 6 7 8	Q. And where do they stop? A. Well, the figure shows that they're long vertically long traces with a smaller width and they at least some of them go from what is the terminal where the FPC will connect, as shown in Fig. 9, and then proceed, some of
4 5 6 7 8 9	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants to contact the conductors at the terminal regions and those conductors which connect to the upper portion.	3 4 5 6 7 8 9	Q. And where do they stop? A. Well, the figure shows that they're long vertically long traces with a smaller width and they at least some of them go from what is the terminal where the FPC will connect, as shown in Fig. 9, and then proceed, some of them, across the seal on the upper side of the
4 5 6 7 8 9 10	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants to contact the conductors at the terminal regions and those conductors which connect to the upper portion. And beyond that, in 93, he's pointing	3 4 5 6 7 8 9 10	Q. And where do they stop? A. Well, the figure shows that they're long vertically long traces with a smaller width and they at least some of them go from what is the terminal where the FPC will connect, as shown in Fig. 9, and then proceed, some of them, across the seal on the upper side of the display and then into the display region. I think
4 5 6 7 8 9 10 11	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants to contact the conductors at the terminal regions and those conductors which connect to the upper portion. And beyond that, in 93, he's pointing out that his intention is to cover an area that's	3 4 5 6 7 8 9 10 11	Q. And where do they stop? A. Well, the figure shows that they're long vertically long traces with a smaller width and they at least some of them go from what is the terminal where the FPC will connect, as shown in Fig. 9, and then proceed, some of them, across the seal on the upper side of the display and then into the display region. I think it's called AR.
4 5 6 7 8 9 10 11 12	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants to contact the conductors at the terminal regions and those conductors which connect to the upper portion. And beyond that, in 93, he's pointing out that his intention is to cover an area that's larger than the gate insulation film G1 so that it	3 4 5 6 7 8 9 10 11 12	<ul> <li>Q. And where do they stop?</li> <li>A. Well, the figure shows that they're</li> <li>long vertically long traces with a smaller</li> <li>width and they at least some of them go from</li> <li>what is the terminal where the FPC will connect,</li> <li>as shown in Fig. 9, and then proceed, some of</li> <li>them, across the seal on the upper side of the</li> <li>display and then into the display region. I think</li> <li>it's called AR.</li> <li>Q. And where the GTM lines, where do</li> </ul>
4 5 6 7 8 9 10 11 12 13	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants to contact the conductors at the terminal regions and those conductors which connect to the upper portion. And beyond that, in 93, he's pointing out that his intention is to cover an area that's larger than the gate insulation film G1 so that it can cover the peripheral areas. That's what it	3 4 5 6 7 8 9 10 11 12 13	<ul> <li>Q. And where do they stop?</li> <li>A. Well, the figure shows that they're</li> <li>long vertically long traces with a smaller</li> <li>width and they at least some of them go from</li> <li>what is the terminal where the FPC will connect,</li> <li>as shown in Fig. 9, and then proceed, some of</li> <li>them, across the seal on the upper side of the</li> <li>display and then into the display region. I think</li> <li>it's called AR.</li> <li>Q. And where the GTM lines, where do</li> <li>they extend?</li> </ul>
4 5 7 8 9 10 11 12 13 14	93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants to contact the conductors at the terminal regions and those conductors which connect to the upper portion. And beyond that, in 93, he's pointing out that his intention is to cover an area that's larger than the gate insulation film G1 so that it can cover the peripheral areas. That's what it says. That's his disclosure. I have no reason to	3 4 5 6 7 8 9 10 11 12 13 14	<ul> <li>Q. And where do they stop?</li> <li>A. Well, the figure shows that they're</li> <li>long vertically long traces with a smaller</li> <li>width and they at least some of them go from</li> <li>what is the terminal where the FPC will connect,</li> <li>as shown in Fig. 9, and then proceed, some of</li> <li>them, across the seal on the upper side of the</li> <li>display and then into the display region. I think</li> <li>it's called AR.</li> <li>Q. And where the GTM lines, where do</li> <li>they extend?</li> <li>A. The GTM lines are on the orthogonal side</li> </ul>
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4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>93 at least, he's disclosing what he's doing with this PSV1 layer. He applies it through the whole substrate. It generally has to be done that way and then openings are created. Clearly he wants to contact the conductors at the terminal regions and those conductors which connect to the upper portion.</li> <li>And beyond that, in 93, he's pointing out that his intention is to cover an area that's larger than the gate insulation film G1 so that it can cover the peripheral areas. That's what it says. That's his disclosure. I have no reason to disagree with that, but I would not generalize that to an important principle that one of ordinary skill would follow.</li> <li>Q. Doesn't that show you that in Exhibit 5 that the PSV layer is going to be over what you've drawn as the sealant? Isn't that explicitly taught by Fig. 5 and the paragraphs that correspond to it?</li> </ul>	3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>Q. And where do they stop?</li> <li>A. Well, the figure shows that they're</li> <li>long vertically long traces with a smaller</li> <li>width and they at least some of them go from</li> <li>what is the terminal where the FPC will connect,</li> <li>as shown in Fig. 9, and then proceed, some of</li> <li>them, across the seal on the upper side of the</li> <li>display and then into the display region. I think</li> <li>it's called AR.</li> <li>Q. And where the GTM lines, where do</li> <li>they extend?</li> <li>A. The GTM lines are on the orthogonal side</li> <li>of the substrate. They're in the bottom left of</li> <li>Fig. 5 and they have their own terminals, of</li> <li>course, and they extend from that terminal from</li> <li>left to right and at least some of them go across</li> <li>the sealant and also access the display area AR</li> <li>and each of those, of course, form independently</li> <li>connection to the TFT array, the gate and the</li> </ul>

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1		1	
1	Page 110 outside the seal or under the seal. If they ever	1	Page 11 the terminal region.
	cross, it's in the TFT, the display portion.	2	-
3	Q. If you look at Fig. 9, would you agree		package to be the same thing as an FPC?
	that we've talked about it discloses a sealant.	4	A. In general, I would.
5	Do you also see that it discloses a	5	Q. Let's look at the '413 patent for a
	signal line?		moment, which you should have in front of you
	-	7	A. I've got it.
7	A. It discloses a DTM, so what I understand to be the drain terminal. I think I'll need to	8	Q. It's Exhibit 1001. If you look at
1	refresh myself on the labels just for a moment.		
10	Q. Sure. I need to get my pen back too.	10	A. Got it.
11	A. Sorry.	11	Q and Claim 1 discusses first and
12	Q. Here's one if we need one later.	1	second wirings that extend under the sealant, is
13	A. Okay. The signal lines are identified		that correct?
1	as DL.	14	A. Well, to be precise, it says, "A sealant
15	Q. Right.		over a first wiring and a second region of a
16	A. And DL is labeled in Fig. 9.		second wiring."
17	Q. And that's the the DL is under the	17	Q. So you would expect there to be a first
18	sealant?		wiring and a second wiring under the sealant,
19	A. The element identified as DL seems to go		correct?
20	from the left of the bottom substrate across under	20	A. I would expect it to be
21	the sealant to the right side.	21	Q. In that region?
22	Q. And the DL line, it connects to an	22	A under the sealant at least partially
23	external tape carrier package, the TCP?	23	in that region.
24	A. When you say "connects," how do you mean	24	Q. Would you agree that the claims don't
25	connects? Clearly there's an electrical	25	specify whether those wirings are side by side or
	Page 111		Page 112
1	connection.	· 1	stacked?
2	Q. Yes. There's an electrical connection?	_	
	2. I es. Indies an elecated connection.	2	A. I disagree. I think that Claim 1
3	A. So whether or not there's a direct		-
3	A. So whether or not there's a direct	3	clearly teaches that it must be overlapping, at
3 4	A. So whether or not there's a direct connection, I'd have to study a bit more if that's	3 4	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim
3 4 5	A. So whether or not there's a direct connection, I'd have to study a bit more if that's what you're asking me about.	3 4 5	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim element it says the second wiring overlaps at
3 4 5 6	<ul><li>A. So whether or not there's a direct connection, I'd have to study a bit more if that's what you're asking me about.</li><li>Q. You would agree there's an electrical</li></ul>	3 4 5 6	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim element it says the second wiring overlaps at least part of the first wiring and it refers to
3 4 5 6 7	<ul><li>A. So whether or not there's a direct connection, I'd have to study a bit more if that's what you're asking me about.</li><li>Q. You would agree there's an electrical connection?</li></ul>	3 4 5 6 7	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim element it says the second wiring overlaps at least part of the first wiring and it refers to all the others as being over each other.
3 4 5 6 7 8	<ul><li>A. So whether or not there's a direct connection, I'd have to study a bit more if that's what you're asking me about.</li><li>Q. You would agree there's an electrical connection?</li><li>A. There is an electrical connection from</li></ul>	3 4 5 6 7 8	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim element it says the second wiring overlaps at least part of the first wiring and it refers to all the others as being over each other. MR. GIBSON: If we're at 10 minutes, why
3 4 5 6 7 8 9	<ul> <li>A. So whether or not there's a direct connection, I'd have to study a bit more if that's what you're asking me about.</li> <li>Q. You would agree there's an electrical connection?</li> <li>A. There is an electrical connection from DL to what's identified as DTM and the FPC that's</li> </ul>	3 4 5 6 7 8 9	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim element it says the second wiring overlaps at least part of the first wiring and it refers to all the others as being over each other. MR. GIBSON: If we're at 10 minutes, why don't we go ahead and change the tape.
3 4 5 6 7 8 9 10	<ul> <li>A. So whether or not there's a direct connection, I'd have to study a bit more if that's what you're asking me about.</li> <li>Q. You would agree there's an electrical connection?</li> <li>A. There is an electrical connection from DL to what's identified as DTM and the FPC that's shown in Fig. 9.</li> </ul>	3 4 5 6 7 8 9 10	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim element it says the second wiring overlaps at least part of the first wiring and it refers to all the others as being over each other. MR. GIBSON: If we're at 10 minutes, why don't we go ahead and change the tape. VIDEOGRAPHER: We're going off record.
3 4 5 6 7 8 9 10 11	<ul> <li>A. So whether or not there's a direct connection, I'd have to study a bit more if that's what you're asking me about.</li> <li>Q. You would agree there's an electrical connection?</li> <li>A. There is an electrical connection from DL to what's identified as DTM and the FPC that's shown in Fig. 9.</li> <li>Q. In Fig. 9, the ITO layer, which is that</li> </ul>	3 4 5 6 7 8 9 10 11	clearly teaches that it must be overlapping, at least partially. After all, it has in the claim element it says the second wiring overlaps at least part of the first wiring and it refers to all the others as being over each other. MR. GIBSON: If we're at 10 minutes, why don't we go ahead and change the tape. VIDEOGRAPHER: We're going off record. This is the end of Media Unit Number 2. The time
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29 (Pages 110 - 113)

Page 114	Τ	Page 116
AFTERNOON SESSION		semiconductor to replace a metal generally.
VIDEOGRAPHER: We're now back on record.	2	(Documents marked previously as Exhibit
This is the beginning of Media Unit Number 3 in	3	Numbers 2013 through 2020 were
the deposition of Dr. Michael Escuti and the time	4	presented.)
is 1:47. Please continue.	5	BY MR. GIBSON:
EXAMINATION (Resumed)	6	Q. Let's go ahead and look at the exhibits
BY MR. GIBSON:	7	that were attached to your declaration. I'm just
Q. You understand that you're still under	8	going to hand you the whole stack of them. It
oath?	9	will just be easier. Thank you for making a copy
A. I do.	10	of them or having a copy made. So if we
Q. Did you have a chance to talk about your	11	MR. SCHLITTER: Just to be clear, I only
testimony or substance of your testimony with	12	asked for the exhibits that were referenced in
anyone at any of the breaks today?	13	that one paragraph, 161.
	14	MR. GIBSON: And that's what I meant
my testimony at all.	15	to
Q. And we were covering some of the organic	16	MR. SCHLITTER: Okay.
materials in the TFTs that you used.	17	MR. GIBSON: say. So we're on the
What are some of the advantages of using	18	same page. That's what I've handed him and that's
organic materials?	19	what I mean to ask him about at this point, not
A. As opposed to what?	20	the other exhibits or the appendices. I think
Q. Inorganic.	21	everything else is attached.
A. The principal advantage is one of cost	22	THE WITNESS: Which appendix do you want
	23	me to turn to?
And that's why we have OLED displays rather than	24	BY MR. GIBSON:
LED displays in our phones that are made of	25	Q. Your exhibit
Page 115		Page 117
-	1	A. Yeah, which exhibit do you want me to
-	2	turn to?
	3	Q. Why don't we start the 2015, which is
	4	
	5	A. I see it. Can I a take a moment to
	6	Q. Sure.
	7	A review it?
- 41	1	
otherwise.	8	Okay. I've reviewed it again now.
	8	
For example, there are stacking configurations that are possible and arrangements	9	Okay. I've reviewed it again now.
For example, there are stacking	9 10	Okay. I've reviewed it again now. Q. Okay. And would you agree with me that
For example, there are stacking configurations that are possible and arrangements	9 10	Okay. I've reviewed it again now. Q. Okay. And would you agree with me that this document is describing general purpose
For example, there are stacking configurations that are possible and arrangements of the layers in a way that's advantageous for a	9 10 11 12	Okay. I've reviewed it again now. Q. Okay. And would you agree with me that this document is describing general purpose coating equipment?
For example, there are stacking configurations that are possible and arrangements of the layers in a way that's advantageous for a particular display.	9 10 11 12 13	Okay. I've reviewed it again now. Q. Okay. And would you agree with me that this document is describing general purpose coating equipment? A. This document doesn't limit the purpose
For example, there are stacking configurations that are possible and arrangements of the layers in a way that's advantageous for a particular display. Q. Now, the '413 patent, would you agree	9 10 11 12 13	Okay. I've reviewed it again now. Q. Okay. And would you agree with me that this document is describing general purpose coating equipment? A. This document doesn't limit the purpose of the instrument and techniques that it's
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	<ul> <li>VIDEOGRAPHER: We're now back on record.</li> <li>This is the beginning of Media Unit Number 3 in the deposition of Dr. Michael Escuti and the time is 1:47. Please continue. EXAMINATION (Resumed)</li> <li>BY MR. GIBSON: <ul> <li>Q. You understand that you're still under oath?</li> <li>A. I do.</li> <li>Q. Did you have a chance to talk about your testimony or substance of your testimony with anyone at any of the breaks today?</li> <li>A. I've not talked about this deposition or my testimony at all.</li> <li>Q. And we were covering some of the organic materials in the TFTs that you used. What are some of the advantages of using organic materials?</li> <li>A. As opposed to what?</li> <li>Q. Inorganic.</li> <li>A. The principal advantage is one of cost in both the material itself and in the processing. And that's why we have OLED displays rather than LED displays in our phones that are made of</li> </ul> </li> </ul>	VIDEOGRAPHER: We're now back on record.2This is the beginning of Media Unit Number 3 in3the deposition of Dr. Michael Escuti and the time4is 1:47. Please continue.5EXAMINATION (Resumed)6BY MR. GIBSON:7Q. You understand that you're still under8oath?9A. I do.10Q. Did you have a chance to talk about your11testimony or substance of your testimony with12anyone at any of the breaks today?13A. I've not talked about this deposition or14my testimony at all.15Q. And we were covering some of the organic16materials in the TFTs that you used.17What are some of the advantages of using18organic materials?20Q. Inorganic.21A. The principal advantage is one of cost22in both the material itself and in the processing.23And that's why we have OLED displays rather than24LED displays in our phones that are made of25Page 115inorganic materials.1Q. Any other advantages?2A. There's there are many other3advantages. Another one is that the device4structures that can be made with organic5semiconductors can often be substantially6

<ol> <li>BY MR. GIBSON:</li> <li>Q. Well, no. Wh</li> <li>though is coating equ</li> <li>purpose of the equipn</li> <li>right?</li> <li>A. I'll give what I</li> <li>answer. It's discussin</li> </ol>	Page 118		~
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<ul> <li>3 though is coating equ</li> <li>4 purpose of the equipn</li> <li>5 right?</li> <li>6 A. I'll give what I</li> <li>7 answer. It's discussion</li> </ul>	atta haina diagnagad hara	-	-
<ol> <li>4 purpose of the equipm</li> <li>5 right?</li> <li>6 A. I'll give what I</li> <li>7 answer. It's discussion</li> </ol>	-	2 display	
5 right? 6 A. I'll give what 1 7 answer. It's discussin	-		It's my understanding that epitaxial
6 A. I'll give what 1 7 answer. It's discussin	•	-	n is not a standard process.
7 answer. It's discussin			For flat panel displays?
ſ			For flat panel displays.
		-	Would you understand that the size of a
8 creating films, one is	1 /		ate that can fit into one of the lasers that
			is describing is very small?
10 or equipment.			What do you mean by "very small"?
		-	Well, it would be smaller than your
12 Vacuum Thin Film Co			rd flat panel displays?
13 A. Even though t			What do you mean by "standard flat panel
14 titled.	14	~ ·	"? I think all of us have typical sizes.
	1 2 1		Well, what's your what's your
16 not listed as a main ap	plication for this 10		tanding of a standard flat panel display?
17 equipment?			I don't think there is a standard size
18 A. I can agree that	t display repair is not 1	18 for a fl	at panel display, even in 1997.
19 explicitly mentioned a			And do you know if this laser was
20 Q. If we turn to the	ne next exhibit, 2016, 20	20 availat	ble in 1997?
21 which is the Pascal ex	hibit, if you want to take a 2	21 A.	Well, as we said or as I just said,
22 moment to refresh you	ir memory on it, just let me 22	22 there's	not much detail provided in this document
23 know when you're do	ne. 23	23 as to th	at laser. I can speculate, but I'm not
24 A. Yes, thank you	1. 24	24 sure ho	ow helpful that is.
25 Okay, I've revie	wed it.	25 Q.	You don't know?
	Page 119		Page 121
1 Q. Would you ag		1 A.	Well, it's a it's a pulsed laser and
			family of lasers that have been
3 does not describe a pr			nown for decades.
4 displays?		4 O.	What's the size of the largest size
	this document does not	-	te that could be used with this laser?
6 explicitly mention dis			I'm not sure there is an answer to that.
			d mostly depend on the size of the chamber
8 pulse laser deposition.			for example, illustrated in the first
<ul><li>9 mention some applica</li></ul>	1		It's, in my view, less constrained by the
10 displays.			id certainly one could put multiple targets
			Itiple lasers in conjunction to illuminate a
12 laser that's used for ep			area if that was ever needed.
12 lasor mars used for ep	12 12 12 12 12 12 12 12 12 12 12 12 12 1	-	But that's not what's being described
12 correct?		4 here, c	-
13 correct?		•	
14 A. I don't think it			No, no. Multiple lasers and multiple
14 A. I don't think it 15 mentions that the proc	about it	o largets	is not mentioned here
<ul><li>A. I don't think it</li><li>mentions that the proc</li><li>doesn't say very much</li></ul>		7 0	is not mentioned here.
<ul> <li>A. I don't think it</li> <li>mentions that the proc</li> <li>doesn't say very much</li> <li>Q. Okay. Do you</li> </ul>	understand that it's used 17		And you don't have an idea of what size
<ul> <li>A. I don't think it</li> <li>mentions that the proc</li> <li>doesn't say very much</li> <li>Q. Okay. Do you</li> <li>for epitaxial materials.</li> </ul>	understand that it's used 17 , a laser? 18	8 substra	And you don't have an idea of what size te could fit inside one of the Pascal laser
<ul> <li>A. I don't think it</li> <li>mentions that the proc</li> <li>doesn't say very much</li> <li>Q. Okay. Do you</li> <li>for epitaxial materials</li> <li>A. The laser is use</li> </ul>	understand that it's used17, a laser?18ed to as a kind of19	8 substra 9 MBEs	And you don't have an idea of what size te could fit inside one of the Pascal laser
<ul> <li>A. I don't think it</li> <li>mentions that the proc</li> <li>doesn't say very much</li> <li>Q. Okay. Do you</li> <li>for epitaxial materials,</li> <li>A. The laser is use</li> <li>exciting energy to pulse</li> </ul>	understand that it's used17, a laser?18ed to as a kind of19se the target and get the20	8 substra 9 MBEs 20 A.	And you don't have an idea of what size te could fit inside one of the Pascal laser I don't have specific knowledge of what
<ul> <li>A. I don't think it</li> <li>mentions that the proc</li> <li>doesn't say very much</li> <li>Q. Okay. Do you</li> <li>for epitaxial materials,</li> <li>A. The laser is use</li> <li>exciting energy to puls</li> <li>target materials off of</li> </ul>	understand that it's used17, a laser?18ed to as a kind of19se the target and get the20the target and then21	8 substra 9 MBEs 0 A. 1 size co	And you don't have an idea of what size te could fit inside one of the Pascal laser I don't have specific knowledge of what uld be accepted inside.
<ul> <li>A. I don't think it</li> <li>mentions that the proc</li> <li>doesn't say very much</li> <li>Q. Okay. Do you</li> <li>for epitaxial materials</li> <li>A. The laser is use</li> <li>exciting energy to puls</li> <li>target materials off of</li> <li>through the rest of the</li> </ul>	understand that it's used17, a laser?18ed to as a kind of19se the target and get the20the target and then21process onto the substrate22	8         substra           9         MBEs           20         A.           21         size co           22         Q.	And you don't have an idea of what size te could fit inside one of the Pascal laser I don't have specific knowledge of what uld be accepted inside. Do you have any knowledge of the size?
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31 (Pages 118 - 121)

	N 100	1	
1	Page 122 Pascal laser MBE is ever used with displays, LCD	1	Page 124 the with control over where and what size, what
1	displays?	1	amount is being removed. And that's indeed a very
3			standard product to repair TFT substrates,
1	but that's not the purpose of these paragraphs or	1	especially at the time of 1997.
1	why I included these websites. It was more a	5	
	•		
1	general analysis responding to Dr. Hatalis'	1	discussing any use of this equipment for repair,
	comments about processes that might be used or		correct?
	could be used. And so this is my brainstorming	8	A. It doesn't explicitly discuss that. It
9			also doesn't rule it out. And I'm providing this
	to, and this is one that came to mind.	1	document as simply an example of a tool that is
11	Q. Don't you think it would be important to	1	used for laser ablation and is a kind of tool that
	know whether this was actually ever used with	1	is used in the LCD industry for repairs.
	displays or not before including it in your	13	Q. Have you ever used any of the equipment
1	declaration that deals with LCD displays?		we've been talking about for repair?
15	A. On this issue, no, I don't think it's	15	A. I've used some of this for fabrication
	important.	1	and what I think of as repair, but admittedly not
17	Q. If we look at the next one,	17	in an industrial setting.
18	Exhibit 2017, the Micro-Tec, do you want to	18	Q. If we turn to Exhibit 2019, this is the
19		1	MicroFab website document. If you want to take a
20	me know when you're		moment to familiarize yourself with that, let me
21	A. Yes, thank you.	21	know when you're finished.
22	Q done.	22	A. Yes, thank you. Okay. I've reviewed
23	A. Okay. I've reviewed it.	23	it.
24	Q. Would you agree that the equipment	24	Q. And would you agree that the MicroFab
25	listed is for products and not for repair?	25	website and the pages you've attached at least
	Page 123		Page 125
1	A. I'm not sure I can limit it in that way.	1	does not list display repair?
2	I don't agree. It's a document that describes	2	A. It does not list display repair.
	-		O Would you agree that there products are
	screen printing, which is common in LCD industry	3	Q. would you agree that these products are
4	screen printing, which is common in LCD industry for various purposes.	1	Q. Would you agree that these products are not even aimed at display production?
4 5	for various purposes.	4	not even aimed at display production?
5	for various purposes. Q. Does it ever mention any type of repair	1	not even aimed at display production? MR. SCHLITTER: Objection, form.
5 6	for various purposes. Q. Does it ever mention any type of repair anywhere in the document?	4 5 6	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that
5 6 7	<ul><li>for various purposes.</li><li>Q. Does it ever mention any type of repair anywhere in the document?</li><li>A. To the best of my memory and to the best</li></ul>	4 5 6 7	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I
5 6 7 8	<ul><li>for various purposes.</li><li>Q. Does it ever mention any type of repair anywhere in the document?</li><li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't</li></ul>	4 5 6 7 8	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is
5 6 7 8 9	<ul><li>for various purposes.</li><li>Q. Does it ever mention any type of repair anywhere in the document?</li><li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't mention repair at all.</li></ul>	4 5 6 7 8 9	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is used, it's possible.
5 6 7 8 9 10	<ul><li>for various purposes.</li><li>Q. Does it ever mention any type of repair anywhere in the document?</li><li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't mention repair at all.</li><li>Q. If we could look at the next one which</li></ul>	4 5 6 7 8 9 10	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is used, it's possible. BY MR. GIBSON:
5 6 7 8 9 10 11	<ul><li>for various purposes.</li><li>Q. Does it ever mention any type of repair anywhere in the document?</li><li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't mention repair at all.</li><li>Q. If we could look at the next one which is Exhibit 2018?</li></ul>	4 5 6 7 8 9 10 11	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is used, it's possible. BY MR. GIBSON: Q. Okay, but you're not aware of an
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5 6 7 8 9 10 11 12 13	<ul> <li>for various purposes.</li> <li>Q. Does it ever mention any type of repair anywhere in the document?</li> <li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't mention repair at all.</li> <li>Q. If we could look at the next one which is Exhibit 2018?</li> <li>A. Okay, I've reviewed it.</li> <li>Q. And this is from the ULVAC website?</li> </ul>	4 5 6 7 8 9 10 11 12 13	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is used, it's possible. BY MR. GIBSON: Q. Okay, but you're not aware of an instance where this is used for display production?
5 6 7 8 9 10 11 12 13 14	<ul> <li>for various purposes.</li> <li>Q. Does it ever mention any type of repair anywhere in the document?</li> <li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't mention repair at all.</li> <li>Q. If we could look at the next one which is Exhibit 2018?</li> <li>A. Okay, I've reviewed it.</li> <li>Q. And this is from the ULVAC website?</li> <li>A. Yes.</li> </ul>	4 5 7 8 9 10 11 12 13 14	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is used, it's possible. BY MR. GIBSON: Q. Okay, but you're not aware of an instance where this is used for display production? A. I'm not.
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5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	<ul> <li>for various purposes.</li> <li>Q. Does it ever mention any type of repair anywhere in the document?</li> <li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't mention repair at all.</li> <li>Q. If we could look at the next one which is Exhibit 2018?</li> <li>A. Okay, I've reviewed it.</li> <li>Q. And this is from the ULVAC website?</li> <li>A. Yes.</li> <li>Q. Would you agree that this the equipment that's listed here is directed to production of thin film solar cells?</li> <li>A. In part it's explicitly mentioned that an application is thin film solar cells, but it is also representative of those systems that are used</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is used, it's possible. BY MR. GIBSON: Q. Okay, but you're not aware of an instance where this is used for display production? A. I'm not. Q. And it doesn't state in the document that it should be used for display production, correct? A. Well, it doesn't specifically mention displays, but certainly it's talking about microelectronics in general and highlights its
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5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>for various purposes.</li> <li>Q. Does it ever mention any type of repair anywhere in the document?</li> <li>A. To the best of my memory and to the best of my review in these few minutes, it doesn't mention repair at all.</li> <li>Q. If we could look at the next one which is Exhibit 2018?</li> <li>A. Okay, I've reviewed it.</li> <li>Q. And this is from the ULVAC website?</li> <li>A. Yes.</li> <li>Q. Would you agree that this the equipment that's listed here is directed to production of thin film solar cells?</li> <li>A. In part it's explicitly mentioned that an application is thin film solar cells, but it is also representative of those systems that are used to prepare LCDs.</li> <li>Q. It doesn't mention in here that it's</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	not even aimed at display production? MR. SCHLITTER: Objection, form. THE WITNESS: I'm not sure I can go that far. It's an etching technique that, while I don't know of a specific instance where it is used, it's possible. BY MR. GIBSON: Q. Okay, but you're not aware of an instance where this is used for display production? A. I'm not. Q. And it doesn't state in the document that it should be used for display production, correct? A. Well, it doesn't specifically mention displays, but certainly it's talking about microelectronics in general and highlights its ability to increase yields and achieve tight tolerances and all of this is consistent with its

<u> </u>		1	
1	Page 126 A. The document itself doesn't mention	1	Page 128 you trust those conclusions?
$  1 \\ 2$	display production or display repair.	$\begin{vmatrix} 1\\2 \end{vmatrix}$	-
1	Q. I seem to not have the last one,		foundation.
	Exhibit 2021 or I don't have that one, but	4	
	maybe we don't need it for the questions. Let's	1	BY MR. GIBSON:
1	give it a shot.	6	Q. What does it depend on?
7	MR. SCHLITTER: I don't have it.	7	
· ·	BY MR. GIBSON:		being used in the argument or the conclusion that
9	Q. If it turns out we do, then we'll	1	the student is making.
10	A. Depends on the question.	10	Q. Let's go back to your declaration, or
11	Q we can get it at a break.		this paragraph 180 of this declaration. Some of
12	I mean, Exhibit 21 you listed, it was a		the two declarations for both days or from both
	paper from 1994, an SIJ digest of technical papers	1	patents, overlap so I'm endeavoring to use the
	and I assume that you read it, correct?		paragraph numbers that correspond to today's
15	A. I certainly read it multiple times and I		declaration. So I think if we look at page 94,
	recall some of it, but depending on your	1	you also have this in your declaration from the
	questions, I may need it.		'102.
18	Q. Do you know anything about the company	18	This is some some opinions you formed
	Photon Dynamics?	1	reviewing Shiba, correct?
20	A. No.	20	A. This is in the section where I discuss
21	Q. Did you review any of the Photon	1	Shiba. If you're going to ask me specifically
	Dynamics' technology that was available in 1997?	22	
23	A. Not that I can recall. I did review as		minute to remind myself what's written here.
	much as I could about anything that mentioned	24	Q. I was actually more going to focus on
24			
		25	your on the on the drawing
	display repair in the literature. Some of those	25	your on the on the drawing
25	display repair in the literature. Some of those Page 127		Page 129
25 1	display repair in the literature. Some of those Page 127 may have been, but I don't remember if it was that	1	Page 129 A. Okay.
25 1 2	display repair in the literature. Some of those Page 127 may have been, but I don't remember if it was that company in particular.	1 2	Page 129 A. Okay. Q that you've that you've got there.
25 1 2 3	display repair in the literature. Some of those Page 127 may have been, but I don't remember if it was that company in particular. Q. So you're not as you sit here today,	1 2 3	Page 129 A. Okay. Q that you've that you've got there. And you made some other in your other
25 1 2 3 4	display repair in the literature. Some of those Page 127 may have been, but I don't remember if it was that company in particular. Q. So you're not as you sit here today, you couldn't identify Photon Dynamic technology	1 2 3 4	Page 129 A. Okay. Q that you've that you've got there. And you made some other in your other declaration, I think you made another drawing as
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		1	
	Page 130		Page 132
1	Q. Right. You didn't you didn't modify		Fig. A and Fig. B is the relationship between the
	the layerings or the masking process or the	1	processing step that deposits the ITO layer which
E	etching process. This is meant to reflect what	1	is labeled pixel electrode 251 in both layers, the
	would happen if you used Fig. 4 of Shiba?		relationship between that and the other layers,
5	A. That's correct.		especially the source electrode material, but also
6	Q. I'm going to show you from page 49 of		to some extent the protective overcoat.
	your other declaration if we could mark this as	7	And Shiba discloses that first, the ITO
	1012.		is deposited; subsequently, the source electrode
9	(Document marked as Exhibit Number 1012		metal is deposited and then finally, the
10	for identification.)		protective overcoat 241 is deposited. That's the
11			sequence that's disclosed in Shiba explicitly.
12	Q. And what is Exhibit 1012?		Now
13	A. Fig I'm sorry, Exhibit 1012 is	13	Q. And there's an orientation film which
1	largely the same thing but from my other		doesn't have much bearing on your assignment?
	declaration.	15	A. Right. That's right. The orientation
16	MR. GIBSON: And let's mark this as	1	film must be there in an LCD display to control
1	1013.	1	the liquid crystal layer and that's largely the
18	(Document marked as Exhibit Number 1013	1	same in both.
19	for identification.)	19	So Dr. Hatalis has asserted that it
1	BY MR. GIBSON:	1	would be obvious and trivial to apply some known
21	Q. And what is Exhibit 1013?	1	principles from the prior art to create the ITO
22	A. Exhibit 1013 is from page 50 of my		layer in the terminal portion of Shiba and I
	declaration for the '204 patent and it is a	1	disagree for several reasons.
	modification of my drawing in Fig. A, which is in	24	And this is one of the reasons or
25	the first two exhibits we just mentioned, as a	25	this figure is used in one of my reasons to say
1		1	Dece 122
	Page 131		Page 133
	hypothetical structure to consider some of the	1	no, it's not trivial and it's not obvious to a
2	hypothetical structure to consider some of the arguments in the case.	2	no, it's not trivial and it's not obvious to a person of ordinary skill in the art.
2 3	hypothetical structure to consider some of the arguments in the case. Q. And what led you to decide to illustrate	2 3	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the
2 3 4	<ul><li>hypothetical structure to consider some of the arguments in the case.</li><li>Q. And what led you to decide to illustrate this hypothetical structure?</li></ul>	2 3 4	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from
2 3 4 5	<ul><li>hypothetical structure to consider some of the arguments in the case.</li><li>Q. And what led you to decide to illustrate this hypothetical structure?</li><li>A. The arguments that we're talking about</li></ul>	2 3 4 5	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps?
2 3 4 5 6	<ul><li>hypothetical structure to consider some of the arguments in the case.</li><li>Q. And what led you to decide to illustrate this hypothetical structure?</li><li>A. The arguments that we're talking about in the case or the issues relate to the location</li></ul>	2 3 4 5 6	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then
2 3 4 5 6 7	<ul><li>hypothetical structure to consider some of the arguments in the case.</li><li>Q. And what led you to decide to illustrate this hypothetical structure?</li><li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to</li></ul>	2 3 4 5 6 7	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope
2 3 4 5 6 7 8	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those</li> </ul>	2 3 4 5 6 7 8	<ul> <li>no, it's not trivial and it's not obvious to a person of ordinary skill in the art.</li> <li>Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps?</li> <li>A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a</li> </ul>
2 3 4 5 6 7 8 9	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those that discussion clearer, I prepared these</li> </ul>	2 3 4 5 6 7 8 9	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a capacitor line Cj that is then overlaid with a
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2 3 4 5 6 7 8 9 10 11	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those</li> <li> that discussion clearer, I prepared these figures so that we could see very clearly the relationship between the layers.</li> </ul>	2 3 4 5 6 7 8 9 10 11	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a capacitor line Cj that is then overlaid with a gate dielectric material 211. And then on top of that is the ITO pattern next and that forms a
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2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those</li> <li> that discussion clearer, I prepared these figures so that we could see very clearly the relationship between the layers. So Fig. A in both declarations is meant to be what Shiba explicitly discloses and Fig. B is a hypothetical to talk through and to consider a modification of the processing under a hypothetical that Dr. Hatalis seems to be suggesting is possible and obvious and I disagree with him.</li> <li>Q. And what you're doing is you're modifying in Exhibit 1013, you're modifying where the ITO layer goes?</li> </ul>	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a capacitor line Cj that is then overlaid with a gate dielectric material 211. And then on top of that is the ITO pattern next and that forms a capacitor. There's two electrodes. There's a carefully controlled dielectric insulator in between those two electrodes and that's that's how Shiba discloses forming the capacitor. That ITO is deposited before the pad 751 material and the protective overcoat. So it would be not possible to keep the processing steps in Shiba and the relationship among those steps and simply create ITO in the terminal portion around pad 51
2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those that discussion clearer, I prepared these figures so that we could see very clearly the relationship between the layers. So Fig. A in both declarations is meant to be what Shiba explicitly discloses and Fig. B is a hypothetical to talk through and to consider a modification of the processing under a hypothetical that Dr. Hatalis seems to be suggesting is possible and obvious and I disagree with him.</li> <li>Q. And what you're doing is you're modifying in Exhibit 1013, you're modifying where the ITO layer goes?</li> <li>A. Not quite.</li> </ul>	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a capacitor line Cj that is then overlaid with a gate dielectric material 211. And then on top of that is the ITO pattern next and that forms a capacitor. There's two electrodes. There's a carefully controlled dielectric insulator in between those two electrodes and that's that's how Shiba discloses forming the capacitor. That ITO is deposited before the pad 751 material and the protective overcoat. So it would be not possible to keep the processing steps in Shiba and the relationship among those steps and simply create ITO in the terminal portion around pad 51 Q. 751?
2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those</li> <li> that discussion clearer, I prepared these figures so that we could see very clearly the relationship between the layers. So Fig. A in both declarations is meant to be what Shiba explicitly discloses and Fig. B is a hypothetical to talk through and to consider a modification of the processing under a hypothetical that Dr. Hatalis seems to be suggesting is possible and obvious and I disagree with him.</li> <li>Q. And what you're doing is you're modifying in Exhibit 1013, you're modifying where the ITO layer goes?</li> <li>A. Not quite.</li> <li>Q. You're trying to put it over the</li> </ul>	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a capacitor line Cj that is then overlaid with a gate dielectric material 211. And then on top of that is the ITO pattern next and that forms a capacitor. There's two electrodes. There's a carefully controlled dielectric insulator in between those two electrodes and that's that's how Shiba discloses forming the capacitor. That ITO is deposited before the pad 751 material and the protective overcoat. So it would be not possible to keep the processing steps in Shiba and the relationship among those steps and simply create ITO in the terminal portion around pad 51 Q. 751? A 751.
2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those that discussion clearer, I prepared these figures so that we could see very clearly the relationship between the layers. So Fig. A in both declarations is meant to be what Shiba explicitly discloses and Fig. B is a hypothetical to talk through and to consider a modification of the processing under a hypothetical that Dr. Hatalis seems to be suggesting is possible and obvious and I disagree with him.</li> <li>Q. And what you're doing is you're modifying where the ITO layer goes?</li> <li>A. Not quite.</li> <li>Q. You're trying to put it over the protective yellow coat?</li> </ul>	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a capacitor line Cj that is then overlaid with a gate dielectric material 211. And then on top of that is the ITO pattern next and that forms a capacitor. There's two electrodes. There's a carefully controlled dielectric insulator in between those two electrodes and that's that's how Shiba discloses forming the capacitor. That ITO is deposited before the pad 751 material and the protective overcoat. So it would be not possible to keep the processing steps in Shiba and the relationship among those steps and simply create ITO in the terminal portion around pad 51 Q. 751? A 751. Q. One question I had and then I'll let you
2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>hypothetical structure to consider some of the arguments in the case.</li> <li>Q. And what led you to decide to illustrate this hypothetical structure?</li> <li>A. The arguments that we're talking about in the case or the issues relate to the location of the ITO and Fig. 4 of Shiba is kind of hard to see. It's really quite dense. So to make those</li> <li> that discussion clearer, I prepared these figures so that we could see very clearly the relationship between the layers. So Fig. A in both declarations is meant to be what Shiba explicitly discloses and Fig. B is a hypothetical to talk through and to consider a modification of the processing under a hypothetical that Dr. Hatalis seems to be suggesting is possible and obvious and I disagree with him.</li> <li>Q. And what you're doing is you're modifying in Exhibit 1013, you're modifying where the ITO layer goes?</li> <li>A. Not quite.</li> <li>Q. You're trying to put it over the</li> </ul>	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	no, it's not trivial and it's not obvious to a person of ordinary skill in the art. Q. Okay. And how have you modified the steps when we're looking at Exhibit 1013 from Exhibit 1011, how have you modified the steps? A. Sure. So if we begin with Fig. A, then we'll see what we compare to. So Fig. A I hope you can see in the capacitor portion, there's a capacitor line Cj that is then overlaid with a gate dielectric material 211. And then on top of that is the ITO pattern next and that forms a capacitor. There's two electrodes. There's a carefully controlled dielectric insulator in between those two electrodes and that's that's how Shiba discloses forming the capacitor. That ITO is deposited before the pad 751 material and the protective overcoat. So it would be not possible to keep the processing steps in Shiba and the relationship among those steps and simply create ITO in the terminal portion around pad 51 Q. 751? A 751.

	Page 134		Page 136
1	pad 751?	1	of the sequence of the order. So I'm changing the
2	~		disclosure of Shiba to consider a hypothesis that
1	that's that's what's shown in Shiba. There's	1	Dr. Hatalis has said is trivial and obvious.
	no disclosure of ITO in the terminal portion. In	4	Q. Right. Okay. And the steps that you're
1	Fig. B, I didn't apply it there simply because	5	changing, you're still going to go ahead and put
	that's not what I'm using. That's not the area of	1	your capacitor line Cj and your scanning line Yj
	this that I'm focusing on. My discussion is		first, right?
	about the consequence of reversing the order, as	8	A. That's correct, that's the same in both
	Dr. Hatalis is saying, on the capacitor.	9	figures.
10	Q. Right. What I'm asking is, wouldn't you	10	Q. And then you're going to go and put down
11	expect there to be an ITO layer on pad 751 as one	11	the gate dielectric 211, correct?
	of ordinary skill in the art?	12	A. That's what would happen next in my
13	MR. SCHLITTER: Objection, form.	13	modified Fig. B, which of course is not disclosed
14	THE WITNESS: No. That's precisely what	14	in Shiba.
15	I'm trying to get at with this Fig. B. I'm saying	15	Q. Then you're going to put down the pad
16	that, first of all, a person of ordinary skill in	16	and the source and the source electrode?
17	the art would not do anything toward this	17	A. Well, maybe I think it's a bit out of
18	structure in Fig. B because it complicates the	18	order. If we want to talk about the pad and the
+	formation of that capacitor.	19	source electrode, then I need to back up to make
20	BY MR. GIBSON:	20	it more clear.
21	Q. Well, I'm talking about just focusing on	21	Q. Go ahead.
22	Shiba in Fig Fig. A, which is	22	A. All right. So as we already said, the
23	A. Okay.	1	1 ,
24	Q you're saying there would be no ITO	1	gate dielectric 211 next. Now, in this structure,
25	layer on the pad?	25	the next step would be the source electrode metal
	Page 135		Page 137
1	A. So first, Shiba does not disclose any	[	and the pad 751. That would need to be
2	A. So first, Shiba does not disclose any ITO around or near or in any relationship with the	2	and the pad 751. That would need to be immediately after the protective overcoat.
2 3	A. So first, Shiba does not disclose any ITO around or near or in any relationship with the pad 751. And a person of ordinary skill	2 3	and the pad 751. That would need to be immediately after the protective overcoat. Q. Right. And that's what I thought I
2 3 4	A. So first, Shiba does not disclose any ITO around or near or in any relationship with the pad 751. And a person of ordinary skill recognizes, in my opinion, that if in the	2 3 4	<ul><li>and the pad 751. That would need to be</li><li>immediately after the protective overcoat.</li><li>Q. Right. And that's what I thought I said.</li></ul>
2 3 4 5	A. So first, Shiba does not disclose any ITO around or near or in any relationship with the pad 751. And a person of ordinary skill recognizes, in my opinion, that if in the processing of the unmodified Fig. 4 of Shiba,	2 3 4 5	<ul><li>and the pad 751. That would need to be</li><li>immediately after the protective overcoat.</li><li>Q. Right. And that's what I thought I</li><li>said.</li><li>A. I may have missed it. I apologize.</li></ul>
2 3 4 5 6	A. So first, Shiba does not disclose any ITO around or near or in any relationship with the pad 751. And a person of ordinary skill recognizes, in my opinion, that if in the processing of the unmodified Fig. 4 of Shiba, which I've reproduced in Fig. A, if the ITO was	2 3 4 5 6	<ul> <li>and the pad 751. That would need to be</li> <li>immediately after the protective overcoat.</li> <li>Q. Right. And that's what I thought I</li> <li>said.</li> <li>A. I may have missed it. I apologize.</li> <li>Q. Okay. I may have said it incorrectly,</li> </ul>
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2 3 4 5 6 7 8	A. So first, Shiba does not disclose any ITO around or near or in any relationship with the pad 751. And a person of ordinary skill recognizes, in my opinion, that if in the processing of the unmodified Fig. 4 of Shiba, which I've reproduced in Fig. A, if the ITO was simply created over there in the same step as it is in the pixel electrode, then that material	2 3 4 5 6 7 8	<ul> <li>and the pad 751. That would need to be</li> <li>immediately after the protective overcoat.</li> <li>Q. Right. And that's what I thought I</li> <li>said.</li> <li>A. I may have missed it. I apologize.</li> <li>Q. Okay. I may have said it incorrectly,</li> <li>but that's what I thought I said.</li> <li>That was my understanding was the next</li> </ul>
2 3 4 5 6 7 8 9	A. So first, Shiba does not disclose any ITO around or near or in any relationship with the pad 751. And a person of ordinary skill recognizes, in my opinion, that if in the processing of the unmodified Fig. 4 of Shiba, which I've reproduced in Fig. A, if the ITO was simply created over there in the same step as it is in the pixel electrode, then that material would be underneath the pad and would not serve	2 3 4 5 6 7 8 9	<ul> <li>and the pad 751. That would need to be</li> <li>immediately after the protective overcoat.</li> <li>Q. Right. And that's what I thought I</li> <li>said.</li> <li>A. I may have missed it. I apologize.</li> <li>Q. Okay. I may have said it incorrectly,</li> <li>but that's what I thought I said.</li> <li>That was my understanding was the next</li> <li>step in your modified Shiba would be you put the</li> </ul>
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	Page 138		Page 140
1	ordinary skill. That's a very difficult thing to	1	lines first.
	do.	2	
3		3	-
4	the are you you're saying the opening on	4	Q. And then you next put down the gate
	protective overcoat 241 that's right above the	5	dielectric which is the same as your modification,
1	gate dielectric 211?	6	correct?
7		7	A. Yes, that's unchanged in any of these.
8	referring to as being difficult and not trivial	8	Q. In both. And what's different in this
	and not obvious and quite a complication for	9	one is the pad 751 and the source electrode is now
1	manufacturing.	10	being extended over the capacitor line.
11	Q. And that's what you consider to be wrong	11	Do you see that?
12	with what Dr. Hatalis has suggested?	12	A. I do.
13	A. Dr. Hatalis has suggested that it's	13	Q. And that would still be one step,
14	trivial and obvious to make the change that I've	14	correct?
	pictured here and I disagree. It is not obvious	15	A. That would be applying the source
	first because Shiba doesn't disclose it, but in	16	electrode would still be one step.
ł	addition, it creates a complication in the	17	Q. And then the next step is to apply the
18	fabrication of that capacitor which really does	18	protective overcoat, correct?
	require precision etching.	19	A. I see that.
20	And for the other areas of that	20	Q. And then the next step is to deposit
21	protective overcoat 41, the openings in the other	21	the or next step is then to do some etching to
1	regions, there needs to be really full etching	22	create some openings, correct?
- E	into that. You can't under-etch protective	23	A. Well, after the deposition or growth of
	overcoat 241 and balancing all of that is much	24	the protective overcoat insulator 241, there would
	harder than the real disclosure that's in Shiba.	25	need to be an etching step to create openings so
	Page 139		Page 141
1	Q. And did you consider other	1	that you can contact the pad 751 and the source
2	modifications?	2	electrode.
3		3	Q. And you see that has been done in this
	A. At least one other modification that I	5	Q. And you see that has been done in this
	A. At least one other modification that I considered was the process where we take the	1	modification?
4		1	
45	considered was the process where we take the	4	modification?
45	considered was the process where we take the disclosure of Shiba and simply add an additional manufacturing step to apply the ITO after the	4 5 6	<ul><li>modification?</li><li>A. I do.</li><li>Q. And that's also a step that you include</li><li>in your modification, is that correct?</li></ul>
4 5 6 7	considered was the process where we take the disclosure of Shiba and simply add an additional manufacturing step to apply the ITO after the	4 5 6 7 8	<ul><li>modification?</li><li>A. I do.</li><li>Q. And that's also a step that you include</li><li>in your modification, is that correct?</li><li>A. Well, creating openings in the</li></ul>
4 5 6 7	considered was the process where we take the disclosure of Shiba and simply add an additional manufacturing step to apply the ITO after the protective overcoat 40 241 and the pad is	4 5 6 7 8	<ul><li>modification?</li><li>A. I do.</li><li>Q. And that's also a step that you include</li><li>in your modification, is that correct?</li></ul>
4 5 6 7 8 9	considered was the process where we take the disclosure of Shiba and simply add an additional manufacturing step to apply the ITO after the protective overcoat 40 241 and the pad is already formed.	4 5 6 7 8 9 10	<ul> <li>modification?</li> <li>A. I do.</li> <li>Q. And that's also a step that you include</li> <li>in your modification, is that correct?</li> <li>A. Well, creating openings in the</li> <li>protective overcoat is in all of these.</li> <li>Q. Yeah. And then the next step is to</li> </ul>
4 5 6 7 8 9 10	considered was the process where we take the disclosure of Shiba and simply add an additional manufacturing step to apply the ITO after the protective overcoat 40 241 and the pad is already formed. So this would be somewhere very late in	4 5 6 7 8 9 10	<ul> <li>modification?</li> <li>A. I do.</li> <li>Q. And that's also a step that you include</li> <li>in your modification, is that correct?</li> <li>A. Well, creating openings in the</li> <li>protective overcoat is in all of these.</li> </ul>
4 5 6 7 8 9 10 11	considered was the process where we take the disclosure of Shiba and simply add an additional manufacturing step to apply the ITO after the protective overcoat 40 241 and the pad is already formed. So this would be somewhere very late in the process and that's another possibility, but	4 5 6 7 8 9 10	<ul> <li>modification?</li> <li>A. I do.</li> <li>Q. And that's also a step that you include</li> <li>in your modification, is that correct?</li> <li>A. Well, creating openings in the</li> <li>protective overcoat is in all of these.</li> <li>Q. Yeah. And then the next step is to</li> </ul>
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	Page 142	T	Page 144
1	You've got an electrode in the capacitor line	1	going to be protected by the metal layer from the
	that's labeled Cj and then you've got a		etching?
3	dielectric. And then you've got what's	3	
4		1	that source electrode 231 during the etching of
5	electrode. And then on top of that you have	5	
	another insulator and then on top of that, you		change to the capacitance of that capacitor.
1	have another conductor, the pixel electrode. So	7	
	that's that whole thing forms a capacitor. One	8	capacitor.
	of ordinary skill would not look at this and say,	9	What I'm focusing on, you said in the
10		10	way Dr. Hatalis had proposed to modify Shiba,
11	the disclosure in Shiba.	11	there would be a problem in damaging the gate
12	Q. Why not?	12	dielectric and this modification solves that
13	A. It's totally redesigned, not only the	13	problem, correct?
14	processing steps and their sequence, but it's	14	A. I can't agree with that all the way
	created a totally different or new capacitor line	15	because the reason it's a problem to damage the
16	and very nonstandard, by the way.	16	5
17	Q. It's the it's the same number of		capacitance of the of this structure and the
18	steps as the original Shiba design, correct?	18	pixel.
19		19	And so the structure you're suggesting
	your description of it, it seems to be the same	20	5 5 5
	number of steps but in a different order. And		the gate dielectric, but it creates another very
	more importantly, it arrives at a structure that's	1	serious change to the design and the capacitance.
	that has a capacitor region that's very	1	So it leads to the same eventual problem.
	meaningfully different than what is disclosed in	24	
25	Shiba. And it's not trivial or obvious to one of	25	trying to get at is, there's not going to be
	Page 143		Page 145
1	ordinary skill to to get to here from Shiba.		damage to the gate dielectric in this modification
2	Q. So let me just break this down.	-	that's in Exhibit 1014?
3	You would agree that it's the same	3	A. I've already said that the source
4	number of steps, just a different order?	2	electrode is going to be above the capacitor and
5	A. I agree with that.		the gate dielectric during the etching step of the
6	Q. Would you also agree that there's not going to be damage to the gate dielectric because	:	241 layer but, again, there are other layers there that you've added and changed because of the
7	there's the metal covering is going to protect		sequence change that will lead to a serious
	it when the etching's done?		difference to the capacitor.
9 10	A. Well, the reason that changing the gate	10	-
10			U NOW LIAKE IT VOIL AGTEE THAT IT IC
11			Q. Now, I take it you agree that it is possible to reverse the order or to change the
	dielectric thickness is a problem is because the	11	possible to reverse the order or to change the
12	dielectric thickness is a problem is because the capacitance of that capacitor can be	11 12	possible to reverse the order or to change the order of the steps so that you can have the ITO
12 13	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in	11 12 13	possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?
12 13 14	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested	11 12 13 14	<ul><li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li><li>A. I agree it is possible to change the</li></ul>
12 13 14 15	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a	11 12 13 14 15	<ul><li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li><li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious</li></ul>
12 13 14 15 16	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a different reason, right. It adds another set of	11 12 13 14 15 16	<ul><li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li><li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious for a person of ordinary skill to begin with the</li></ul>
12 13 14 15 16 17	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a different reason, right. It adds another set of electrodes and an insulator on the other side.	11 12 13 14 15 16	<ul><li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li><li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious for a person of ordinary skill to begin with the disclosure in Shiba and reach to this structure.</li></ul>
12 13 14 15 16 17 18	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a different reason, right. It adds another set of electrodes and an insulator on the other side. And so it's it's very dramatically	11 12 13 14 15 16 17 18	<ul> <li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li> <li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious for a person of ordinary skill to begin with the disclosure in Shiba and reach to this structure.</li> <li>Q. Would you agree that changing the ITO</li> </ul>
12 13 14 15 16 17 18 19	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a different reason, right. It adds another set of electrodes and an insulator on the other side. And so it's it's very dramatically and possibly even more dramatically changing that	11 12 13 14 15 16 17 18 19	<ul> <li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li> <li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious for a person of ordinary skill to begin with the disclosure in Shiba and reach to this structure.</li> <li>Q. Would you agree that changing the ITO layer the order of the depositing of the ITO</li> </ul>
12 13 14 15 16 17 18 19 20	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a different reason, right. It adds another set of electrodes and an insulator on the other side. And so it's it's very dramatically and possibly even more dramatically changing that capacitance. It's a very significant design	11 12 13 14 15 16 17 18 19 20	<ul> <li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li> <li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious for a person of ordinary skill to begin with the disclosure in Shiba and reach to this structure.</li> <li>Q. Would you agree that changing the ITO</li> </ul>
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12 13 14 15 16 17 18 19 20 21 22	dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a different reason, right. It adds another set of electrodes and an insulator on the other side. And so it's it's very dramatically and possibly even more dramatically changing that capacitance. It's a very significant design	11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li> <li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious for a person of ordinary skill to begin with the disclosure in Shiba and reach to this structure.</li> <li>Q. Would you agree that changing the ITO layer the order of the depositing of the ITO layer allows you to get the ITO layer also on pad</li> </ul>
12 13 14 15 16 17 18 19 20 21 22	<ul> <li>dielectric thickness is a problem is because the capacitance of that capacitor can be uncontrollable or different than it would be in the disclosure of Shiba. And this suggested structure also changes capacitance but for a different reason, right. It adds another set of electrodes and an insulator on the other side. And so it's it's very dramatically and possibly even more dramatically changing that capacitance. It's a very significant design change.</li> <li>Q. Okay. Let's just start with my</li> </ul>	11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>possible to reverse the order or to change the order of the steps so that you can have the ITO layer above the protective overcoat?</li> <li>A. I agree it is possible to change the order, but I don't think it is trivial or obvious for a person of ordinary skill to begin with the disclosure in Shiba and reach to this structure.</li> <li>Q. Would you agree that changing the ITO layer the order of the depositing of the ITO layer allows you to get the ITO layer also on pad 751?</li> <li>A. Well, you're offering a hypothetical</li> </ul>

	Page 146	ľ	Page 148
1	ordinary skill would consider based on the	1	BY MR. GIBSON:
	disclosure of Shiba.	2	Q. Okay. And in Exhibit 1014, you agree
3	Q. All right. In the modification that you	3	there's no increase in the manufacturing steps?
4	suggested, you could also have put the if you	4	A. 1013?
5	look at Exhibit 1013, you could put the ITO layer	5	Q. 1014. 1013 is yours. 1014 is the
	on pad 751, correct?	6	modified one that I've handed you.
7	A. It would in that case I didn't draw	7	A. I agree that there's no increase in the
8	it because I was focused on the capacitor portion,	8	number of manufacturing steps, but it does lead to
9	but if it were applied, the only place it could be	9	a capacitor that's going to behave very
10	would be above pad 751 but below the dielectric	10	
11	insulator called the protective overcoat 241.		what's disclosed in Shiba.
12	Q. In your modification, it would be below?	12	Q. And do you know how it would behave
13	A. I'm sorry. Yeah, I stand corrected.		differently, the capacitor?
14	I'm sorry.	14	A. Well, this structure would would
15	In my modification, it would also be	15	
- E	above, similar to your drawing. Yes. So let me	16	* · · · ·
1	correct myself.	17	0
18	Q. And in your modification, wouldn't it be	18	
	more appropriate to show the ITO layer on pad 751?	19	change and the consequence of that would be that
	I know that's not what you were focused on, but	20	81
	shouldn't you show it there?	21	1 1 0
22	A. I didn't need to show it. That's not	22	being given its data signal, all of that changes
	the part I was talking about.		very dramatically.
24	Q. But isn't it going to be sitting on pad	24	Q. And how do you know that? Is it just
25	751?	25	based on there being two capacitors now as you
1	Page 147	1	Page 149 said?
	A. I still don't think one of ordinary skill, based on the disclosure in Shiba, would be	2	A. Specifically how do I know what?
$\begin{vmatrix} 2\\ 3 \end{vmatrix}$	inclined to put ITO on the pad.		
4	monned to put 110 on the pad.		O What you just said
	O But you agree that it's possible to do	3	Q. What you just said. A Well basic electronics and basic
	Q. But you agree that it's possible to do it?	4	A. Well, basic electronics and basic
5	it?	4 5	A. Well, basic electronics and basic electrical engineering supports the first part of
5 6	it? A. I agree that your hypothetical makes it	4 5 6	A. Well, basic electronics and basic electrical engineering supports the first part of what I said, that these are essentially capacitors
5 6 7	it? A. I agree that your hypothetical makes it possible. I think your hypothetical is just not	4 5 6	A. Well, basic electronics and basic electrical engineering supports the first part of what I said, that these are essentially capacitors in series.
5 6 7 8	it? A. I agree that your hypothetical makes it possible. I think your hypothetical is just not reasonable. It's not obvious, it's not trivial to	4 5 6 7 8	A. Well, basic electronics and basic electrical engineering supports the first part of what I said, that these are essentially capacitors in series. Beyond that, I know from my experience
5 6 7 8 9	it? A. I agree that your hypothetical makes it possible. I think your hypothetical is just not reasonable. It's not obvious, it's not trivial to a person of ordinary skill.	4 5 7 8 9	A. Well, basic electronics and basic electrical engineering supports the first part of what I said, that these are essentially capacitors in series.
5 6 7 8 9 10	<ul> <li>it?</li> <li>A. I agree that your hypothetical makes it possible. I think your hypothetical is just not reasonable. It's not obvious, it's not trivial to a person of ordinary skill.</li> <li>Q. And in your modified Fig. 4, it would</li> </ul>	4 5 7 8 9 10	A. Well, basic electronics and basic electrical engineering supports the first part of what I said, that these are essentially capacitors in series. Beyond that, I know from my experience in LCDs that this capacitor has quite a lot to do
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5 6 7 8 9 10 11 12 13 14	<ul> <li>it?</li> <li>A. I agree that your hypothetical makes it possible. I think your hypothetical is just not reasonable. It's not obvious, it's not trivial to a person of ordinary skill.</li> <li>Q. And in your modified Fig. 4, it would also be possible to put the ITO layer on the pad, correct?</li> <li>A. It would be possible. I did not draw</li> </ul>	4 5 7 8 9 10 11 12 13 14	A. Well, basic electronics and basic electrical engineering supports the first part of what I said, that these are essentially capacitors in series. Beyond that, I know from my experience in LCDs that this capacitor has quite a lot to do with the time the behavior and time of the LCD pixel, not only as it's being charged, but also its ability to hold that charge while the other rows in the display are being addressed.
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5 6 7 8 9 10 11 12 13 14 15 16 17	<ul> <li>it?</li> <li>A. I agree that your hypothetical makes it possible. I think your hypothetical is just not reasonable. It's not obvious, it's not trivial to a person of ordinary skill.</li> <li>Q. And in your modified Fig. 4, it would also be possible to put the ITO layer on the pad, correct?</li> <li>A. It would be possible. I did not draw it, but I also don't think my modified Fig. 4 is is an option that one of ordinary skill would take based on the disclosure in Shiba.</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18	<ul> <li>A. Well, basic electronics and basic</li> <li>electrical engineering supports the first part of</li> <li>what I said, that these are essentially capacitors</li> <li>in series.</li> <li>Beyond that, I know from my experience</li> <li>in LCDs that this capacitor has quite a lot to do</li> <li>with the time the behavior and time of the LCD</li> <li>pixel, not only as it's being charged, but also</li> <li>its ability to hold that charge while the other</li> <li>rows in the display are being addressed.</li> <li>Q. And why do you say that the creating</li> <li>the source electrode over the gate dielectric that</li> <li>is over the capacitor line creates a second</li> <li>capacitor?</li> <li>A. Because a single capacitor has two</li> </ul>
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5 6 7 8 9 10 11 12 13 14 15 16 17 18	<ul> <li>it?</li> <li>A. I agree that your hypothetical makes it possible. I think your hypothetical is just not reasonable. It's not obvious, it's not trivial to a person of ordinary skill.</li> <li>Q. And in your modified Fig. 4, it would also be possible to put the ITO layer on the pad, correct?</li> <li>A. It would be possible. I did not draw it, but I also don't think my modified Fig. 4 is is an option that one of ordinary skill would take based on the disclosure in Shiba.</li> <li>Q. But you could do it without adding manufacturing steps?</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	<ul> <li>A. Well, basic electronics and basic</li> <li>electrical engineering supports the first part of</li> <li>what I said, that these are essentially capacitors</li> <li>in series.</li> <li>Beyond that, I know from my experience</li> <li>in LCDs that this capacitor has quite a lot to do</li> <li>with the time the behavior and time of the LCD</li> <li>pixel, not only as it's being charged, but also</li> <li>its ability to hold that charge while the other</li> <li>rows in the display are being addressed.</li> <li>Q. And why do you say that the creating</li> <li>the source electrode over the gate dielectric that</li> <li>is over the capacitor line creates a second</li> <li>capacitor?</li> <li>A. Because a single capacitor has two</li> <li>conductors and an insulator separating them and in</li> <li>this case, there's three conductors with two</li> </ul>
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5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>it?</li> <li>A. I agree that your hypothetical makes it possible. I think your hypothetical is just not reasonable. It's not obvious, it's not trivial to a person of ordinary skill.</li> <li>Q. And in your modified Fig. 4, it would also be possible to put the ITO layer on the pad, correct?</li> <li>A. It would be possible. I did not draw it, but I also don't think my modified Fig. 4 is is an option that one of ordinary skill would take based on the disclosure in Shiba.</li> <li>Q. But you could do it without adding manufacturing steps?</li> <li>MR. SCHLITTER: Objection, form. THE WITNESS: In my modification, there may not be additional manufacturing steps per se, but there's an increased sensitivity that will</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>A. Well, basic electronics and basic</li> <li>electrical engineering supports the first part of what I said, that these are essentially capacitors in series.</li> <li>Beyond that, I know from my experience in LCDs that this capacitor has quite a lot to do with the time the behavior and time of the LCD pixel, not only as it's being charged, but also its ability to hold that charge while the other rows in the display are being addressed.</li> <li>Q. And why do you say that the creating the source electrode over the gate dielectric that is over the capacitor line creates a second capacitor?</li> <li>A. Because a single capacitor has two conductors and an insulator separating them and in this case, there's three conductors with two insulating films separating them. So the stack of this double capacitor</li> </ul>

1	Page 150	Τ	Page 152
1	go through the second insulator 241 and then	1	-
	finally arrive at the pixel electrode 251 as the	2	
1	last electrode.	3	there's one use of contact through the transparent
4			conductor and then two uses of contact through an
5		1	opening.
6		6	
7		7	sure you've seen many times.
8		8	A. Yes, I have.
9	exotic double capacitor design in Shiba.	9	Q. If you want to look at it in the
10	Q. Why are you saying that the pixel	10	declaration or you can look at it in the patent.
11	electrode forms a third capacitor in the modified	11	A. No, I have this claim chart in the
12	figure in Exhibit 1014?	12	declaration that's helpful in identifying the
13	A. I'm recognizing that it's true from your	13	elements of the claim, so I'm preparing for a
14	illustration.	14	discussion on that.
15	Q. Why?	15	
16	0	6	seeing sort of half of the opening where the ITO
17	that are in a stack with two insulating films in		is connecting in the in between the resin
18	between.	18	interlayer film?
19		19	<u> </u>
20		20	
21	Q. In terms of the word "through" that's	21	A. I'm not sure that's I'm not sure I
	used in both the '413 and the '204 patents, is	}	know what you mean by "half the opening."
23		23	Q. Well, if you were to draw to the right
24	•		of what's occurring, which we don't see in
25	THE WITNESS: In the '413 patent, the	25	Fig. 4A, you would have more ITO layer than the
	Page 151		Page 153
	word "through" is used in a phrase that involves		ITO would go above the insulating layer film, the
	contact through an opening and I think it's that		resin?
1	phrase that should be examined more than just the	3	A. I think the '413 patent is silent on
	word "through."		what's to the right.
•	BY MR. GIBSON:	5	Q. And you as you don't think a person
6	Q. And you disagree with the Board's		
1 7			of ordinary skill in the art would understand that
1	interpretation of that word, I take it?	7	to the right there's going to be a place where the
8	interpretation of that word, I take it? A. I disagree with the second definition	7 8	to the right there's going to be a place where the ITO stops and the insulating layer begins again?
8 9	<ul><li>interpretation of that word, I take it?</li><li>A. I disagree with the second definition</li><li>that the Board has offered in the decision. I</li></ul>	7 8 9	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the
8 9 10	<ul><li>interpretation of that word, I take it?</li><li>A. I disagree with the second definition</li><li>that the Board has offered in the decision. I</li><li>agree wholeheartedly with the first definition.</li></ul>	7 8 9 10	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed
8 9 10 11	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> </ul>	7 8 9 10 11	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the
8 9 10 11 12	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> </ul>	7 8 9 10 11 12	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of
8 9 10 11 12 13	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> <li>Q there are a number of different</li> </ul>	7 8 9 10 11 12 13	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of the very same pattern without the return of the
8 9 10 11 12 13 14	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition that the Board has offered in the decision. I agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> <li>Q there are a number of different instances of the word "through," correct, in that</li> </ul>	7 8 9 10 11 12 13 14	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of the very same pattern without the return of the element 113.
8 9 10 11 12 13 14 15	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> <li>Q there are a number of different</li> <li>instances of the word "through," correct, in that</li> <li>claim?</li> </ul>	7 8 9 10 11 12 13 14 15	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of the very same pattern without the return of the element 113. Q. Well, where is the where is the
8 9 10 11 12 13 14 15 16	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> <li>Q there are a number of different</li> <li>instances of the word "through," correct, in that</li> <li>claim?</li> <li>A. There are at least three uses of the</li> </ul>	7 8 9 10 11 12 13 14 15 16	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of the very same pattern without the return of the element 113. Q. Well, where is the where is the opening where the ITO in Fig. 4A, where is the
8 9 10 11 12 13 14 15 16 17	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> <li>Q there are a number of different</li> <li>instances of the word "through," correct, in that</li> <li>claim?</li> <li>A. There are at least three uses of the</li> <li>phrase "contact through an opening." I think it's</li> </ul>	7 8 9 10 11 12 13 14 15 16 17	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of the very same pattern without the return of the element 113. Q. Well, where is the where is the opening where the ITO in Fig. 4A, where is the opening that connects 4A or that in 4A connects
8 9 10 11 12 13 14 15 16 17 18	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> <li>Q there are a number of different</li> <li>instances of the word "through," correct, in that</li> <li>claim?</li> <li>A. There are at least three uses of the</li> <li>phrase "contact through an opening." I think it's</li> <li>in the last three elements of the Claim 1.</li> </ul>	7 8 9 10 11 12 13 14 15 16 17 18	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of the very same pattern without the return of the element 113. Q. Well, where is the where is the opening where the ITO in Fig. 4A, where is the opening that connects 4A or that in 4A connects 114 to the external connection lines 403?
8 9 10 11 12 13 14 15 16 17 18 19	<ul> <li>interpretation of that word, I take it?</li> <li>A. I disagree with the second definition</li> <li>that the Board has offered in the decision. I</li> <li>agree wholeheartedly with the first definition.</li> <li>Q. If we look at Claim 1 of the '413</li> <li>A. I've got it.</li> <li>Q there are a number of different</li> <li>instances of the word "through," correct, in that</li> <li>claim?</li> <li>A. There are at least three uses of the</li> <li>phrase "contact through an opening." I think it's</li> <li>in the last three elements of the Claim 1.</li> <li>Q. Well, it's not always contact through an</li> </ul>	7 8 9 10 11 12 13 14 15 16 17 18 19	to the right there's going to be a place where the ITO stops and the insulating layer begins again? A. Not necessarily. It's one of the options certainly, but it's not not disclosed and it's not required either. The rest of the region to the right could simply a continuation of the very same pattern without the return of the element 113. Q. Well, where is the where is the opening where the ITO in Fig. 4A, where is the opening that connects 4A or that in 4A connects 114 to the external connection lines 403? A. The opening is where the element 113 is
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39 (Pages 150 - 153)

<b></b>			Page 156
1	Page 154 applied similar to one of the insulators that	1	Fig. 4A shows.
1	we've already talked about today and it's	2	Q. Does the '413 patent disclose any
	deposited on the whole the whole substrate and	1	problems with the failure of the bonding of the
	then needs to be patterned and opened so that		sealant to the substrate?
[	there would be ability to contact through that	5	A. I believe it does. You might be able to
	opening to the conductive layers below.	í	direct me there to save us time.
7		7	Q. All right. I'm not aware of it doing
	after after this figure ends on the right, you		that.
	don't know what's happening? There's many	9	A. Well, let me let me look. Okay.
	possibilities?		Thank you for the moment to refresh my memory.
11	A. There are many possibilities and I think		It's clear from the specification that a resin
	the two we identified is where this cross-section		inter-layer film is always disclosed as being
	on the right side in the first region continues to		above the wiring below the sealant in the
	the right.	l I	specification and that's required in Claim 1, but
15	And the other possibility, as you've		there's no there doesn't seem to be any
	suggested, is that at some point to the right,		explicit discussion as to why that's important in
	there's a return or the other side of the opening		the spec.
	with where there's a return of the second	18	Q. And there's no discussion saying that
} .	insulator 113. Both are possible.	19	that was a problem in the prior art, that somehow
20	Q. All right. And you would find as one		there's a problem with the sealant in the prior
1	of ordinary skill in the art, you would think that		art and it's not bonding with the substrate
	one of ordinary skill in the art would find that		because of some other structure?
	both are possible?	23	A. Well, there does not seem to be an
24	A. A person of ordinary skill would find	24	explicit disclosure of those kind of problems, but
	both possible and both would be consistent with		Column 3 around lines 23 to 26 say or disclose
	Page 155		Page 157
1	Page 155 the claim language of contact through an opening.	1	Page 157 the ordering of placing an inter-layer film made
	the claim language of contact through an opening.		the ordering of placing an inter-layer film made
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2 3	<ul><li>the claim language of contact through an opening.</li><li>Q. In the example that I gave where you essentially have the mirror image of 4A to the</li></ul>	2 3	<ul><li>the ordering of placing an inter-layer film made</li><li>of a resin material on the wiring.</li><li>Q. Those are focused on height</li></ul>
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	Page 158		Page 160
1		1	often in projectors.
2	mean, that's been known for a long time, before	2	Q. So you would agree though that in terms
	1997 that it was a problem to try to bond to an	3	of bonding, it would be advantageous to have the
4	ITO layer, right?	4	ITO layer not be the layer directly below the
5	A. I think it is a principle that a person	5	sealant to one of ordinary skill in the art in
6	of ordinary skill would have known by 1997, that	6	1997?
7	that was a situation to try to avoid.	7	A. I think one of ordinary skill would see
8	Q. All right. So you would agree then that		that as would have known that that would make a
9		9	better seal and depending on the other
10	would know that you would not want to have the ITO		constraints, that may be the choice that they
11	layer as your uppermost layer that would interact	11	would take advantage of.
12	with a sealant?	12	Q. When you say "the choice," what do you
13	A. I wouldn't characterize it that way.	13	mean by "the choice"?
14		14	A. It's a design choice that's made, right,
1	would would know that the adhesion between a	1	the sequence of layers, the presence of ITO there
1	sealant and an ITO layer would be less strong and		or not or whether there's an opening there or not
	have a shorter lifetime than one formed with a	1	or the insulator or not on both substrates as
18	resin inter-layer film or an insulator. But	1	well. All those are things that have to be
19	still, a person of ordinary skill might still		chosen.
20	choose to make that bond anyway, perhaps because	20	Q. Right. Well, I'm just the way you
21	· -	1	answered the question, I want to make sure we're
22	Q. But you would agree that they would also		on the same page.
23	know that there would be issues with the bonding	23	You agree that one of ordinary skill in
	if they had the ITO layer on top, so if you all		the art in 1997 would understand in terms of
25	things being equal, you would rather not have the	25	bonding, you would rather be bonding to an
	Page 159		Page 161
			_
	ITO layer on top touching the sealants or bonding		insulating layer rather than the ITO layer?
2	ITO layer on top touching the sealants or bonding with the sealant?	2	insulating layer rather than the ITO layer? A. If nothing else mattered, then bonding
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41 (Pages 158 - 161)

	Page 162		Page 164
	side of the sealant, it's touching whatever is	1	just want to know if you have a view if there is
	below that.	1	an additional problem. I'm not asking for
3		1	speculation.
	looking at it, what that layer is. I thought it	4	A. I can't think of an additional problem
1 -	was ITO, but now upon inspecting it, it may		with having ITO underneath the insulating layer 9.
6	5	6	MR. GIBSON: Why don't we go ahead and
7		7	
8		8	MR. SCHLITTER: Should we take a break
9			then?
	does.	10	VIDEOGRAPHER: We're going off record.
11		11	
	Exhibit I think it's 2010. That's the Sukegawa		is the 3:05.
	Fig. 2C that was drawn on by Professor Hatalis.	13	(Short recess.)
	Yes, that's it.	14	VIDEOGRAPHER: We're back on record.
15	0	1	This is the beginning of Media Unit Number 4 in
16		1	the deposition of Dr. Michael Escuti. The time is
17	6	1	3:21. Please continue.
1	drew it, that it is not touching the ITO layer?		BY MR. GIBSON:
19	A. Well, of course I disagree with the	19	Q. If you'd turn to your declaration,
	placement of the sealant there, but despite that,	1	page 23.
	it's not illustrated by Dr. Hatalis as touching	21	A. I've got it.
	the ITO.	22	Q. And you've put a copy of Fig. 4A into
23	Q. It's not?		that and then you've drawn a dotted line and
24	A. It is not.	1	designated a first and a second region?
25	Q. Is there any problem with the ITO layer	25	A. That's what's shown. In fact, this is a
	Page 163		Page 165
1	running under the insulating film that's touching	1	figure that I think I'd like to adopt another
2	the sealant?		figure in place of from the decision on page 13,
3	A. I'm not sure what you mean by is there a		because my modification here identifying the
4	problem.	1	regions is imprecise and not helpful in its
5	Q. Do you have any issue with the ITO layer	1	imprecision.
	running under the insulating running under an	6	Q. Why do you say it's imprecise?
1	insulating film that's touching a sealant? Do you	7	
8			A. Well, the reason I created this modified
0	think that would cause any issues?	8	figure was to emphasize how the these regions
9	A. Well, if we listen to the disclosure in	8 9	figure was to emphasize how the these regions are spoken of in the claim as having items that
9 10	A. Well, if we listen to the disclosure in Sukegawa, the ITO is present there as one of the	8 9 10	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of
9 10 11	A. Well, if we listen to the disclosure in Sukegawa, the ITO is present there as one of the double protection layers against corrosion. The	8 9 10 11	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating
9 10 11 12	A. Well, if we listen to the disclosure in Sukegawa, the ITO is present there as one of the double protection layers against corrosion. The insulating film above it is the second one. I	8 9 10 11 12	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating it, but I didn't precisely draw those arrows to
9 10 11 12 13	A. Well, if we listen to the disclosure in Sukegawa, the ITO is present there as one of the double protection layers against corrosion. The insulating film above it is the second one. I don't disagree with Sukegawa on that.	8 9 10 11 12 13	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating it, but I didn't precisely draw those arrows to indicate what I think is the first and second
9 10 11 12 13 14	<ul> <li>A. Well, if we listen to the disclosure in</li> <li>Sukegawa, the ITO is present there as one of the</li> <li>double protection layers against corrosion. The</li> <li>insulating film above it is the second one. I</li> <li>don't disagree with Sukegawa on that.</li> <li>Q. So I'm not sure, is there is there a</li> </ul>	8 9 10 11 12 13 14	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating it, but I didn't precisely draw those arrows to indicate what I think is the first and second region precisely. So it's misleading. So
9 10 11 12 13 14 15	<ul> <li>A. Well, if we listen to the disclosure in</li> <li>Sukegawa, the ITO is present there as one of the</li> <li>double protection layers against corrosion. The</li> <li>insulating film above it is the second one. I</li> <li>don't disagree with Sukegawa on that.</li> <li>Q. So I'm not sure, is there is there a</li> <li>problem or not with having the ITO layer run</li> </ul>	8 9 10 11 12 13 14 15	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating it, but I didn't precisely draw those arrows to indicate what I think is the first and second region precisely. So it's misleading. So instead, it's the decision page 13 has the figure
9 10 11 12 13 14 15 16	<ul> <li>A. Well, if we listen to the disclosure in Sukegawa, the ITO is present there as one of the double protection layers against corrosion. The insulating film above it is the second one. I don't disagree with Sukegawa on that.</li> <li>Q. So I'm not sure, is there is there a problem or not with having the ITO layer run underneath the insulating layer that's bonding to</li> </ul>	8 9 10 11 12 13 14 15 16	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating it, but I didn't precisely draw those arrows to indicate what I think is the first and second region precisely. So it's misleading. So instead, it's the decision page 13 has the figure that I would like to adopt fully in place of this
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9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>A. Well, if we listen to the disclosure in Sukegawa, the ITO is present there as one of the double protection layers against corrosion. The insulating film above it is the second one. I don't disagree with Sukegawa on that.</li> <li>Q. So I'm not sure, is there is there a problem or not with having the ITO layer run underneath the insulating layer that's bonding to the sealant?</li> <li>A. In this discussion, the primary problem is that it's not disclosed in Sukegawa. That's expressly what's not disclosed. The sealant is not shown here. Wherever the sealant is, it's not here in Sukegawa. If you want me to speculate about additional problems that could happen Q. I don't want you to speculate. I just</li> </ul>	8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating it, but I didn't precisely draw those arrows to indicate what I think is the first and second region precisely. So it's misleading. So instead, it's the decision page 13 has the figure that I would like to adopt fully in place of this figure. Q. So when you look at Claim 1 of the '413 A. Got it. Q in terms of the prior art, you would agree we're talking about liquid crystal display devices? No dispute there? A. No dispute there.
9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>A. Well, if we listen to the disclosure in Sukegawa, the ITO is present there as one of the double protection layers against corrosion. The insulating film above it is the second one. I don't disagree with Sukegawa on that.</li> <li>Q. So I'm not sure, is there is there a problem or not with having the ITO layer run underneath the insulating layer that's bonding to the sealant?</li> <li>A. In this discussion, the primary problem is that it's not disclosed in Sukegawa. That's expressly what's not disclosed. The sealant is not shown here. Wherever the sealant is, it's not here in Sukegawa. If you want me to speculate about additional problems that could happen</li> </ul>	8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	figure was to emphasize how the these regions are spoken of in the claim as having items that are above or I should say over the regions of the second wiring. And that's why I was creating it, but I didn't precisely draw those arrows to indicate what I think is the first and second region precisely. So it's misleading. So instead, it's the decision page 13 has the figure that I would like to adopt fully in place of this figure. Q. So when you look at Claim 1 of the '413 A. Got it. Q in terms of the prior art, you would agree we're talking about liquid crystal display devices? No dispute there?

42 (Pages 162 - 165)

	Page 166	1	Page 168
1	substrate?	1	it's present. Sukegawa does not disclose the
2	A. Prior art does have a first wiring over	2	location or position of the sealant at all, but I
3	a substrate.	3	do think one of ordinary skill would identify it
4	Q. Prior art also has a first insulating	4	as between the two substrates.
5	film over the first wiring?	5	Q. And because Sukegawa says there's an
6	A. In some cases, yes.	6	insulating film as the outermost layer on the
7	Q. Like Sukegawa has that, for example?	7	substrate, you would expect the sealant to be in
8	A. For example, Sukegawa.	8	contact with that outermost layer?
9	Q. And there's also a second wiring over	9	1
10	the substrate and the first insulating film,		illustrated in Fig. 3 or the series of Figs. 3, I
11	Sukegawa has that?		think that's consistent with that's one example
12	A. Sukegawa also has the second wiring over		where that's the case, where the sealant is in
13	the substrate and the first insulating film.	13	contact with that upper insulating film.
14	Q. And it also has a second insulating	14	
15	film?		wiring overlaps at least part of the first wiring
16	A. Sukegawa does have a second insulating	1	in Sukegawa?
	film over the second wiring, but I should note	17	A. Do I agree
1	that it's it's not over the second wiring in	18	Q. That the first and second wiring overlap
1	combination with the other limitations of the rest	1	at least in part?
20	of this Claim 1.	20	A. I do agree that the first and second
21	Q. I'm just going down the down the		wirings in Sukegawa overlap at least in part.
	order. It does have a second insulating film over	22	Q. And if you look at Sukegawa, Fig. 2C,
1	the second wiring?	1	the first wiring would be element 2?
24	A. To this point, yes, but to the extent	24	A. The first wiring, Sukegawa doesn't call
25	that any of the other limitations affect what	25	it simply that. He's got other names, but that
	D 1(7		
	Page 167		Page 169
1	qualifies as that second insulating film, I can't		might be a first wiring if we were to try to apply
2	qualifies as that second insulating film, I can't agree.	2	might be a first wiring if we were to try to apply the language from Claim 1 in the '413 patent.
2 3	qualifies as that second insulating film, I can't agree. But at least to this point, yes, it has	2 3	might be a first wiring if we were to try to apply the language from Claim 1 in the '413 patent. Q. You think a person of ordinary skill in
2 3 4	qualifies as that second insulating film, I can't agree. But at least to this point, yes, it has another insulating film, which until this point we	2 3 4	<ul><li>might be a first wiring if we were to try to apply</li><li>the language from Claim 1 in the '413 patent.</li><li>Q. You think a person of ordinary skill in</li><li>the art would understand that, to be equivalent to</li></ul>
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2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>qualifies as that second insulating film, I can't agree.</li> <li>But at least to this point, yes, it has another insulating film, which until this point we can identify as being over the second wiring.</li> <li>Q. And a transparent conductive layer, you understand that to be an ITO?</li> <li>A. I would not take that to be equivalent to ITO. ITO is an example of a transparent conductor. It's a very common choice for that, but it's not exclusively the choice that must be made.</li> <li>Q. Fair enough. The transparent conductive layer, you have that in Sukegawa over a first region of the second wiring?</li> <li>A. Well, there is a transparent conductor over a second wiring in Sukegawa, but I don't agree that it is in a first region in the way the rest of the claim talks about.</li> <li>Q. Would you agree that there is somewhere in Sukegawa you're going to have sealant that is in direct contact with the second</li> </ul>	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>might be a first wiring if we were to try to apply the language from Claim 1 in the '413 patent.</li> <li>Q. You think a person of ordinary skill in the art would understand that, to be equivalent to a first wiring?</li> <li>A. For the first wiring, I think so.</li> <li>Q. And then element 3, would you understand that to be an insulating layer?</li> <li>A. Element 3 is called an inter-layer insulating film in Sukegawa, and so clearly it's an insulator, and it is the first one that appears over the first wiring.</li> <li>Q. And you would consider those the second wiring and first wiring to be in contact through the opening in insulating film 3?</li> <li>A. In Sukegawa, the upper metal layer wiring 7 is in contact with the first or lower metal layer wiring 2 through the openings in the insulating layer 3.</li> <li>Q. And those are vertical openings as depicted there?</li> <li>A. They're depicted as vertical openings,</li> </ul>

43 (Pages 166 - 169)

	Page 170		Page 172
1	standard practice for one of ordinary skill in the		in the art looking at Sukegawa would understand
	art to avoid sealing LCDs in a way that the	1	there would be sealant present?
	sealant was in contact with a conductor such as an	3	2
1	ITO in the terminal region and instead have the	4	
	sealant be in contact with another material	1	sealant is ordinarily near the edge of the counter
6	MR. SCHLITTER: Objection, form.	1	substrate but with some offset from the counter
7			substrate edge?
8	Q such as an insulating resin?	8	-
9	A. Well, we discussed that before the	9	· · · · · · · · · · · · · · · · · · ·
-	break, right. It's a principle that would have	10	of "some offset" and the term "near" it's not
1	been known to a person of ordinary skill that the	1	defined in this conversation, but to the extent
	adhesion in the two cases would be different. One		that there's normal meaning applied to those, then
	is preferable, but not required.	1	that's where sealant is placed in general, offset
14	Q. Would you agree that it would be		from the edge of the counter substrate as we
[	standard practice to avoid sealing LCDs in a way		looked at in Nakamoto as one example.
	that the sealant was in contact with the ITO		BY MR. GIBSON:
	layer?	17	
18	A. I don't think I can characterize a		would one of ordinary skill in the art put the
	standard practice. I think both were options to a		sealant?
	person of ordinary skill.	20	A. Well, Sukegawa, wherever it is, it's not
21	Q. And if you'd look at your declaration on	1	in any of these terminal figures, including 2C.
	page 25, if you look at the third line, the		The only place it might be found would be in
	sentence that begins, "It is therefore standard		Fig. 3D because Fig. 3D includes the counter
	practice for one of ordinary skill in the art to	1	substrate as element 200.
	avoid sealing LCDs in such a way that the sealant	25	So wherever Sukegawa would put it or
		20	
1	Page 171 is in contrast with a conductor ( $\alpha \propto 1TO$ ) in the	1	
	is in contact with a conductor (e.g., ITO) in the	4	that a person of ordinary skill would understand
2	is in contact with a conductor (e.g., ITO) in the terminal region with another material (e.g.,	2	that a person of ordinary skill would understand it should be would be to the left side of Fig. 3D
2 3	is in contact with a conductor (e.g., ITO) in the terminal region with another material (e.g., insulating resin) elsewhere."	2 3	that a person of ordinary skill would understand it should be would be to the left side of Fig. 3D between the two substrates.
2 3 4	is in contact with a conductor (e.g., ITO) in the terminal region with another material (e.g., insulating resin) elsewhere." Do you see that?	2 3 4	<ul><li>that a person of ordinary skill would understand</li><li>it should be would be to the left side of Fig. 3D</li><li>between the two substrates.</li><li>Q. And there would be would you agree</li></ul>
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2 3 4 5 6	<ul> <li>is in contact with a conductor (e.g., ITO) in the terminal region with another material (e.g., insulating resin) elsewhere."</li> <li>Do you see that?</li> <li>A. I do. That's what it says.</li> <li>Q. Do you stand by those words?</li> </ul>	2 3 4 5 6	<ul><li>that a person of ordinary skill would understand</li><li>it should be would be to the left side of Fig. 3D</li><li>between the two substrates.</li><li>Q. And there would be would you agree</li><li>that there would be sealant between 100 and 200 in</li><li>Fig. 3D?</li></ul>
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44 (Pages 170 - 173)

	D 174	Τ	D 176
1	Page 174 were to put the sealant in a counter substrate	1	Page 176 Q. Right. But in interpreting the claims,
	where Professor Hatalis did in 2C, correct?		you wouldn't limit the sealant to the example in
3		3	· · · · · · · · · · · · · · · · · · ·
4		4	
		5	
	more important, but that's an additional one.	6	
7	· · · · · · · · · · · · · · · · · · ·	-	BY MR. GIBSON:
	have to have spacers in it?	8	
9	A. I would agree that some sealants don't		take it from your testimony earlier today, you've
	have spacers in them.		never seen that patent before?
11	Q. And the '413 patent doesn't limit itself	11	
	to sealant with spacers in it, it's not a	12	
	restriction of the claims?	1	the '413 patent or the '204 patent, you didn't go
14	A. It's not a restriction of the claims,	1	and look at other prior art that was that was
	but I certainly not of Claim 1.	1	around 1997 or earlier to determine the overall
16	Q. And you're not trying to read in that	1	state of the art?
	restriction into your interpretation of Claim 1,	17	
	correct?	1	informally, but whatever I found didn't amount to
19	A. I'm not trying to read that as a		much that was used to form my opinions.
	requirement to Claim 1. It is a practice that a	20	Q. And you don't recall any of that art?
	person of ordinary skill would commonly do,	21	A. I don't.
	especially in 1997, but it's it's not required.	22	Q. Did you keep it anywhere?
23	Q. All right. And it would be reasonable	23	A. No.
	not to do it, right, not to use sealant with	24	Q. What kind of searching did you do?
	spacers, correct?	25	A. Google patent kind of searching.
	Page 175		Page 177
1	A. It would depend.	1	Q. What did you do specifically in terms of
2	Q. It would depend on what they were trying	2	Google patent searching?
3	to achieve, but in certain situations, it would be	3	A. I don't recall specifically, but
4	reasonable to have sealant that didn't have		
~	reasonable to have sealant that utun t have	4	searching keywords that would be relevant to the
5			searching keywords that would be relevant to the case and see what came up and then search the
5 6	spacers, correct?	5	searching keywords that would be relevant to the case and see what came up and then search the results to see if there's anything that's relevant
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45 (Pages 174 - 177)

	Dece 179		Page 180
1	Page 178 A. By the time I submitted my declaration?	1	testimony about what Fig. 9 is?
2	Q. Yes.	2	A. I certainly would.
3	A. I think that's the number I gave you,	3	Q. And those three patents that I just
4	100 and more than 130. I haven't looked since	l I	showed you, those were not in any way considered
	then.		by you in formulating your opinion either for the
6	Q. If you could look at the '102 patent and	F	'413 matter or the '204 matter?
-	look at just Figs. 5A, 5B, 5C, 5D.	7	A. I've never seen them before, so they had
8	A. I'll do my best but, of course I've		no part in my opinion.
	never seen this, so I'm not sure what I can say	9	Q. If we could turn back to Sukegawa.
	about a reference I've never seen.	10	A. I've got it.
11	Q. And you may not be able to and that's	11	Q. And look at Fig. 2C.
	that's fine.	12	A. I've got it.
13	I'm just going to ask you, do you	13	Q. And if you 9 is the is the resin
1	recognize the steps that are taking place in 5A		insulating layer in 2C?
1	through 5G?	15	MR. SCHLITTER: Objection, form.
16	MR. SCHLITTER: Objection, foundation.		BY MR. GIBSON:
17	THE WITNESS: 5A through	17	Q. Or second insulating film?
1	BY MR. GIBSON:	18	A. Is that a question?
19	Q. 5G.	19	Q. Yeah.
20	A. I'd have to read the specification to	20	A. 9 is called the protective insulating
21	know what's going on here.	21	film and it would be an insulator.
22	Q. Okay.	22	Q. And that also there's another part of
23	MR. GIBSON: Mark this as 1016.	23	9 over on the right-hand side?
24	(Document marked as Exhibit Number 1016	24	A. In Fig. 2C, prior art to Sukegawa, there
25	for identification.)	25	is a small piece of that layer to the right side,
	Page 179		Page 181
			· · · · · · · · · · · · · · · · · ·
1	BY MR. GIBSON:	1	yes. It's not labeled, but yes, it's there.
1 2	BY MR. GIBSON: Q. I'd just ask you if you've seen this	2	<ul><li>yes. It's not labeled, but yes, it's there.</li><li>Q. And that's been opened up through an</li></ul>
2		2	<ul><li>yes. It's not labeled, but yes, it's there.</li><li>Q. And that's been opened up through an etching step?</li></ul>
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1			
1	Page 182 we're considering here.	1	Page 184 A. The sealant is element 113 on the right
2		1	side.
	let me ask you this, what is part 10 or element	3	
	10?		element?
5		5	
1	film.	6	
7		7	
8		1	has is offset from the edge of the counter
9	-		substrate 500, and underneath element 113 are many
	course, which is structured and has peaks and	E E	structures. The first structure that it counters
1	valleys.	11	is the insulating layer 241. The next element
12	•		that it in going down from the sealant would be
	wire 7?		the wiring 127, and proceeding onward, the next
14	A. What are you referring to as being		element is gate dielectric 211 and then finally
15	connected to second wire 7?		the substrate 200.
16	Q. The transparent conductive layer 8.	16	Q. So you would agree that the wiring units
17	A. 8 is in direct contact with 7 in this	17	127 are running under the sealant in Shiba?
18	figure.	18	A. Some a portion of the wiring 127 lies
19	Q. And 7 is also in direct contact with 2?	19	under the sealant, largely along the direction of
20	A. Through the openings of layer 3, it is	20	the sealant.
21	contacting layer 2.	21	Q. If we look at back at Sukegawa and 2C
22	Q. You would consider those to be in direct	22	again.
23	contact, right, 7 and 2?	23	A. I've got it.
24	A. They are in direct contact through the	24	Q. And I think you have some opinions that
25	openings, yeah.	25	if lines 7 and 8 were extended, that there would
	Page 183		Page 185
1	Page 183 Q. Would you also consider them to be in	1	Page 185 be a problem with the sealant having to adhere to
1	Q. Would you also consider them to be in electrical contact, 7 and 2?	2	be a problem with the sealant having to adhere to line 8. And I want to make sure I understand what
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		<u> </u>	
1	Page 186	1	Page 18 That's the clear teaching of Sukegawa. Everywhere
1	sorry, line 8 and 7 would remain under the insulating film 9, but that's not the case that	1	that you have wiring 7, you have double coverage.
	-	1	That's central to his invention.
	I'm referring to in this paragraph, because this		
1	paragraph 174 in my disclosure is referring to a	4	
	transparent conductor that's been deposited		flipped the two layers, right?
	according to the Claims 1, which requires that the	6	
	transparent conductor be deposited through the		element 8, the transparent conductor, along with 7
	opening in the insulating film. In this Fig. 2C,	1	to the left off this picture in this hypothetical.
1	it would be element 9.	9	Q. Why can't it just end the way it is now?
10		10	<b>x</b> <i>i</i>
1	we in this hypothetical, if Sukegawa was	1	disclosure in Sukegawa. Sukegawa says it's
1	modified so that the ITO layer was deposited		central and important to prevent corrosion of the
1	through that opening and then extended, well,		terminal to have double coverage over element 7 to
1	then, of course, the ITO would be above and would	1	prevent the pin holes and wiring corrosions that
1	then be in contact with the sealant. Because		are some of which are identified in Fig. 2B
1	there's no disclosure in Sukegawa to end the ITO	1	right above.
	before getting to the sealant, the ITO in Sukegawa	17	Q. Now, I take it that you would agree that
1	is always for corrosion protection of the layer 7.		it's obvious for one of ordinary skill in the art
19	Q. Right. One of ordinary skill in the art		to open up the insulation layer to allow two
1	would know that you wouldn't want to have the ITO		metals to connect?
	layer be the layer that the sealant would bond to.	21	MR. SCHLITTER: Objection, foundation.
22	We went over that, right?	22	THE WITNESS: Can you rephrase
23	A. Well, we have the teaching of Sukegawa	1	perhaps be more specific?
	that this ITO layer is intended to protect the	1	BY MR. GIBSON:
25	corrosion of element 7. And so if someone was	25	Q. Well, the prior art, even prior art to
	Page 187		Page 189
	beginning with Sukegawa and was was applying	t	Sukegawa 2C, you're seeing someone open up an
1	it, then a person of ordinary skill would keep it		insulation layer, layer 3, to connect two metal
	despite the adhesion challenges that it may	3	layers, correct?
4	present.	4	A. That's what's going on in in the
5	Q. But we also know that one of ordinary		connection between element 7 and 2 through the
	skill in the art is going to want to have a better	6	openings in layer 3, certainly.
7	bonding and better adhesion, correct?		
1 0	÷	7	Q. So as of 1997, that would be obvious to
8	A. Well, as we also discussed, that kind of	8	one of ordinary skill in the art, that's a way to
9	A. Well, as we also discussed, that kind of question has to be decided in view of the many	8 9	one of ordinary skill in the art, that's a way to connect two wires is to open up the insulation
9 10	A. Well, as we also discussed, that kind of question has to be decided in view of the many constraints in the display system. So Sukegawa is	8 9	one of ordinary skill in the art, that's a way to connect two wires is to open up the insulation layer and then deposit the second metal?
9 10	A. Well, as we also discussed, that kind of question has to be decided in view of the many	8 9 10 11	one of ordinary skill in the art, that's a way to connect two wires is to open up the insulation layer and then deposit the second metal? A. That's one way
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9 10 11 12	A. Well, as we also discussed, that kind of question has to be decided in view of the many constraints in the display system. So Sukegawa is explicitly disclosing a solution for corrosion resistance of these these wirings, especially	8 9 10 11 12 13 14	one of ordinary skill in the art, that's a way to connect two wires is to open up the insulation layer and then deposit the second metal? A. That's one way MR. SCHLITTER: Objection, foundation. THE WITNESS: That is one way a person of ordinary skill would could do a connection
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1		1	layer 9, the only thing protecting wiring 7 is the
2	clearly disclosed in the prior art to have through	2	ITO layer 8 or the transparent conductor 8.
	holes to connect two conductors through those	3	And that's a single layer of coverage
1	holes or to make contact through those holes.	4	and his key observation is that that's not good
5		1	enough. And so he invents in Fig. 3 is one
6	1997?	6	example of his invention. He has others. He has
7			a scheme where he provides double coverage where
	that where that would also be true.		everywhere on wiring above wiring 7 there's two
9			things that protect it, including element 8, 9 and
	flip the layers under Sukegawa and still maintain	1	10 in his invention.
	protection against the corrosion that you'd have	1	BY MR. GIBSON:
	to extend the wires further than we see in 2C,	12	Q. Is that in both the terminal portion and
	what do you what exactly do you mean by that?	1	the display portion?
14		14	A. It's not because he only has wiring 7 in
15	THE WITNESS: Well, if we hypothesize		the terminal portion. So it's not in the display
	that a person takes Sukegawa and does not follow	1	portion at all. This wiring doesn't extend into
	his disclosure, but instead extends wiring 7 off	1	the display portion.
	the picture to the left, my point is that if a	18	Q. Why don't we look at paragraph 39 of
	person does that, then Sukegawa teaches that this		your declaration?
	person must also extend the transparent	20	A. I see it.
	conductor 8.	21	Q. And you're describing the invention of
22	And if we're forming 8 last so that it's	22	the '413 patent here?
	through the opening in 9, then that would	23	A. That's the subject I'm commenting on,
	necessarily also have to follow to provide that	24	the aspects of the invention, the '413 patent.
	double coverage all along the length of wiring 7.	25	Q. And you write, "Furthermore, in order to
	Page 191		Page 193
1	Page 191 That's the key disclosure of the invention in	1	improve the reliability of an LCD by providing for
		2	improve the reliability of an LCD by providing for the sealant to have favorable adhesion, this
2	That's the key disclosure of the invention in	2 3	improve the reliability of an LCD by providing for the sealant to have favorable adhesion, this invention provides a structure where the sealant
2	That's the key disclosure of the invention in Sukegawa is double coverage protecting layer 7.	2 3	improve the reliability of an LCD by providing for the sealant to have favorable adhesion, this invention provides a structure where the sealant does not overlap the ITO film."
2 3 4 5	<ul><li>That's the key disclosure of the invention in</li><li>Sukegawa is double coverage protecting layer 7.</li><li>BY MR. GIBSON:</li><li>Q. Why would you need to extend wiring 7?</li><li>A. Sukegawa teaches that wiring 7 is prone</li></ul>	2 3	improve the reliability of an LCD by providing for the sealant to have favorable adhesion, this invention provides a structure where the sealant
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1	Page 194	1	Page 196 Claim 1 of the '413 patent, there must be a
1	A. I wouldn't agree to that. If I would	1	transparent conductive layer over a first region
	disagree with that statement if we understand by	1	of the second wiring.
1	second wiring the same thing as in Claim 1 of the	1 .	And if we go to a later claim element,
_	'413 patent.	4	-
5	Q. But you would agree that there's that		which I think is 13, that transparent conductive layer must be in direct contact with that second
	in for example, in 2C in Sukegawa, there's a		
1 I	second wiring 7?	1	wiring through an opening in the second insulating
8	A. Well, there is an upper wiring, as	-	film.
9	Sukegawa calls it, that is in contact with layer 2	9	So the transparent conductor doesn't
	through the openings of layer 3, and so that's		meet the claim element. And so how can I possibly agree that there's a first region that corresponds
1	wiring that's wiring 7, but it doesn't meet the		to what's in the Claim 1? I can't.
	claim limitations of Claim 1. So I hesitate to		
I .	call that the second wiring that's in Claim 1.	13	Q. And that's because of the order of
14	Q. And you're saying that because you think	1	the order of the layers in the prior art described
	the second wiring has to be put down in a		in Sukegawa?
1	different order than what you're seeing in 2C?	16	A. Yes, the reason that wiring 7 does not
17	A. That's part of it. But the other major		have even a first region, let alone any other
	part is there needs to be a first region and		regions, is because of the ordering of the
1	second region of the second wiring and there is	1	transparent conductor is, in Sukegawa at least,
1	there is not such a division of regions in		not being through the opening of layer 9.
F	Sukegawa.	21	I'm sorry. It's not it's not in I
22	Q. You think there's just one region?	(	should say it's not in direct contact through an
23	A. It depends.		opening in the second insulating film.
24	Q. What does it depend on?	24	Q. But you would agree there's a second
25	A. Well, are you asking me if the entire	25	wiring in Sukegawa?
	Page 195		Page 197
1	Page 195 wiring 7 meets the limitations for the first	1	A. There is a numerically additional wiring
	-	1	
	wiring 7 meets the limitations for the first	1	A. There is a numerically additional wiring
2 3	wiring 7 meets the limitations for the first region in Claim 1?	2	A. There is a numerically additional wiring clearly, but it doesn't meet the claim language of
2 3	<ul><li>wiring 7 meets the limitations for the first</li><li>region in Claim 1?</li><li>Q. No, I'm asking you whether you think</li></ul>	2 3 4	A. There is a numerically additional wiring clearly, but it doesn't meet the claim language of Claim 1 of the '413 patent.
2 3 4 5	<ul><li>wiring 7 meets the limitations for the first</li><li>region in Claim 1?</li><li>Q. No, I'm asking you whether you think</li><li>there's only one region in Sukegawa?</li></ul>	2 3 4 5 6	<ul> <li>A. There is a numerically additional wiring clearly, but it doesn't meet the claim language of Claim 1 of the '413 patent.</li> <li>Q. There's a there's a transparent conductive layer?</li> <li>A. Again, there is a transparent conductive</li> </ul>
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<b>—</b>	Page 198		Dage 200
	1 BY MR. GIBSON:		Page 200 consider that to be in direct contact?
	2 Q. It wouldn't serve its intended purpose.	2	
	A. I don't know about that, but if this	3	example, from the figure?
	4 terminal region, which is also illustrated in	4	
	5 from top down in other figures, you know, if	5	layer that's touching a piece of metal, would they
1	6 that if there were no opening in layer 9 for		be in direct contact?
	7 contact to be had between the anisotropic	7	A. Well, referring to Fig. 2C, it sounds
	8 conducting film 10 and the layers below it, then	8	like you're asking me if element 8 is in direct
1	9 there would be no electrical connection, at least	9	contact with layer 7. Yes, it is.
1	0 in this portion. Of course it's possible to	10	Q. And would a transparent conductive layer
1	1 provide it somewhere else.	11	be in electrical contact if it's touching a piece
12	2 Q. Right. But as you understand the prior	12	of metal?
1	3 art that's described in 2C, there would be no	13	A. At least to the extent that we're
1	4 electrical connection provided from the FPC to the	14	talking about the contact in Fig. C between the
1:	5 conductive layer?	15	ITO and another metal, they would be in electrical
10			contact.
	7 that the opening that's illustrated was not there,	17	Q. What if there's no electricity flowing,
-	3 but was instead fully layer 9, then there would be		are they still in electrical contact?
	9 no contact between layer 10 and 8.	19	A. Whether or not there's current or
20		20	
	between 7 and 8 either, correct?	1	whether there's electrical contact.
22	8	22	Q. I take it you've read the Motion to
1	hypothesis, the only thing different was that the	1	
	l layer 9 was was simply without the opening.	24	A. I have read it.
25	5 But since element 8, the transparent conductor, is	25	Q. And what's your understanding of it?
	Page 199		Page 201
	deposited before layer 9, then the electrical	1	A. I don't recall it very specifically, so
1	2 contact between 8 and 7 is already present. So		if you want me to, I'd prefer to review it so I
	what what we do with layer 9 has no bearing on	3	can answer your questions.
	the electrical connection between 8 and 7.	4	Q. Do you have an understanding that
5	S 5, 7	5	there's been some a request should the
6		7	petition be granted, there's been a request to amend some of the claims?
8		8	A. Yes, I do understand that that's the
9		ł	purpose of the amendment.
	those two things are.	10	Q. And there's been some request to then
	BY MR. GIBSON:	1	add some limitations?
12		12	A. That's my understanding of that
12		1	amendment.
			Q. Do you know what limitations are
		14	
1	other, then I would refer to that as direct contact. And if they're both metals, they would	14 15	
15	contact. And if they're both metals, they would		requested?
15   16		15 16	requested? A. Since I wasn't involved in writing it
15   16	contact. And if they're both metals, they would also be in electrical contact, but electrical contact is not the same as direct contact.	15 16	requested? A. Since I wasn't involved in writing it and I really only read it once, I don't recall.
15 16 17	contact. And if they're both metals, they would also be in electrical contact, but electrical contact is not the same as direct contact. Q. What's the difference?	15 16 17 18	<ul><li>requested?</li><li>A. Since I wasn't involved in writing it</li><li>and I really only read it once, I don't recall.</li><li>Q. When you look at Claim 1 of the '413</li></ul>
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r	2.000	I	D 204
	Page 202	1	Page 204 Would you agree that the FPC is in
1	go over the substrate and the first insulating	$\begin{vmatrix} 1 \\ 2 \end{vmatrix}$	
1	film?	1	direct contact through layer 9 with to the
3	A. Yes.		transparent conductive layer?
4	Q. And then the second insulating film is	4	A. I'm trying to find out what element 31
5	going to go over the second wiring?		is called. All right. So you asked me about a
6	A. Yes.		flexible printed circuit, which is the language of
7	Q. And then it talks about a transparent		the '413 patent. In Sukegawa, that is composed of
	conductive layer over a first region of the second		several things or it comprises several things. So
	wiring, but it doesn't specify that it will be		it has a flexible wiring substrate 31. It has a
	over the second insulating film.	1	copper foil wiring 31B, and at least it also has
11	Do you see that?		an anisotropic conducting film 10.
12	A. The claim does not require that the	12	And depending on which of those or all
	transparent conductor be over the second		of those that you're referring to as a flexible
	insulating film. It requires instead that the		printed circuit, I would probably have to give
	direct contact with the second wiring be through		different answers. So let me answer you this way
	an opening in the second insulating film. Having	1	and you can follow-up.
	a bit of the transparent conductor on top of the	17	It is true that in Sukegawa, Fig. 2C,
18	second insulating film as illustrated in 4A is one		that the anisotropic conducting film 10 is in
19	example.		1
20	Q. Is there another way to do that, to have	20	
21	the transparent conductive layer not be over the	21	Q. Would you also consider that to be
22	insulating film?	22	
23	A. Well, if we refer to Fig. 4A in the '413	23	A. Element 10 is in electrical contact with
24	patent, an alternative would be to pattern the ITO		layer 8 because it is a direct contact and they're
25	such that that vertical edge and plateau that's	25	both conductors.
	Such that that vertical edge and plateau thats	25	both conductors.
	Page 203		Page 205
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1	Page 203	1	Page 205
1 2	Page 203 over the second insulating film wasn't there. It	1	Page 205 Q. And what's your issue with the the
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1	Bage 206	De 200
1	Page 206 Q. So I take it that you would have an	<ul><li>Page 208</li><li>1 of course, one option of many.</li></ul>
1	issue with Sukegawa showing a second wiring as	2 Q. But in 1997, that wouldn't be
	it's described in the '413 patent?	3 particularly innovative, would it?
4		4 A. It would be a preferred example, but
5		5 not not innovative to use aluminum for wirings.
6		6 Q. One of ordinary skill in the art would
	issue with Sukegawa showing either a first or a	7 know that aluminum was an option in 1997?
8		8 A. Yes.
9		9 Q. And if you look at claim Claim 4
	not a second region in Sukegawa that meets the	10 A. I see it.
	claim limitations of the '413, Claim 1.	11 Q in 1997, one of ordinary skill in the
12		12 art would know that a transparent conductive layer
	patent, would you consider the auxiliary lines and	13 could be made from an ITO?
	external connection lines to be in direct contact?	14 A. Yes, I think that would have been clear
15		15 to a person of ordinary skill at the time of the
	contact through the opening in element 112, the	16 '413 filing.
	first inter-layer film as it's called in the	17 Q. And, in fact, are you aware that
	Fig. 4A.	18 Sukegawa also discloses that?
19	-	19 MR. SCHLITTER: Objection, form.
		20 BY MR. GIBSON:
21	A. Yes.	21 Q. Are you aware that Sukegawa also
22		22 discloses that the conductive layer, the
	connection lines, do you consider those to be in	23 transparent conductive layer can be an ITO?
	direct contact?	24 A. Yes. I agree with that.
25	A. The ITO is in direct contact with the	25 Q. Now, if you look at Claim 5?
	Page 207	
1	external connection lines through the opening in	1 A. I see it.
	layer 113.	2 Q. It says, "A liquid crystal display
3	Q. And you would consider them also to be	3 device, according to Claim 1, wherein the first
	in electrical contact?	4 insulating film comprises silicon nitride."
5	A. I would, yes.	4 INSINALING THILL CONTRACT STUCOL THEFTICE.
	-	5 Would you agree that one of ordinary
6	Q. And you would consider the ITO and the	5 Would you agree that one of ordinary 6 skill in 1997 would have understood that that
6 7	Q. And you would consider the ITO and the	5 Would you agree that one of ordinary
6 7 8	Q. And you would consider the ITO and the external I'm sorry the auxiliary lines to be in electrical contact?	<ul> <li>5 Would you agree that one of ordinary</li> <li>6 skill in 1997 would have understood that that</li> <li>7 would have been an option for the first insulating</li> <li>8 film?</li> </ul>
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53 (Pages 206 - 209)

	~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~		D 010
1	Page 210 is 4:49.	1	Page 212 to make contacts through openings in an insulating
1	BY MR. GIBSON:	1	film between two conductors.
3			BY MR. GIBSON:
	would understand that if you have a deposit of a	4	Q. Now, it's your view that in the '413
	second line second wiring and then an	1	patent, the claims are limited to the order of
	insulation film on top and then an ITO layer on	1	materials as shown or the deposited materials
	top of that, that the way to connect those is to	1	are in the order as shown in Fig. 4A?
	create an opening in the insulation wire	8	A. It's my opinion that the sequence of the
9	MR. SCHLITTER: Objection as to form.		elements that are disclosed here in Claim 1 is
	BY MR. GIBSON:	10	uniquely specified. There are no materials
11	Q the insulation line?		specified.
12		12	Q. Well, putting aside the materials, the
13	THE WITNESS: To some extent it does	13	order of the manufacturing steps, you say in
	depend on the situation. It's I don't think	1	Claim 1 they really correspond to what's in
15	· · · · · · · · · · · · · · · · · · ·		Fig. 4A?
	more context.	16	A. Fig. 4A is an example that corresponds
	BY MR. GIBSON:	1	with the claim. It's not the only example, but
18	Q. Well, in 1997, if you were going to have		it's a good example.
	a structure that has a second wiring and then an	19	Q. Is there some other example that you
20			could come up with?
	transparent conductive layer and you want to	21	A. Well, we discussed one example which
	connect those two, one way to do that in 1997, it	1	would be, for example, where the ITO portion does
	was known to open up the insulation layer?		not rise up over the second insulating film, but
24	MR. SCHLITTER: Objection, form.	1	instead just lies within the opening.
25	THE WITNESS: I can agree that it was	25	Q. But the manufacturing steps would still
	Page 211		Page 213
1	known to a person of skill ordinary skill by	1	be the same in that situation, right?
	the time of 1997 that one way is to to connect	2	A. That's correct.
	those two conductors would be to create an opening	3	Q. And the order of deposits would still be
	in the insulator before the insulating before	4	the same?
	the second conductor was deposited and thereby,	5	A. The sequence of the manufacturing to
- 6		1	make the element in Claim 1, I believe is uniquely
	when you deposited the second conductor, it would make contact with the first conductor that was put	1	
7	when you deposited the second conductor, it would	6	make the element in Claim 1, I believe is uniquely
7 8	when you deposited the second conductor, it would make contact with the first conductor that was put	6 7 8	make the element in Claim 1, I believe is uniquely specified.
7 8 9	when you deposited the second conductor, it would make contact with the first conductor that was put down. It's called a through hole. It's also	6 7 8	<ul><li>make the element in Claim 1, I believe is uniquely specified.</li><li>Q. And it's always going to have the order</li></ul>
7 8 9 10	when you deposited the second conductor, it would make contact with the first conductor that was put down. It's called a through hole. It's also called a contact hole, a via, right. There's many	6 7 8 9	<ul><li>make the element in Claim 1, I believe is uniquely specified.</li><li>Q. And it's always going to have the order that's specified in 4A under your view of Claim 1?</li></ul>
7 8 9 10	when you deposited the second conductor, it would make contact with the first conductor that was put down. It's called a through hole. It's also called a contact hole, a via, right. There's many standard names for that.	6 7 8 9 10 11	<ul><li>make the element in Claim 1, I believe is uniquely specified.</li><li>Q. And it's always going to have the order that's specified in 4A under your view of Claim 1?</li><li>A. And which order are you referring to?</li></ul>
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7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>when you deposited the second conductor, it would make contact with the first conductor that was put down. It's called a through hole. It's also called a contact hole, a via, right. There's many standard names for that.</li> <li>BY MR. GIBSON:</li> <li>Q. And contact holes or through holes were well-known in the art as of 1997?</li> <li>A. They were very well-known to a person of ordinary skill and the claim language, of course, uses that terminology and specifies that the contact should happen through the opening.</li> <li>Q. But there was nothing innovative or novel about using contact hole to connect twotwo wires or a conductive layer and a wire? MR. SCHLITTER: Objection, form, foundation.</li> </ul>	6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>make the element in Claim 1, I believe is uniquely specified.</li> <li>Q. And it's always going to have the order that's specified in 4A under your view of Claim 1?</li> <li>A. And which order are you referring to?</li> <li>Q. Well, you're going to have a substrate first. You're then going to have your auxiliary lines. You're going to have a first insulating layer, then you're going to have external connection lines, an ITO then you're going to have external connection lines and a second insulating layer and then your ITO layer. That's going to be the order of deposit as set forth in Fig. 4A and is what you say is mandated also by Claim 1?</li> <li>A. You didn't mention anything about the first region and second region and the sealant.</li> </ul>

	D 014		
1	Page 214 Q. And it is Fig. 4A shows exactly what		Page 216 be put down in the order that's depicted in
	you say Claim 1 describes, correct?		Fig. 4A
3		3	
4			BY MR. GIBSON:
5		5	
6		6	
	for several paragraphs on this, but the sequence		must proceed from in this figure from the
	of layers that would need to be fabricated would	1	bottom up. And we can go through that sequence in
	be understood by a person of ordinary skill to		the claim if you'd like, but first as
	proceed from the bottom up and would correspond to	10	
	what's shown in Fig. 4A, although not exclusively,		that's fine.
1	right, at least in terms of this an example, the	12	I'm just trying to understand whether as
	sequence would still need to be the same even in	13	you read Claim 1, is there any way to do the
	other embodiments and other examples.	1	deposition order different than what you see in
15	Q. That's my question.	1	Fig. 4A?
16	Is there any other sequence, other than	16	A. It depends. I may not be able to come
17	what's shown in 4A, that would fall under the	17	up with an alternate order right now, but
18	claim language of Claim 1?	1	certainly the claim has a specific order and a
19	A. Could you rephrase the question?		specific relationship between them. And it would
20	Q. Yes. According to you, the Claim 1 has	20	probably take me a little thought, extended
21	a particular sequence of deposits, correct?	21	thought to see if I could come up with something
22	A. Yes.	22	that was substantially different from Fig. 4A but
23	Q. And Fig. 4A shows that sequence,	23	still met the claims.
24	correct?	24	What I can speak on is what the claims
25	A. Fig. 4A is an example of that sequence	25	require in terms of sequence and I have that in my
	Page 215		Page 217
1	Page 215 of deposition and patterning as well, of course,	1	Page 217 declaration. We can say it again now.
1	-	12	
1	of deposition and patterning as well, of course,	2	declaration. We can say it again now.
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55 (Pages 214 - 217)

	D 010		D
.	Page 218 it to Fig. 4A, as I've already said.	1	Page 220 A. That's how I clearly understand it and I
			certainly think that one of ordinary skill would
	here?		would also have that singular understanding.
		4	
1			on this matter, correct?
$\left  \begin{array}{c} \epsilon \\ \epsilon \end{array} \right $		6	
17		7	
			matter specifically are you referring to?
9		1	BY MR. GIBSON:
10		10	
	your in your declaration, you believe that	1	of the order that these layers must be deposited
	order is required because of the use of the word	1	in, that definition of the word "through"?
13	-	12	· · · · · · · · · · · · · · · · · · ·
14		13	2
1	word "over" that's used repeatedly and there's an	14	
1	additional overlay. And then additionally, that		marked as the next, 1019.
10		10	
	through an opening" in various films. So they	17	•
1		1	BY MR. GIBSON:
19 20		20	
20		1	depictions of two metals as well as an insulating
21			film. And if we let's assume that we're
22	MR. SCHLITTER: Objection, form.		depositing a metal 1 and then we want to form two
23			additional layers, a metal 2 and an insulating
	word "through" which is not in that phrase, that's		film and then an opening to the insulating film so
25		25	
1	Page 219 correct.	1	Page 221 the two metals can be connected to a third metal
1	BY MR. GIBSON:		which we haven't depicted here.
3	Q. That's in 1.12 in your declaration,	$\begin{vmatrix} 2\\ 3 \end{vmatrix}$	Would you agree with me that the two
	there's contact through the transparent conductive	1	ways you can do that are what's shown here?
1		5	MR. SCHLITTER: Objection, form,
6	layer? A. That's correct. The electrical contact		foundation.
-		. 0	
E /	is hy means or via the transparent conductive		
	is by means or via the transparent conductive layer to the second wiring and the FPC So in	7	THE WITNESS: Could you remind me what
8	layer to the second wiring and the FPC. So in	7 8	THE WITNESS: Could you remind me what you're asking me to assume?
8 9	layer to the second wiring and the FPC. So in other words, the second wiring and FPC are in	7 8 9	THE WITNESS: Could you remind me what you're asking me to assume? BY MR. GIBSON:
8 9 10	layer to the second wiring and the FPC. So in other words, the second wiring and FPC are in electrical contact because of the transparent	7 8 9 10	THE WITNESS: Could you remind me what you're asking me to assume? BY MR. GIBSON: Q. Yeah. We're going to lay down a first
8 9 10 11	layer to the second wiring and the FPC. So in other words, the second wiring and FPC are in electrical contact because of the transparent conductive layer. It's an alternate way to read	7 8 9 10 11	THE WITNESS: Could you remind me what you're asking me to assume? BY MR. GIBSON: Q. Yeah. We're going to lay down a first metal. That's in yellow. You see metal 1?
8 9 10 11 12	layer to the second wiring and the FPC. So in other words, the second wiring and FPC are in electrical contact because of the transparent conductive layer. It's an alternate way to read that.	7 8 9 10 11 12	THE WITNESS: Could you remind me what you're asking me to assume? BY MR. GIBSON: Q. Yeah. We're going to lay down a first metal. That's in yellow. You see metal 1? A. Yes.
8 9 10 11 12 13	layer to the second wiring and the FPC. So in other words, the second wiring and FPC are in electrical contact because of the transparent conductive layer. It's an alternate way to read that. Q. And when we look at 1.13 that does use	7 8 9 10 11 12 13	THE WITNESS: Could you remind me what you're asking me to assume? BY MR. GIBSON: Q. Yeah. We're going to lay down a first metal. That's in yellow. You see metal 1? A. Yes. Q. And then we're going to have two
8 9 10 11 12 13 14	layer to the second wiring and the FPC. So in other words, the second wiring and FPC are in electrical contact because of the transparent conductive layer. It's an alternate way to read that. Q. And when we look at 1.13 that does use direct contact through an opening, you're using	7 8 9 10 11 12 13 14	THE WITNESS: Could you remind me what you're asking me to assume? BY MR. GIBSON: Q. Yeah. We're going to lay down a first metal. That's in yellow. You see metal 1? A. Yes. Q. And then we're going to have two additional layers, a metal 2?
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56 (Pages 218 - 221)

1	Page 222	1	Page 224
1	two structures that would do that?		sure what you're imagining.
2	A. Which construct are you referring to?	2	
3		3	· · · · · · ·
4		4	layer be applied on top of this, well, surely.
5	layers, the insulating film and the need to	1	And it can be patterned if desired.
	connect to a third layer, metal layer	6	
7		7	with metal 2 and metal 1?
8	BY MR. GIBSON:	8	A. If it was simply deposited on this
9	Q is there any other way that you can	9	structure that's illustrated in Exhibit 1019, then
1	think to depict that other than these two?		part of it could be in electrical contact with
11		1	both metal 1 and metal 2.
12		12	Q. Now, if you look at the second one and
	difficult, but I'm not sure I understand your	1	we deposit metal 1 first and then we deposit
	question.	1	metal 2, and then we deposit the insulating film,
1	BY MR. GIBSON:	1	we can then create an opening to metal 2 through
16			that insulating film, correct?
[	there's a metal 1 that we've deposited?	17	
18	2		structure. Of course you could you could have
19		19	
	with metal 1?	20	-
21		1	film is deposited and then patterned and then
1	part of what I'm missing is what's the sequence		metal 2 somehow created. I mean, it's
	that you're depositing these? Or what are you	23	Q. Isn't that what we did just up above?
1	assuming is the sequence of your deposition and	24	A. That would be consistent with what's
1	patterning?	25	above.
	Page 223		Page 225
1	Q. What we're wanting to do is if you have	1	Q. And in the bottom example, we could also
1	a two metals that are contacting each other and	2	connect a metal 3 through that opening in order to
1	you're going to have an insulating film and you	2	achieve an electrical contact between metal
1			
	need to have and that insulating film in one		with metal 2 and metal 1?
5	situation you've got the we'll take the top one	4 5	A. It sounds like a very similar question
5		4 5 6	A. It sounds like a very similar question to the first illustration, that an additional
5 6 7	situation you've got the we'll take the top one first. In the first one, we've got the metal	4 5 6 7	A. It sounds like a very similar question to the first illustration, that an additional metal could be applied to the second illustration.
5 6 7 8	situation you've got the we'll take the top one first. In the first one, we've got the metal deposited, right? And then we deposit an	4 5 6 7 8	A. It sounds like a very similar question to the first illustration, that an additional metal could be applied to the second illustration. And in that case, the if metal 3 was applied,
5 6 7 8 9	situation you've got the we'll take the top one first. In the first one, we've got the metal deposited, right? And then we deposit an insulating film over the metal, metal 1. We etch	4 5 6 7 8 9	A. It sounds like a very similar question to the first illustration, that an additional metal could be applied to the second illustration. And in that case, the if metal 3 was applied, it would be applied through the opening that's in
5 6 7 8 9	situation you've got the we'll take the top one first. In the first one, we've got the metal deposited, right? And then we deposit an	4 5 6 7 8 9	A. It sounds like a very similar question to the first illustration, that an additional metal could be applied to the second illustration. And in that case, the if metal 3 was applied,
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5 6 7 8 9 10 11	situation you've got the we'll take the top one first. In the first one, we've got the metal deposited, right? And then we deposit an insulating film over the metal, metal 1. We etch out that insulating film so that we can deposit metal 2, right?	4 5 7 8 9 10 11 12 13	<ul> <li>A. It sounds like a very similar question to the first illustration, that an additional metal could be applied to the second illustration.</li> <li>And in that case, the if metal 3 was applied, it would be applied through the opening that's in the second illustration. Whereas, of course, in the first illustration, it would not be through any opening if a third metal was applied.</li> <li>Q. Now, is there any other way that you</li> </ul>
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1	layers and an insulating film -	1	BY MR. GIBSON:
2	· · · · · · · · ·	2	Q. And do you recognize Exhibit 1020?
3	metals and one insulating film.	3	A. I do.
4		4	Q. And what is Exhibit 1020?
5	have the first two metal layers in direct contact	5	A. It's a figure that's that I've
6	and then you're ultimately going to want to create	6	created or prepared and it's included in my '204
7	a way that you can connect to a third metal, what	7	declaration.
	I'm trying to understand is, are these the only	8	Q. All right. And what were you trying to
9	two ways that you could use those layers?	9	illustrate with that?
10	A. I don't know. There might be a dozen	10	A. I can comment on what's shown, but I
1	other ways.		would need my disclosure to remind myself
12	· · ·	•	specifically what I was talking about in reference
13	•		to it.
14		14	Q. Okay. Why don't you just comment on
15	A. On this exhibit?		what's shown? Part your declaration has
16		t .	similar paragraphs, but sometimes you didn't
17			include all the nice pictures in the '413 as you did in the '204.
	you're saying there's a metal 1, and there's a		
	metal 2 and you're asking me are there other ways	19	A. Well, Fig. C is showing they are
	than what's illustrated in these two where we		
	could connect them.		
22	Q. No, metal 1 and metal 2 will be in direct contact.		
23	A. In direct contact, okay, and have there		above both of those on the Fig. C side is the
1	be an insulating film somehow?		insulating layer, it's protective overcoat 241
25	be an insulating mini somenow:	25	insulating layer, it's protocitive overcout 211
			P
1	Page 227	1	Page 229
1	Q. Yes, and you'll be able to connect to a		using the language of Shiba.
2	Q. Yes, and you'll be able to connect to a third metal.	2	using the language of Shiba. So this is a hypothetical structure
2 3	<ul><li>Q. Yes, and you'll be able to connect to a third metal.</li><li>A. Sure. So one example would have first</li></ul>	2 3	using the language of Shiba. So this is a hypothetical structure using the language and labeling that's in Shiba
2 3 4	<ul><li>Q. Yes, and you'll be able to connect to a third metal.</li><li>A. Sure. So one example would have first the metal 1, then another deposition before the</li></ul>	2 3 4	using the language of Shiba. So this is a hypothetical structure using the language and labeling that's in Shiba that, in my opinion, would be would correspond
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1       substrate. The first layer that's shown here is       1       going to deposit the TTO?       Page 23.         2       - corresponds to the gate dielectric 211. And       1       and the the standler rectain 21.       A. That sequence of elements is the way         3       form left to right, would be the pad 751, a       5       Mat 1 think Fig. De ould be constructed. I think         4       form left to right, would be the pad 751, a       5       what I would point to as a first wring in this         5       e-O. It's another metal?       6       A. The sequence of elements is the way         7       A. Well, it's the first metal in this - in       8       them the insulator could be - would         9       Q. And then you have the ITO layers on top?       9       it and then finally the ITO deposited and       10         10       A. Top tied. And then the finsulator could be seare the steps that we're       12       secing in the first - the first drawing on         13       conductor is this - at least in this portion,       14       insulating film, then second, in this ease,         14       it translating on and if that was done, it would       10       A. There's no condecrots about what the         17       conductor is this - at least in this portion,       14       insulating film, then second, in this portion,         18       terminal region and if th		Da 220		n
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13       conductor is this - at least in this portion,       13       Exhibit 1019. We have a metal 1, then an         14       this pad 751. There's no other conductors below       14       insulating film, then second, in this case,         15       it.       15       insulating film, then second, in this case,         16       And I'm hypothesizing applying the       17       teaching in Sukegawa to create an ITO layer in the         18       terminal region and if that was done, it would       16       A. If we're not concerned about what the         17       teaching in Sukegawa to create an ITO layer in the       16       A. If we're not concerned about what the         18       terminal region and if that was done, it would       19       Q. Okay. And then in Fig. C., what are you         20       don't think it's obvious to a person of ordinary       21       A. Isn't that what I just commented on?         21       is done, then Fig. C on the left is what would       22       Q. I think we were dealing with Fig. D.         23       A. Okay. Well, Fig. C represents what I       24         24       Q. And what's going to go on top of the ITO?       23       A. If wo're not of creates a person of ordinary skill apply Sukegawa         25       Q. Uh-huh. Yes.       1       1       to Shiba. I don't think that's appropriate. I         2       oh	1			
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24 Then you're going to deposit then you're going 24 second figure in 1019.				
				second figure in 1019.
		to etch me protective overcoat and then you're	23	

59 (Pages 230 - 233)

1		1	Dago 226
1	Page 234	1	Page 236 Q. Thank you for the clarification.
	BY MR. GIBSON:	$\begin{vmatrix} 1\\2 \end{vmatrix}$	
2	Q. Now, what you drew at the bottom of Exhibit 1019, could you apply that to Sukegawa		what I think would result and I think a person of
1	somehow?	1	ordinary skill would see as possible, even though
5	· · · · ·		I don't think that combination is obvious.
	on	6	Fig. D is what it would have to be to
7			read on our claim in the '413 patent because in
8			Fig. D, the ITO layer, the transparent conductor,
9	-		is being applied through the opening of the second
	to speculate at all. That's never that's never		insulating film. Although, I mean, let's also be
1	what I'm asking you to do.		clear that there is no first insulating film in
12			these figures. It's simply an insulating film.
1	Exhibit at the bottom of Exhibit 1019, is that	13	Q. I'm just asking you, is there a third
	a structure that you think one of ordinary skill	14	option that you see applying Sukegawa to Shiba or
1	in the art would apply to Sukegawa to modify it?		are these the only two?
16	MR. SCHILITTER: Objection, form and	16	A. There is a third option. I think it's
17		17	important to mention. If Shiba is taken by a
18	THE WITNESS: It depends. I mean, my	18	person of ordinary skill and really without
19	figure was in response to your request that I		modification to the processing steps an ITO layer
20	imagine another way to connect three metals and an	20	is created in the terminal portion, then this ITO
21	insulator.	21	would form beneath pad 751. It would be below
22	BY MR. GIBSON:	22	751. So that's a third third example. I talk
23	Q. Right.	23	about it, but I don't illustrate that.
24	A. And there are more. There are many more	24	Q. Can you draw that?
25	than what I've just shown here.	25	A. Should I draw it on 1021?
	Page 235		Page 237
1	Q. Now I'm narrowing it.	1	Q. Please. 1020 I think that is.
2		2	A. I'm sorry, 1020. (Indicating.)
1	imagine a way that this could be applied to the	3	So I've drawn it there. That's the most
4	teaching in Sukegawa.	4	natural variation of Shiba to a person of ordinary
5	Q. Yes, just as you did with exhibits	5	1
6	with your Figs. C and D.	ſ	without changing the manufacturing of the display.
7		7	Q. But Sukegawa would suggest putting the
1	any living the teaching of one notant to enother and		
	applying the teaching of one patent to another and		ITO layer above, right, for protection?
1	considering what would result.	9	A. That's the teaching of Sukegawa, but
10	considering what would result. In this case, it's it's an arbitrary	9 10	A. That's the teaching of Sukegawa, but it's this third figure that I've drawn that is
10 11	considering what would result. In this case, it's it's an arbitrary connection of three metals and an insulator	9 10 11	A. That's the teaching of Sukegawa, but it's this third figure that I've drawn that is trivial and obvious to a person of ordinary skill,
10 11 12	considering what would result. In this case, it's it's an arbitrary connection of three metals and an insulator without a context. It's it would be hard for	9 10 11 12	A. That's the teaching of Sukegawa, but it's this third figure that I've drawn that is trivial and obvious to a person of ordinary skill, not the Sukegawa combination.
10 11 12 13	considering what would result. In this case, it's it's an arbitrary connection of three metals and an insulator without a context. It's it would be hard for me to do that. I think I can't imagine, as I'm	9 10 11 12 13	<ul><li>A. That's the teaching of Sukegawa, but it's this third figure that I've drawn that is trivial and obvious to a person of ordinary skill, not the Sukegawa combination.</li><li>Q. But a person of ordinary skill would</li></ul>
10 11 12 13 14	considering what would result. In this case, it's it's an arbitrary connection of three metals and an insulator without a context. It's it would be hard for me to do that. I think I can't imagine, as I'm here now, where it would be obvious to a person of	9 10 11 12 13 14	<ul><li>A. That's the teaching of Sukegawa, but</li><li>it's this third figure that I've drawn that is</li><li>trivial and obvious to a person of ordinary skill,</li><li>not the Sukegawa combination.</li><li>Q. But a person of ordinary skill would</li><li>recognize that you'd want to put the ITO layer on</li></ul>
10 11 12 13 14 15	considering what would result. In this case, it's it's an arbitrary connection of three metals and an insulator without a context. It's it would be hard for me to do that. I think I can't imagine, as I'm here now, where it would be obvious to a person of ordinary skill to employ this kind of structure in	9 10 11 12 13 14 15	<ul><li>A. That's the teaching of Sukegawa, but it's this third figure that I've drawn that is trivial and obvious to a person of ordinary skill, not the Sukegawa combination.</li><li>Q. But a person of ordinary skill would recognize that you'd want to put the ITO layer on top to avoid corrosion?</li></ul>
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10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>considering what would result.</li> <li>In this case, it's it's an arbitrary</li> <li>connection of three metals and an insulator</li> <li>without a context. It's it would be hard for</li> <li>me to do that. I think I can't imagine, as I'm</li> <li>here now, where it would be obvious to a person of</li> <li>ordinary skill to employ this kind of structure in</li> <li>Sukegawa. There's no teaching against it, of</li> <li>course.</li> <li>Q. Are there in looking at your Figs. C</li> <li>and D, when you applied the teachings of Shiba to</li> <li>Sukegawa, did you see a third option beyond a</li> <li>Fig. C and D?</li> <li>A. To be a little more clear, it was really</li> </ul>	9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>A. That's the teaching of Sukegawa, but</li> <li>it's this third figure that I've drawn that is</li> <li>trivial and obvious to a person of ordinary skill,</li> <li>not the Sukegawa combination.</li> <li>Q. But a person of ordinary skill would</li> <li>recognize that you'd want to put the ITO layer on</li> <li>top to avoid corrosion?</li> <li>A. Well, a person beginning with the</li> <li>disclosure in Shiba would recognize that Shiba is</li> <li>intended to minimize and not increase the</li> <li>manufacturing steps as well as other objectives</li> <li>that have to do with the width of the seal region</li> <li>and those kind of things.</li> <li>And so Sukegawa's objective and</li> </ul>

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-		Page 238		Page 240
	1	counter.	1	black?
	2	Q. If you could turn back to Exhibit 1014,	2	2 A. Yes.
		this is the modified Shiba. You have that in	3	( )
	4	front of you?	4	contact, no charge can be stored?
	5	A. I do have it.	5	A. I would not agree with that because the
	6	Q. I want to make sure I understand where	6	signals in this portion are changing in time and
	7	the three capacitors are.	7	' so it's not a static situation. It's something
	8	A. There's two capacitors.	8	that has fairly high frequency signals going on.
	9	Q. Okay. You're saying there's two	9	If it were static and this was a display
1	10	capacitors and the first one is in pink?		that was in the same image and nothing was
1	11	A. Well, a capacitor is formed with three	11	changing in this electrical portion, then they
1	12	elements. The first element would be a conductor.	12	would that may be, but that's not the case
1	13	That would be the pink element. The rest of the		here, right. There's going to be time varying
1	14	capacitor would be the dielectric, which is in	14	signals that are fairly high frequency.
		orange. I guess it's 211. And then finally, the	15	
1	16	black or dark brown illustrated here as an	16	voltage difference between these two?
1	17	extension of the source electrode 231.	17	A. Oh, there certainly could be a voltage
1	18	Q. Okay. So that's that's one		difference between the pixel electrode 251 as
1	19	capacitor.	19	illustrated here, and the source electrode 231.
2	20	And what is the second one, just the		It would depend on the signals that are going
2	21	pixel electrode itself?	21	through.
2	22	A. Well, no. All capacitors have to have	22	Q. Now, you would and you would agree,
2	23	two conductors and an insulator somehow in	23	though, the first capacitor you identified already
2	24	between. So the other one begins with the source	24	exists in Shiba? It's the second one that you're
2	25	electrode 231, proceeds up where the insulator is	25	pointing to as potentially causing an issue?
		Page 239		Page 241
	1	the protective overcoat 241 and then the final	1	A. By "first capacitor," do you mean the
	2	conductor is pixel electrode 271 in this	2	capacitor formed by the capacitor line Cj and the
	3	illustration.	3	extended source electrode 231?
	4	Q. I see. And that forms a second	4	Q. Yes.
	5	capacitor?	5	
	6		1 7	A. That's not disclosed in Shiba at all, of
		A. It's a		A. That's not disclosed in Shiba at all, of course.
	7	A. It's a MR. SCHLITTER: 251.		-
1	8	A. It's a MR. SCHLITTER: 251. THE WITNESS: I'm sorry, yes, 251 is the	6 7 8	course. Q. Do you think there's a capacitor in Shiba?
	8 9	A. It's a MR. SCHLITTER: 251. THE WITNESS: I'm sorry, yes, 251 is the pixel electrode. So those three elements form an	6 7 8 9	course. Q. Do you think there's a capacitor in Shiba? A. There certainly is a capacitor in Shiba
1	8 9 0	A. It's a MR. SCHLITTER: 251. THE WITNESS: I'm sorry, yes, 251 is the pixel electrode. So those three elements form an additional capacitor that is, in principle, in	6 7 8 9 10	course. Q. Do you think there's a capacitor in Shiba? A. There certainly is a capacitor in Shiba and it's formed between the capacitor line Cj and
1 1	8 9 0 1	A. It's a MR. SCHLITTER: 251. THE WITNESS: I'm sorry, yes, 251 is the pixel electrode. So those three elements form an additional capacitor that is, in principle, in series with the first.	6 7 8 9 10 11	<ul><li>course.</li><li>Q. Do you think there's a capacitor in Shiba?</li><li>A. There certainly is a capacitor in Shiba and it's formed between the capacitor line Cj and the pixel electrode 251 with the gate dielectric</li></ul>
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1	Page 242		Page 244
1	before, but the connection that's being made	1	two wires and how they're connected through the
	between the lines 401 and 403 through the	2	insulation film?
	inter-layer film, that's something that was known	3	A. Are you referring to the what's
1	in 1997 before the '413 patent, correct?	4	labeled as 401 and 403?
5	A. Making connections through openings in	5	Q. I am.
6	an insulating film similar to what's represented	6	A. There's at least two advantages that I
	here was well-known to a person of ordinary skill.	7	think are identified in the spec that at least
	And that phrase "contact through an opening" is	8	as best I recall, first these lines, of course,
9	representative of that enigmatic term in the art.	9	extend to the left in this illustration and go
10	Q. Would you consider this to be a	10	across the sealant and that can be and so going
11	multi-layer wiring?	11	from the right side, the terminal portion, to the
12	MR. SCHLITTER: Objection to form.	12	left under the sealant in this illustration would
13	THE WITNESS: What specifically are you	13	mean that the resistance of that connection from
14	asking about?	14	the right side, the terminal in this illustration
	BY MR. GIBSON:	1	to the left through the sealant, that resistance
16	Q. The connection between well, not the	1	is lowered.
17	connection, but the way that 111 and 111	17	An additional benefit or advantage is
	sorry 401 and 403 are depicted in Fig. 4, would	18	that the there's redundancy in those wirings
1	you consider that to be multi-layer wiring	1	and in this structure. So that's definitely an
	structures?	E Contraction of the second se	advantage in this context.
21	A. I would not.	21	Q. And in 1997, were those advantages
22	Q. Why not?	22	well-known to someone of ordinary skill in the
23	A. And I also don't think a person of	1	art?
	ordinary skill would call it that in this context.	24	A. In this context, no.
	Well, the specification in the '413 and the claims	25	Q. I don't mean I don't know what you
	Page 243		Page 245
1	refer to those elements 401 and 403 as separate	1	meant by "in this context," but what I'm saying,
	refer to those elements 401 and 403 as separate		
2	•	2	meant by "in this context," but what I'm saying,
2	refer to those elements 401 and 403 as separate wirings, a first wiring and a second wiring in the	2 3	meant by "in this context," but what I'm saying, having a two wires connected through an
2 3	refer to those elements 401 and 403 as separate wirings, a first wiring and a second wiring in the claim. Of course it has different words in the	2 3 4	meant by "in this context," but what I'm saying, having a two wires connected through an insulation layer, were there advantages to those
2 3 4 5	refer to those elements 401 and 403 as separate wirings, a first wiring and a second wiring in the claim. Of course it has different words in the	2 3 4	meant by "in this context," but what I'm saying, having a two wires connected through an insulation layer, were there advantages to those that were known to people of ordinary skill in the
2 3 4 5 6	refer to those elements 401 and 403 as separate wirings, a first wiring and a second wiring in the claim. Of course it has different words in the figure, and so this is a single connection that	2 3 4 5 6	meant by "in this context," but what I'm saying, having a two wires connected through an insulation layer, were there advantages to those that were known to people of ordinary skill in the art in 1997?
2 3 4 5 6	refer to those elements 401 and 403 as separate wirings, a first wiring and a second wiring in the claim. Of course it has different words in the figure, and so this is a single connection that involves two wirings, but I don't think it's fair	2 3 4 5 6 7	<ul><li>meant by "in this context," but what I'm saying, having a two wires connected through an insulation layer, were there advantages to those that were known to people of ordinary skill in the art in 1997?</li><li>A. For a terminal connection in an LCD that</li></ul>
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	Page 246		Page 248
1	wirings.		removed, but I think what's more likely is
2	Q. Any others?	2	material oxidizes or has some kind of chemical
3	A. Any others of examples of contacts being	3	change so that it's no longer a good conductor.
4	made through an opening between two conductors?	4	So if layer 7 and layer 2 were simply
5	Q. Right.	5	flat and laid on top of each other, there would be
6		1	immediate degradation or the potential would be
7	must be in just about every electronic circuit	1	immediate degradation more rapidly than in this
	that we have in our pockets and on this table and	1	structure where the corrosion would have to go
	they would have been similarly in 1997. But, of	1	around other structures.
	course, in Claim 1, it's not simply that they're	10	
	connected, but there's other claim elements that		prior art that weren't dealing with the corrosion
	show this advantage in the terminal region to		issue, right?
	accomplish something specific.	13	A. I'd have to read the specification to be
13 14			sure. It is prior art. I'm not so sure that they
	1997, what were the advantages of connecting these		don't deal with corrosion. I think what he's
		1	
	two lines through a contact hole?	1	as best I recall, what he does is he refers to
17	5 .	1	this prior art to say in these cases, there's only
18	6	1	a single layer of protection that's provided in
	I mean, I can't really hypothesize and speculate		this region through the transparent conductor 8
20	*	20	0
21	· ·	1	good enough for his purposes. But until Sukegawa,
22		1	at least in some cases, that was good enough.
23	0	23	Q. And what I want to try to get at is,
	BY MR. GIBSON:	1	before Sukegawa, you have two lines being two
25	Q. And why is that?	25	wires being connected through an insulating
	Page 247		Page 249
1	A. Well, he explains that he uses this	1	opening, correct?
2	structure of wiring contact 7 and contacting	2	A. Certainly.
3	wiring 2 through the opening in 3 to well, to	3	Q. And you're saying the only motivation
4	ensure a corrosion-resistant terminal in	4	you knew of in 1997 to do that was to avoid
5	combination with the other elements.	r –	corrosion?
	combination with the other cichlents.	5	conosion:
6	And I think I don't know if he	5 6	A. That's not at all what I'm saying.
6 7	And I think I don't know if he	1	
7	And I think I don't know if he explicitly says this, but I would recognize that	6 7	A. That's not at all what I'm saying.
7 8	And I think I don't know if he explicitly says this, but I would recognize that that structure helped Sukegawa in the peeling	6 7	<ul><li>A. That's not at all what I'm saying.</li><li>Q. Okay. What other reasons would someone</li></ul>
7 8 9	And I think I don't know if he explicitly says this, but I would recognize that	6 7 8 9	<ul><li>A. That's not at all what I'm saying.</li><li>Q. Okay. What other reasons would someone do that, someone of ordinary skill in the art?</li></ul>
7 8 9 0	And I think I don't know if he explicitly says this, but I would recognize that that structure helped Sukegawa in the peeling operation because it provides a rough surface with	6 7 8 9 10	<ul><li>A. That's not at all what I'm saying.</li><li>Q. Okay. What other reasons would someone do that, someone of ordinary skill in the art?</li><li>A. In microelectronics, it is a common</li></ul>
7 8 9 0	And I think I don't know if he explicitly says this, but I would recognize that that structure helped Sukegawa in the peeling operation because it provides a rough surface with peaks and valleys so that the anisotropic conductor can better connect in his context than	6 7 8 9 10 11	<ul> <li>A. That's not at all what I'm saying.</li> <li>Q. Okay. What other reasons would someone do that, someone of ordinary skill in the art?</li> <li>A. In microelectronics, it is a common occurrence that there needs to be a connection between conductors of different layers, different</li> </ul>
7 8 9 10 1	And I think I don't know if he explicitly says this, but I would recognize that that structure helped Sukegawa in the peeling operation because it provides a rough surface with peaks and valleys so that the anisotropic conductor can better connect in his context than it would be if it was a flat layer.	6 7 8 9 10 11 12	<ul> <li>A. That's not at all what I'm saying.</li> <li>Q. Okay. What other reasons would someone do that, someone of ordinary skill in the art?</li> <li>A. In microelectronics, it is a common occurrence that there needs to be a connection between conductors of different layers, different physical layers. And that's achieved most</li> </ul>
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1	Page 250		Page 252
1	A. Well, again, there are many situations	1	think of any more.
	where there's a circuit that has a metal wiring on		BY MR. GIBSON:
1	one layer and then an insulator and then another	3	Q. So if we look at Sukegawa again maybe
1	metal. The kind of chips that we have nowadays	4	we'll look at 1B this time.
1	have, I think, half a dozen. It's very common.	5	A. I've got it.
	And even my students prototype PC boards with	6	Q. And would you consider this to depict
	multi-layer wiring. That's not	7	multi-layer wiring, a multi-layer wiring
	semiconductor-based, but it's simply proto boards.	1	structure?
9	And in those cases, of course, they have	9	A. I would not and I think Sukegawa would
1	an insulator, they have different levels of	10	also not call it that.
1	wiring, and they often make holes in the insulator	11	Q. What type of structure would you call
	and make contact through them. It's a way to make	12	it?
	contact between metals that are in different	13	A. I think a person of ordinary skill at
14	layers.	14	the time of the '413 patent would call this a
15	Q. But it doesn't have any other	15	structure that that has multiple wirings in it
16	advantages, it's just a way to make contact?	16	and insulators. So if you're referring to
17	A. I wouldn't characterize it that way.	17	elements 2, 3, 7 and 8, then it's a four-layer
18	I'm saying that's that's what one of ordinary	18	structure.
19	skill would begin with. There may be advantages	19	Q. With multiple wirings?
20	to that beyond it. Sukegawa has one. There may	20	A. With multiple wirings.
21	be more.	21	Q. Would you consider those wires to be
22	Q. And as of 1997, are you aware of what	22	deposited in a layer?
23	those would be?	23	MR. SCHLITTER: Objection, form.
24	MR. SCHLITTER: Objection, form,	24	THE WITNESS: Which one in particular
25	foundation.	25	or
	Page 251		Page 253
1	Page 251 THE WITNESS: As I sit here now, I can't	1	Page 253 BY MR. GIBSON:
1	-	2	BY MR. GIBSON: Q. Well, let's take 2. Is that deposited
2	THE WITNESS: As I sit here now, I can't	2	BY MR. GIBSON: Q. Well, let's take 2. Is that deposited in a layer on the substrate?
2	THE WITNESS: As I sit here now, I can't speculate and list them all for you.	2 3 4	<ul><li>BY MR. GIBSON:</li><li>Q. Well, let's take 2. Is that deposited</li><li>in a layer on the substrate?</li><li>A. Well, whether it's a layer, it does</li></ul>
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<sup>64 (</sup>Pages 250 - 253)

		-	
1	Page 254 THE WITNESS: I'm not sure. It would	1	Page 256 corrosion?
	depend on that context.	2	
	BY MR. GIBSON:	3	
3			
	Q. You would agree with me that there's a	4	
5	deposit of wire 2 and then over that there's a	5	5
6	deposit of an insulating film 3?	6	1 1 2
7	A. Yes, that's certainly what's in Fig. 1B.	7	· ·
8	Q. And then there's an etching step that	8	
9	5	1	Fig. 3C.
10	A. Yes, they're I think a person of	10	A. I see it.
11	ordinary skill would expect that, even if it's not	11	Q. And focusing on the right side of
12	explicitly talked about.	12	Fig. 3C, do you see layer 9?
13	Q. And then layer 7 or wiring 7 is	13	A. I do see it.
14	deposited?	14	Q. And would you agree that it's going to
15	A. That's correct.	15	be present to the right of the arrow labeled "for
16	Q. And it fills in the holes that we have	16	terminal portion"?
17	in layer 3?	17	A. Well, there's two "for terminal portion"
18	A. I don't think it's illustrated as	18	labels, one to the right and one to the left.
	filling in the holes, but clearly it's going into	19	Q. I'm talking about the one to the right.
	the holes. It's going through the openings to	20	A. And the one on the left does not have
	make the contact in with layer 2 through the	21	layer 9 on it, of course, but the one on the right
	openings in layer 3.		does. So I would understand it, at least on the
23	Q. All right. So there's and there's	1	right side, to extend what's implied here is
	electrical contact between layers or wire 7 and	•	that it extends all the way to the terminal
1	wire 2 as a result of the holes in layer 3?		portion.
25	whe z as a result of the holes in layer 5?	25	portion.
	Page 255		Page 257
1	A. Yes, that's right.	1	Q. And if we look back at Fig. 1B
2	Q. And 6 is depicting one of those holes?	2	A. I've got it.
3	A Wall 6 is pointing to one of those	3	Q do you see that there's layer 9 on
1	A. Well, 6 is pointing to one of those		
	holes. I'm not sure if it's specifically the	4	the left?
5	holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec,		the left? A. I do.
5 6	holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the	4 5 6	<ul><li>the left?</li><li>A. I do.</li><li>Q. And it's going to be extending to the</li></ul>
5 6 7	holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in	4 5 6	<ul><li>the left?</li><li>A. I do.</li><li>Q. And it's going to be extending to the display portion, is that correct?</li></ul>
5 6 7	holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.	4 5 6 7 8	<ul><li>the left?</li><li>A. I do.</li><li>Q. And it's going to be extending to the display portion, is that correct?</li><li>A. I do see what Fig. 1B says about that,</li></ul>
5 6 7	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> </ul>	4 5 6 7 8 9	<ul><li>the left?</li><li>A. I do.</li><li>Q. And it's going to be extending to the display portion, is that correct?</li><li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side</li></ul>
5 6 7 8	holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.	4 5 6 7 8 9	<ul><li>the left?</li><li>A. I do.</li><li>Q. And it's going to be extending to the display portion, is that correct?</li><li>A. I do see what Fig. 1B says about that,</li></ul>
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5 6 7 8 9 10 11 12 13 14	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> </ul>	4 5 6 7 8 9 10 11 12 13	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> </ul>
5 6 7 8 9 10 11 12 13 14 15	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of,</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that,</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of, element 9?</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that, at least occasionally in Sukegawa's mind,</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18 19	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over</li> <li>elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of, element 9?</li> <li>A. The specification for Sukegawa mentions</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that, at least occasionally in Sukegawa's mind, element 9 does get interrupted is Fig. 3C where</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of, element 9?</li> <li>A. The specification for Sukegawa mentions that it can be made of silicon nitride.</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that, at least occasionally in Sukegawa's mind, element 9 does get interrupted is Fig. 3C where it's interrupted on the left side of that figure</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of, element 9?</li> <li>A. The specification for Sukegawa mentions that it can be made of silicon nitride.</li> <li>Q. And you would agree that's an insulating</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that, at least occasionally in Sukegawa's mind, element 9 does get interrupted is Fig. 3C where it's interrupted on the left side of that figure and I can't say.</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of, element 9?</li> <li>A. The specification for Sukegawa mentions that it can be made of silicon nitride.</li> <li>Q. And you would agree that's an insulating layer?</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that, at least occasionally in Sukegawa's mind, element 9 does get interrupted is Fig. 3C where it's interrupted on the left side of that figure and I can't say.</li> <li>Q. I'm not talking about the left side,</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of, element 9?</li> <li>A. The specification for Sukegawa mentions that it can be made of silicon nitride.</li> <li>Q. And you would agree that's an insulating layer?</li> <li>A. Yes, I would.</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that, at least occasionally in Sukegawa's mind, element 9 does get interrupted is Fig. 3C where it's interrupted on the left side of that figure and I can't say.</li> <li>Q. I'm not talking about the left side, though. I'm talking about Fig. 3C from the right</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24	<ul> <li>holes. I'm not sure if it's specifically the opening in 3 or not. I'd have to check the spec, but it is pointing to the vicinity of one of the openings. Element 6 is the contact hole in layer 3. They're also called through holes.</li> <li>Q. Looking again at 2C</li> <li>A. I've got it.</li> <li>Q you would agree that that 9 is an insulation layer?</li> <li>A. 9 is an insulating layer.</li> <li>Q. And it's extending over 8 and 7?</li> <li>A. In Fig. 2C, it is partially over elements 8 and 7, yes.</li> <li>Q. Do you know what it's made of, element 9?</li> <li>A. The specification for Sukegawa mentions that it can be made of silicon nitride.</li> <li>Q. And you would agree that's an insulating layer?</li> </ul>	4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	<ul> <li>the left?</li> <li>A. I do.</li> <li>Q. And it's going to be extending to the display portion, is that correct?</li> <li>A. I do see what Fig. 1B says about that, sure. Element 9 is there. It's on the left side of Fig. 1B and I think what's implied is that it would extend to the left toward the display portion.</li> <li>Q. Without interruption?</li> <li>A. I can't say.</li> <li>Q. Is there anything that tells you it would be interrupted somewhere along that path?</li> <li>A. Well, the one thing that tells me that, at least occasionally in Sukegawa's mind, element 9 does get interrupted is Fig. 3C where it's interrupted on the left side of that figure and I can't say.</li> <li>Q. I'm not talking about the left side,</li> </ul>

65 (Pages 254 - 257)

	Bogg 259		Page 260
1	Page 258 would be interrupted in that area?	1	Q. Well, let me get to my question. And
2	A. There's nothing to suggest that it is	1	I'll move to strike the last sentence and just not
3		•	being responsive.
	that it's not.	4	Will the you would agree that where
	Q. Do you agree that the insulating layer 9		you see 7A, it is going to be under insulating
5	is the top layer between the display portion and		layer 9?
4	the terminal portion?	7	MR. SCHLITTER: Objection, form.
8	A. Again, if we go back to Fig. 3C, that	8	THE WITNESS: The only time layer 7A is
			illustrated, as far as I can tell, is in Fig. 3C.
9	clearly not true on the left side.		And clearly, it's under element 9 in that figure.
11	Q. I'm talking about from the right of 3C	1	BY MR. GIBSON:
	to the left of 1B, would you agree that layer 9 is	12	Q. And do you see any indication that 7A
	shown to be is shown to be the top layer	•	would not be under element 9?
	between the display portion and the terminal	14	A. It's it's not clear to me that it
		1	would be either way. I can't tell either way.
1	portion?	16	Q. And would you well, there's nothing
16	A. Well, I thought I just answered that. So Fig. 3C has two terminal portions, right?		that ever shows that 7A is above layer 9, correct?
	There's one on the left side and one on the right	18	A. There's nothing that shows that, no.
	side. I believe one of ordinary skill would see	19	Q. Okay. Is there anything that ever shows
		1	7A exposed without a layer 9?
	Fig. 1B or terminal figures in Sukegawa as representing either side of the display. It	20	A. Well, the whole terminal portion, yeah.
	depends on how it's put into the display.	22	Q. What are you referring to?
22	And so I think Fig. 1B can be seen on	23	A. Well, for example, we were talking about
1	both sides of Fig. 3C as as one option. So		Fig. 1B, but this is true of many of the examples.
1	Fig. 3C clearly says that there are terminals on		In Fig. 1B, there's an opening created in the
25			
	Page 259	1	Page 261
	either side of it and on the right side, layer 9		terminal portion in layer 9 and in layer 9, or underneath that opening is wiring 7 as well as
	does appear to extend from that side to the		
3			
1 .	terminal portion. But on the left side, it	3	other things, and there is no insulating film 9
1	terminal portion. But on the left side, it clearly cannot.	3 4	other things, and there is no insulating film 9 above that.
5	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right	3 4 5	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A,
5 6	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side.	3 4 5 6	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A.
5 6 7	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree	3 4 5 6 7	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is
5 6 7 8	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the	3 4 5 6 7 8	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9?
5 6 7 8 9	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion?	3 4 5 6 7 8 9	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that
5 6 7 8 9 10	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9	3 4 5 6 7 8 9 10	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa.
5 6 7 8 9 10 11	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion,	3 4 5 6 7 8 9 10 11	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa. Q. Is there any implicit disclosure?
5 6 7 8 9 10 11 12	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion, but not on the left side.	3 4 5 6 7 8 9 10 11 12	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa. Q. Is there any implicit disclosure? A. Only to the extent that Fig. 3C shows an
5 6 7 8 9 10 11 12 13	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion, but not on the left side. Q. Now, if you look at Fig. 3C, you see	3 4 5 6 7 8 9 10 11 12 13	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa. Q. Is there any implicit disclosure? A. Only to the extent that Fig. 3C shows an example where layer 9 ends and conductors
5 6 7 8 9 10 11 12 13 14	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion, but not on the left side. Q. Now, if you look at Fig. 3C, you see wiring 7A?	3 4 5 6 7 8 9 10 11 12 13 14	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa. Q. Is there any implicit disclosure? A. Only to the extent that Fig. 3C shows an example where layer 9 ends and conductors continue.
5 6 7 8 9 10 11 12 13 14 15	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion, but not on the left side. Q. Now, if you look at Fig. 3C, you see wiring 7A? A. I do.	3 4 5 6 7 8 9 10 11 12 13 14 15	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa. Q. Is there any implicit disclosure? A. Only to the extent that Fig. 3C shows an example where layer 9 ends and conductors continue. Q. Well, that doesn't have a 7A?
5 6 7 8 9 10 11 12 13 14 15 16	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion, but not on the left side. Q. Now, if you look at Fig. 3C, you see wiring 7A? A. I do. Q. Would you agree that's the data signal	3 4 5 6 7 8 9 10 11 12 13 14 15 16	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa. Q. Is there any implicit disclosure? A. Only to the extent that Fig. 3C shows an example where layer 9 ends and conductors continue. Q. Well, that doesn't have a 7A? A. Well, it may not have a 7A, but it has
5 6 7 8 9 10 11 12 13 14 15 16 17	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion, but not on the left side. Q. Now, if you look at Fig. 3C, you see wiring 7A? A. I do. Q. Would you agree that's the data signal wiring that extends toward the terminal portion?	3 4 5 6 7 8 9 10 11 12 13 14 15 16 17	other things, and there is no insulating film 9 above that. Q. I'm referring specifically to 7A, element 7A. Do you ever see a situation where 7A is exposed in an opening of 9? A. There is no explicit disclosure of that situation in Sukegawa. Q. Is there any implicit disclosure? A. Only to the extent that Fig. 3C shows an example where layer 9 ends and conductors continue. Q. Well, that doesn't have a 7A? A. Well, it may not have a 7A, but it has an 8A. I'm looking to see what 8A is called. In
5 6 7 8 9 10 11 12 13 14 15 16 17 18	terminal portion. But on the left side, it clearly cannot. Q. Okay. But I'm focusing on the right side. And on the right side, would you agree with me that it's the uppermost layer over the display and the terminal portion? A. On the right side, it is likely that 9 does extend from this TFT to the terminal portion, but not on the left side. Q. Now, if you look at Fig. 3C, you see wiring 7A? A. I do. Q. Would you agree that's the data signal wiring that extends toward the terminal portion? A. Yes, 7A is the data signal wiring. It's	3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18	<ul> <li>other things, and there is no insulating film 9 above that.</li> <li>Q. I'm referring specifically to 7A, element 7A.</li> <li>Do you ever see a situation where 7A is exposed in an opening of 9?</li> <li>A. There is no explicit disclosure of that situation in Sukegawa.</li> <li>Q. Is there any implicit disclosure?</li> <li>A. Only to the extent that Fig. 3C shows an example where layer 9 ends and conductors continue.</li> <li>Q. Well, that doesn't have a 7A?</li> <li>A. Well, it may not have a 7A, but it has an 8A. I'm looking to see what 8A is called. In this case, it's a conductor. It's the pixel</li> </ul>
5 6 7 8 9 10 11 12 13 14 15 16 17 18 19	<ul> <li>terminal portion. But on the left side, it</li> <li>clearly cannot.</li> <li>Q. Okay. But I'm focusing on the right</li> <li>side.</li> <li>And on the right side, would you agree</li> <li>with me that it's the uppermost layer over the</li> <li>display and the terminal portion?</li> <li>A. On the right side, it is likely that 9</li> <li>does extend from this TFT to the terminal portion,</li> <li>but not on the left side.</li> <li>Q. Now, if you look at Fig. 3C, you see</li> <li>wiring 7A?</li> <li>A. I do.</li> <li>Q. Would you agree that's the data signal</li> <li>wiring that extends toward the terminal portion?</li> <li>A. Yes, 7A is the data signal wiring. It's not shown in Fig. 3C where it goes, but it</li> </ul>	3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19	<ul> <li>other things, and there is no insulating film 9 above that.</li> <li>Q. I'm referring specifically to 7A, element 7A.</li> <li>Do you ever see a situation where 7A is exposed in an opening of 9?</li> <li>A. There is no explicit disclosure of that situation in Sukegawa.</li> <li>Q. Is there any implicit disclosure?</li> <li>A. Only to the extent that Fig. 3C shows an example where layer 9 ends and conductors continue.</li> <li>Q. Well, that doesn't have a 7A?</li> <li>A. Well, it may not have a 7A, but it has an 8A. I'm looking to see what 8A is called. In this case, it's a conductor. It's the pixel electrode.</li> </ul>
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66 (Pages 258 - 261)

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		1	
1	Page 262 contact with layer 9?	1	Page 264 the sealant.
2	MR. SCHLITTER: Objection, foundation.	2	Q. Do you know if Sukegawa discloses
3	THE WITNESS: It's not disclosed in	1	internal drivers or integrated drivers?
4	Sukegawa, but I can agree that a person of	4	A. As best as I recall at the moment,
5	ordinary skill would anticipate that that's so.	1	Sukegawa does not, but if you want a definitive
6			answer, I'd have to review Sukegawa to be sure.
7	Q. Now, in a liquid crystal display, would	7	Q. Why don't you take a moment and look at
	you agree that there are two sets of lines that	1	it?
	run orthogonal to each other?	9	A. In Sukegawa, the driver circuit is
10	A. In the vast majority of displays that	1	identified in Column 1, Column 2 and it's
	are sold, that's the case, yes.	t t	consistently identified as being outside the
	Q. And one of those one set of the lines	1	display. I can't find any mention of a peripheral
12	-		driving circuit.
	is for scan lines and one set is for signal or	13	-
	data lines?	F	Q. And where would you see those in the
15	A. That's generally the case, and it's the		figures? Where would you expect them to be?
	case in all of the patents I think we're looking	16	A. Expect what?
	at.	17	Q. The external drivers.
18	Q. And, for example, in the '413 patent, if	18	A. Which figure?
	you look at Fig. 13, that illustrates prior art	19	Q. I'm asking you if you see a figure that
	showing signal and data lines that are orthogonal		depicts those or where they would be connected.
	to each other?	21	A. Fig. 3D I think comes closest, although
22	A. It's not clear to me that that's shown		they're not shown as far as I can tell. Fig. 3D
	in Fig. 13, but I think it is true in Fig. 13.	ł	shows, of course, the two substrates on the left
24	Q. Are those lines shown to extend outside	1	side 100 and 200. There's the anisotropic
<u>~</u>			conducting time 10 that connects the tlavible
25	the display portion at the bottom and right-hand	25	conducting film 10 that connects the flexible
25	Page 263		Page 265
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67 (Pages 262 - 265)

	D. 0//		Dama 269
1	Page 266 MR. SCHLITTER: Objection, foundation.	1	Page 268 A. Now that I've reviewed that column, I
$\begin{vmatrix} 1\\ 2 \end{vmatrix}$	THE WITNESS: Can you tell me what you		can see that some of my comments were not informed
	mean by "types"?		by that those elements about Fig. 3D. So I
1	BY MR. GIBSON:		could revise them if you'd like. But yes, I can
5	Q. Yeah. What kind of lines?		see that element 32 is the driver IC in this
6	MR. SCHLITTER: Same objection.		example.
7	THE WITNESS: Can you tell me what you	7	Q. And how does that inform your testimony?
	mean by "lines"?	8	A. Well, it's principally to point out that
	BY MR. GIBSON:		Fig. 3D does show in element 32 the driver IC.
10	Q. Well, there are scan lines, data lines.	•	It's actually shown. I think I had said it was
11	A. Do you want me to characterize all	1	off to the right side, so that's incorrect.
	driver circuits?	12	But this is, nevertheless, still just
13	Q. No, just in reference to Fig. 3D, what		one example of a connection to the terminal that
	would you expect that someone of ordinary skill in	1	is disclosed in 3B, 3C, 3E, et cetera. And there
	the art looking at Fig. 3D would assume that there	1	would be many other configurations that I think
	would be in terms of external drivers?	F	would be fair variations to one of ordinary skill
17	A. Well, I think Fig. 3D is silent on what	1	in light of Sukegawa.
1	kind of driver or purpose is is connected to	18	Q. Okay. Would you understand that there
1	this FPC. So, for example, yes, scan line drivers	19	would be a scan line driver and a data or signal
1	could be connected. Data line drivers could be	[	line driver in Fig. 3D?
21	connected.	21	A. Fig. 3D refers to a driver IC dye. I
22	But another important example is the	22	don't think it specifies whether that is the scan
23	ground and voltage lines could be reference		or the data driver. I think he's implying it
	voltages could be connected in this way as well.	24	could be either or something else.
	It's a it's a generic connection, a generic	25	Q. Do you know what the role of the driver
	Page 267		Page 269
1	Page 267 terminal that could be applied to any electrical	1	Page 269 is?
	terminal that could be applied to any electrical	1	_
2	0	2	is?
2	terminal that could be applied to any electrical connection that's desired to the active matrix	2	is? MR. SCHLITTER: Objection, form.
2 3 4	terminal that could be applied to any electrical connection that's desired to the active matrix substrate.	2 3	is? MR. SCHLITTER: Objection, form. BY MR. GIBSON:
2 3 4 5	terminal that could be applied to any electrical connection that's desired to the active matrix substrate. Q. Would you consider, if you look at if	2 3 4 5	is? MR. SCHLITTER: Objection, form. BY MR. GIBSON: Q. What's it used for?
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		1	
1	Page 270 TFT. The inverse would be true if it was a top	1	Page 272 signal line 7A, that terminal line is not going to
	gate TFT.	1	look like Fig. 1B, correct?
3	-	3	
4			prior art that's cited, and Fig. 3C, then this
5			terminal would would not necessarily lead to a
6		1	connection with 7A unless something else was in
	is showing a scan line terminal?		between changing the electrical connection from
8			
1	· · · · · · · ·		the layer 2 up toward layer 7A.
	because, of course, Fig. 2C is prior art. It's	9	Q. And would you understand that a figure
	not his invention. In Sukegawa, Fig. 3 is the		such as 1B could be modified so that it would
	beginning of the series of embodiments and it's	1	function with 3C so that you would have line 7
1	not clear that Sukegawa definitely wants to say		extending into the terminal portion?
	that element 2 in Fig. 2C is the same as what's in	13	A. I don't think the disclosure supports
	Fig. 3C. I think it's consistent with the		that. I think what's explicitly disclosed is
1	disclosure, but I don't think he requires it.	1	that 2 goes in, and I think what a person of
16		1	ordinary skill would more likely see is that
1	before is that you're going to have say in 3C	1	there's a later opening to the left of what's
1	we have a here we have a data line with 7A?		illustrated in Fig. 1B that has a similar
19		1	connection through that opening of the layer 7
20	Q. That's going to be extending, is that		down to layer 2. I think that's what's much more
21		1	obvious to a person of ordinary skill.
22	A. It does seem to be extending off to the	22	Q. And that would be so you could have a
F	right of Fig. 3C.	1	connection between 7 and 7A?
24	Q. And would you then expect there to be a	24	A. Via layer 2.
25	driver for that data line that would be off to the	25	MR. GIBSON: Okay. And I assume we have
	Page 271		Page 273
1	right in the terminal portion?	1	the same understanding I had with you on these two
2	A. Well, it's it's not disclosed	2	depositions, that we can use the transcript in
3	clearly, but I think one of ordinary skill would	3	either of the two proceedings since there is so
4	expect that wiring 7A does eventually connect	4	much overlap and that I'll endeavor not to repeat
5	through perhaps other conductors to a driver IC of	5	myself tomorrow, though I might not be perfect at
6	some kind.	6	that.
7	Q. And this would be the reverse TFT that	7	MR. SCHLITTER: I think that would be
8	we were talking about in 2C?	0	· · · · · · ·
0		0	fine as long as you know, with that
9	A. I'm not sure what you mean, "the reverse		tine as long as you know, with that understanding that we won't plow the same ground
-	A. I'm not sure what you mean, "the reverse TFT."	9	
10 11	TFT." Q. Let's not I think you said it better	9	understanding that we won't plow the same ground
10 11 12	TFT." Q. Let's not I think you said it better earlier. That you would have a display TFT if we	9 10 11 12	understanding that we won't plow the same ground again. MR. GIBSON: No, I'm going to do my best not to. I mean, there may be there may be some
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10 11 12 13 14 15 16 17 18 19 20 21 22	<ul> <li>TFT."</li> <li>Q. Let's not I think you said it better</li> <li>earlier. That you would have a display TFT if we</li> <li>were talking about line 2 and you're going to have</li> <li>a TFT that's driving the data line if we have</li> <li>line 7A?</li> <li>MR. SCHLITTER: Objection, form.</li> <li>THE WITNESS: I'm afraid I don't know</li> <li>what a display TFT is.</li> <li>BY MR. GIBSON:</li> <li>Q. Okay. That was not that's not what I</li> <li>meant.</li> <li>I guess if you look at Fig. 3C and</li> </ul>	9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	understanding that we won't plow the same ground again. MR. GIBSON: No, I'm going to do my best not to. I mean, there may be there may be some overlap just because of the nature of the way these things are. But with that, I am done for the day, although I'll reserve the right to ask questions after you do. MR. SCHLITTER: I just have one topic. EXAMINATION BY MR. SCHLITTER: Q. I wanted to refer to Exhibit 1011. A. Did you say 1011? Q. Yes.

1	Page 274	Page 276
1	THE WITNESS: Yes.	1
2	Ah, finally.	UNITED STATES PATENT AND TRADEMARK OFFICE 2 BEFORE THE PATENT TRIAL AND APPEAL BOARD
3	BY MR. SCHLITTER:	3
4	Q. Okay. Exhibit 1011 is from page 94 of	INNOLUX CORPORATION, ) 4 )
5		Petitioner, )
6	A. Yes, it is.	5 )
7	Q. And you mentioned that on your direct	vs. ) IPR2013-00066 6 ) U.S. Pat. No.
8	testimony or your cross testimony that the	SEMICONDUCTOR ENERGY ) 7,876,413
	capacitor line Cj and the scanning lines Yj would	7 LABORATORY CO., LTD., )
	be the first thing that would be formed as shown	8 Patent Owner. )
1	in this figure, correct?	9
12	A. Yes, that's correct.	10       I, MICHAEL J. ESCUTI, Ph.D., being first         11       duly sworn, on oath say that I am the deponent in
13	Q. And the second thing that would be	12 the aforesaid deposition taken on September 5th,
	formed would be gate dielectric 211?	13 2013; that I have read the foregoing transcript of
15	A. That's correct.	<ul><li>14 my deposition, consisting of pages 1 through 278</li><li>15 inclusive, and affix my signature to same.</li></ul>
16	Q. Do you see the two white rectangles	16
	overlying the scanning line, vertically above the	as it now appears
1	scanning lines Yj?	17 as it now appears with corrections 18
19	A. I do.	19 MICHAEL J. ESCUTI, Ph.D.
20	Q. What are those?	20 21
21	A. Those are the semiconducting layers that	SUBSCRIBED and sworn to
1	form the channel of the TFT.	22 before me this day of
23	Q. What is the difference between the	, 2013.
1	smaller rectangle on the top and the larger	
1	rectangle on the bottom, the white rectangles I'm	24 Notary Public 25
1	Page 275 referring to?	Page 277
		1 CERTIFICATE OF CERTIFIED SHORTHAND REPORTER
1 2		CERTIFICATE OF CERTIFIED SHORTHAND REPORTER     L Sandra L Rocca a State of Illinois
2	A. It's a particular design of the TFT	2 I, Sandra L. Rocca, a State of Illinois
3	A. It's a particular design of the TFT which has different amounts of doping in in	<ol> <li>I, Sandra L. Rocca, a State of Illinois</li> <li>licensed Certified Shorthand Reporter, License No.</li> </ol>
3 4	A. It's a particular design of the TFT which has different amounts of doping in in those two regions. And the purpose of that	<ol> <li>I, Sandra L. Rocca, a State of Illinois</li> <li>licensed Certified Shorthand Reporter, License No.</li> <li>084-003435, do hereby certify:</li> </ol>
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1	signature not being obtained;	
2	That I am not counsel for nor related to	
	any of the parties herein, nor a relative or	
	employee of such attorney or counsel for any of	
	the parties hereto, nor am I interested directly	
6	or indirectly in the outcome hereof.	
7	IN WITNESS WHEREOF, I have hereunto set	
	my hand and seal of office this day of	
9	, 2013.	
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11		
12	SANDRA L. ROCCA, CSR, RPR, RMR, CRR	
12	CSR License No. 084-003435	
13 14	Expires May 31, 2015	
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